

FIG. 1

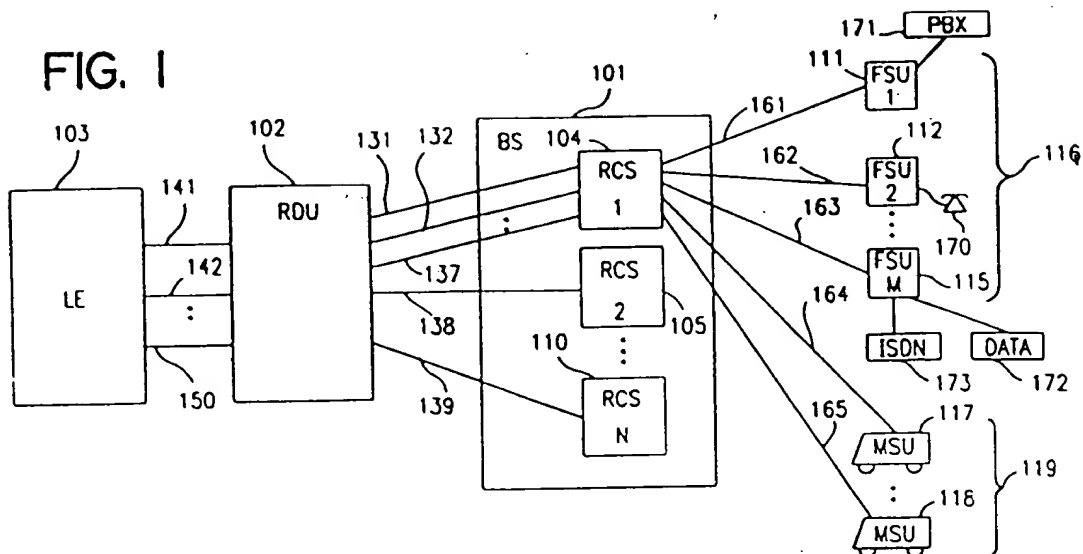


FIG. 2a

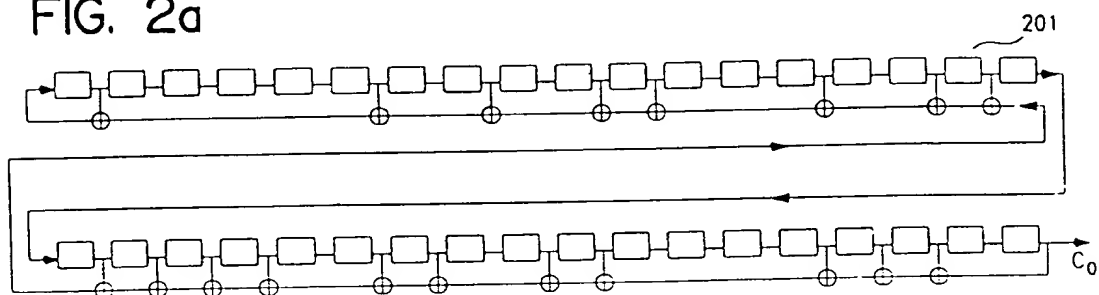


FIG. 2b

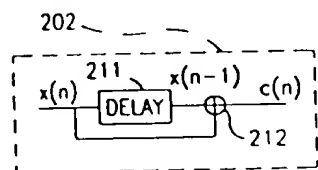
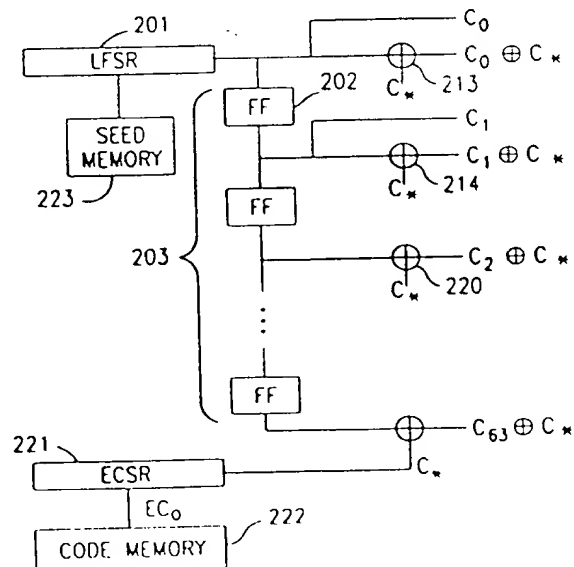
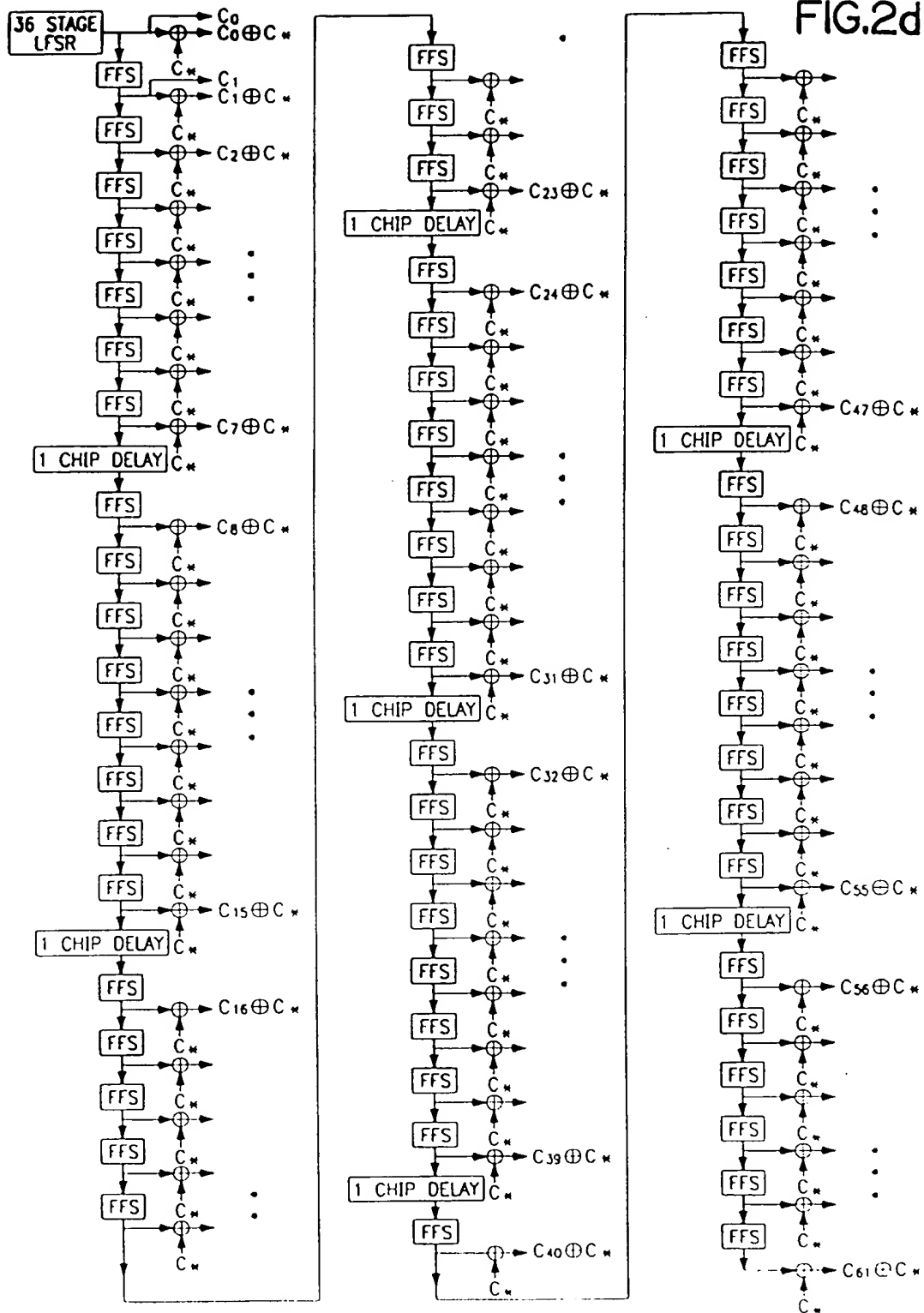


FIG. 2c





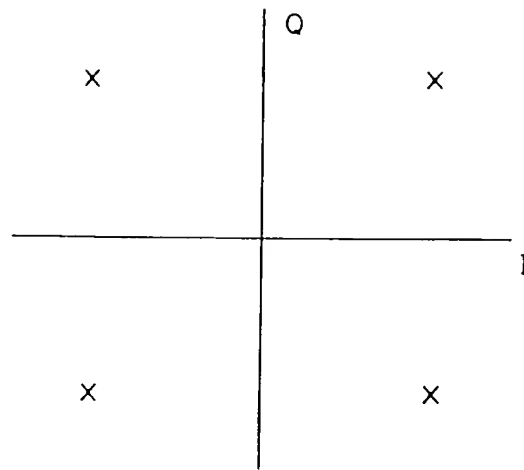


FIG. 3a

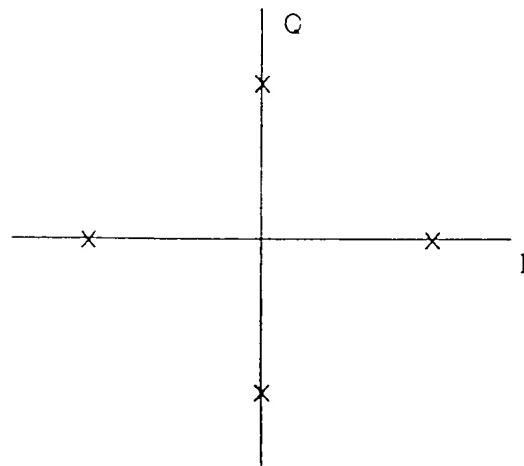


FIG. 3b

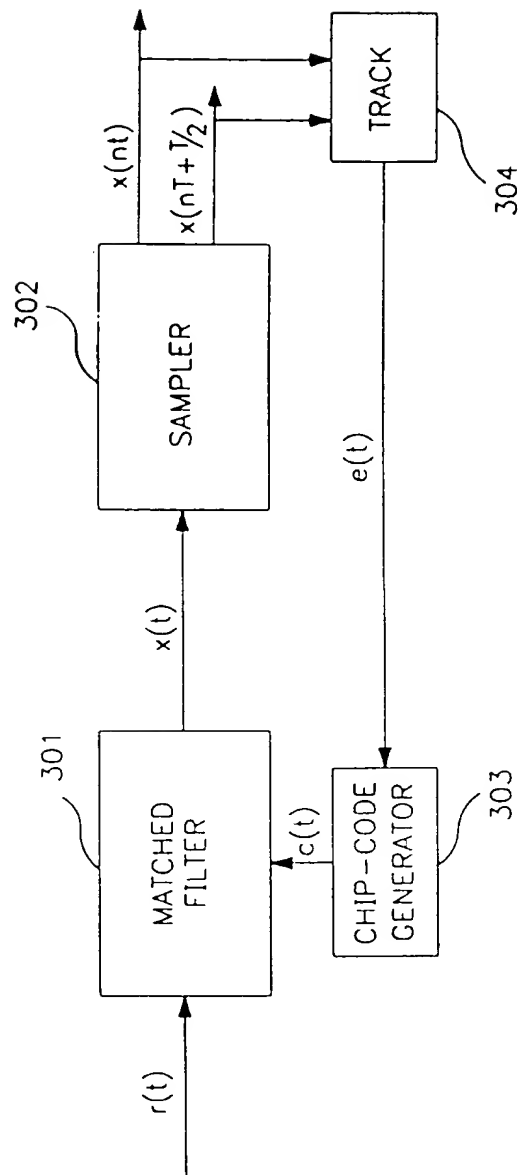


FIG. 3c

FIG. 4

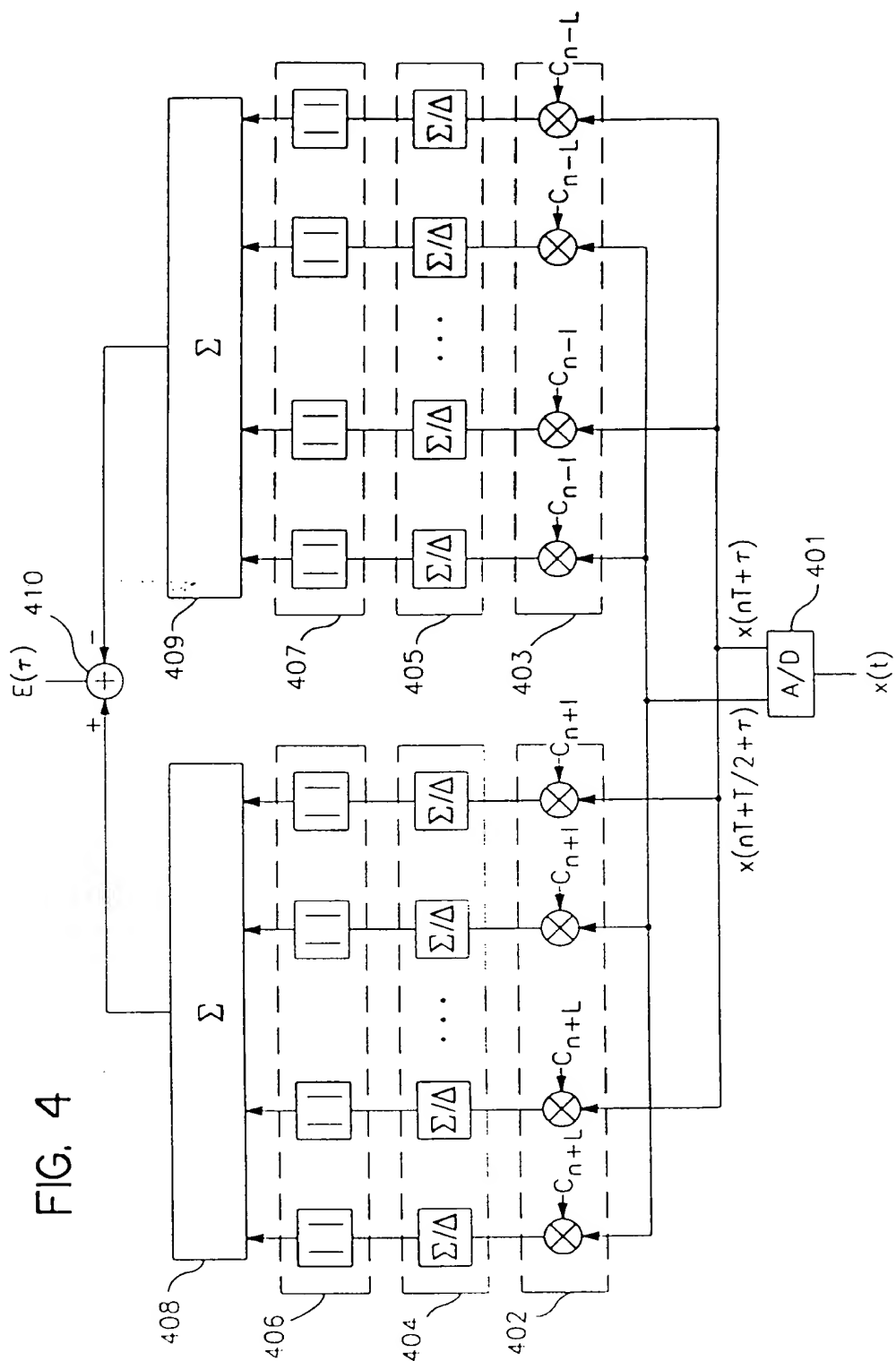


FIG. 5a

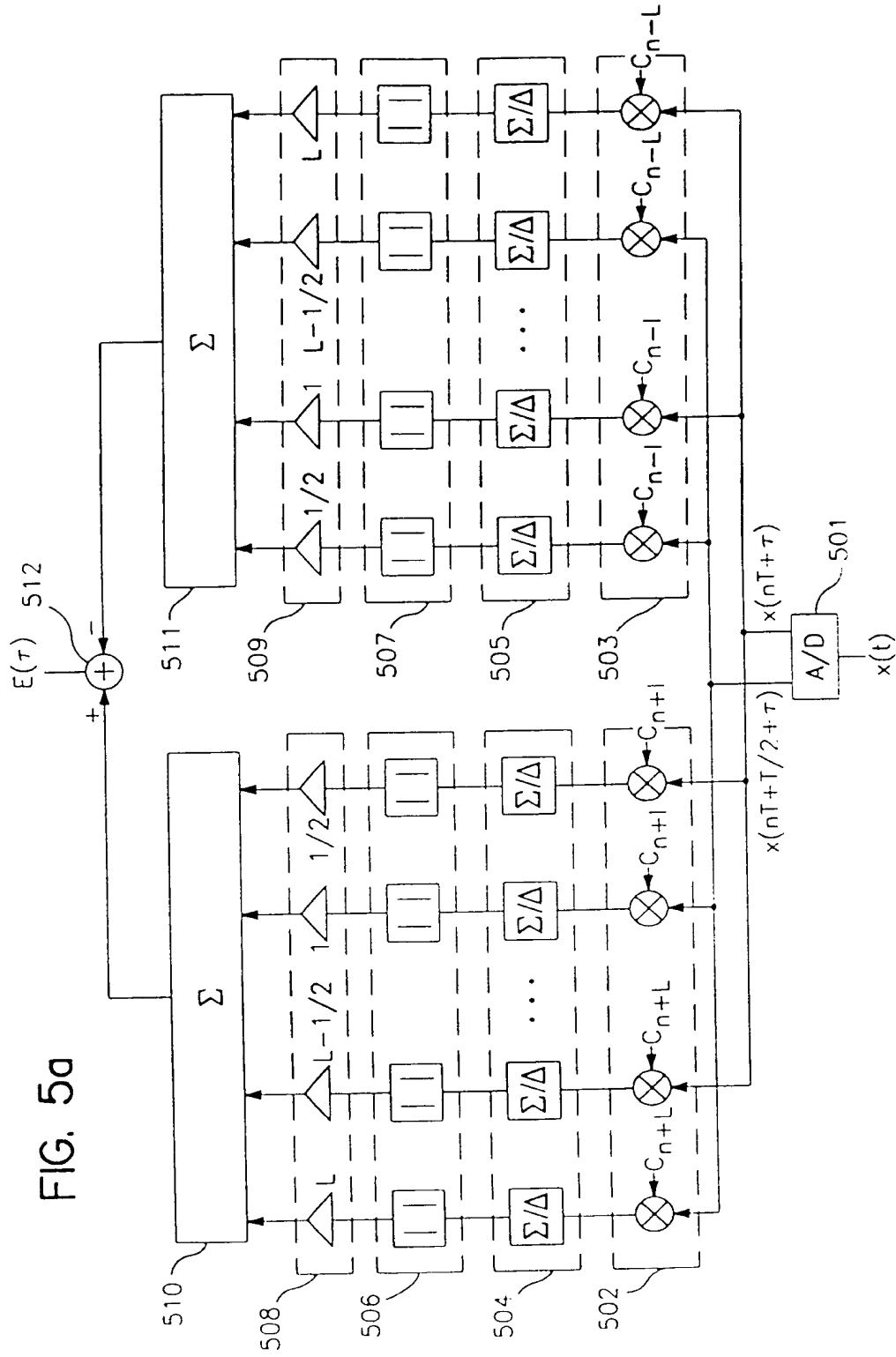
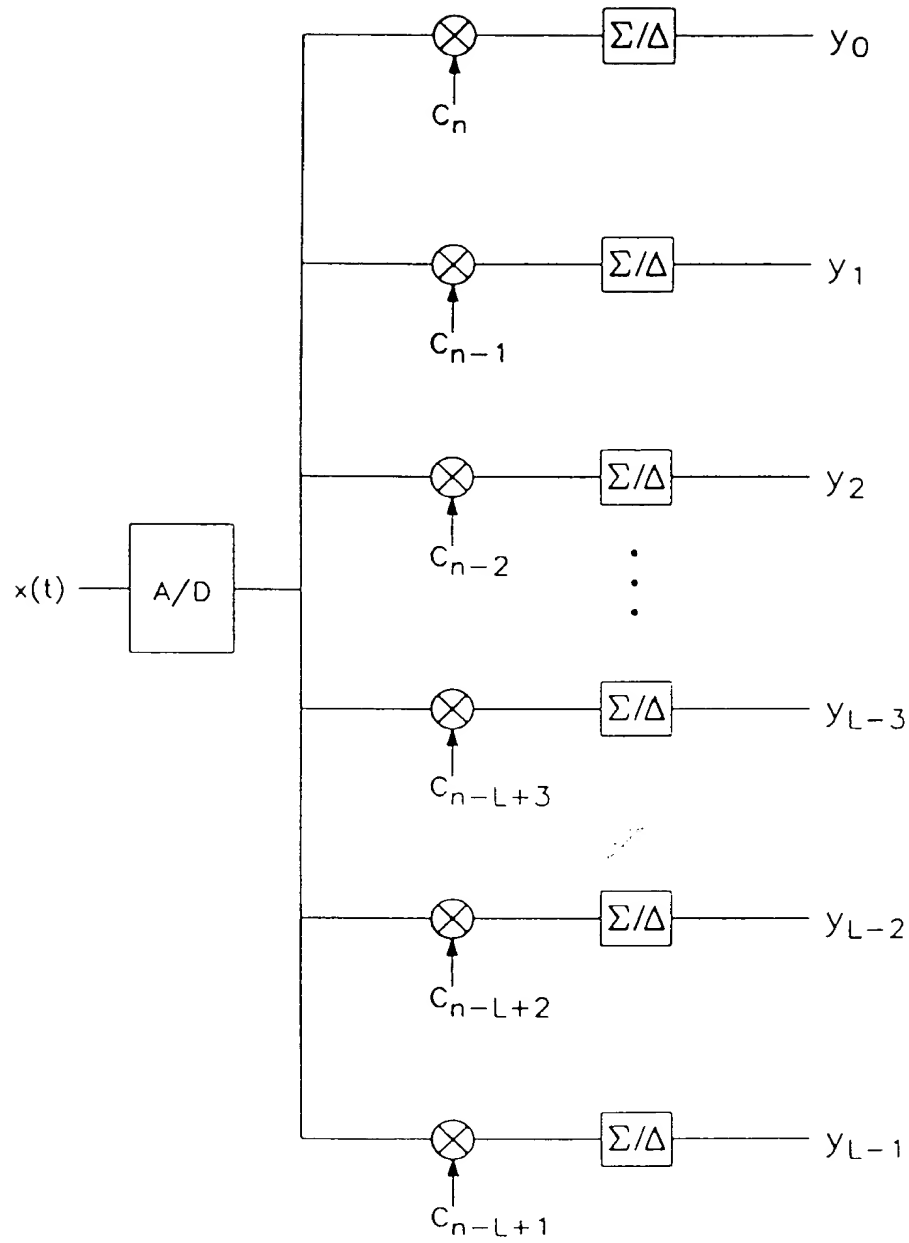


FIG. 5b



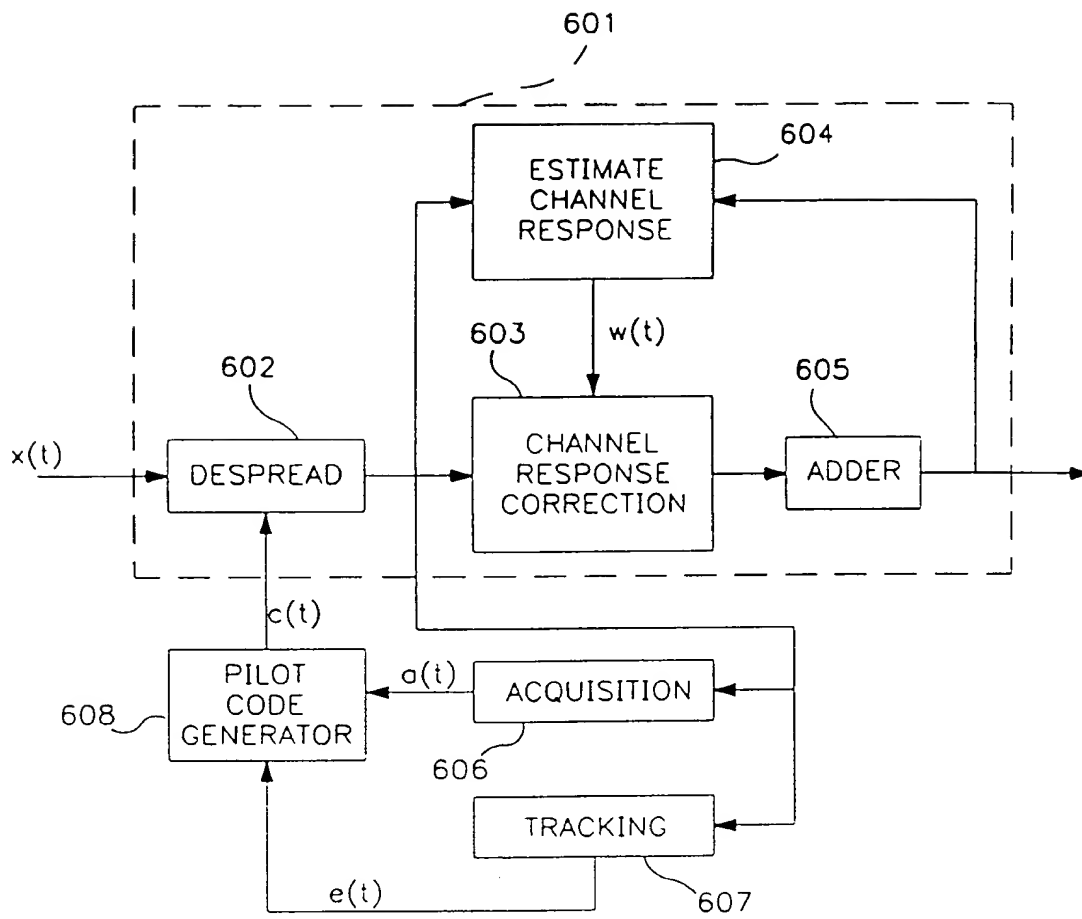


FIG. 6



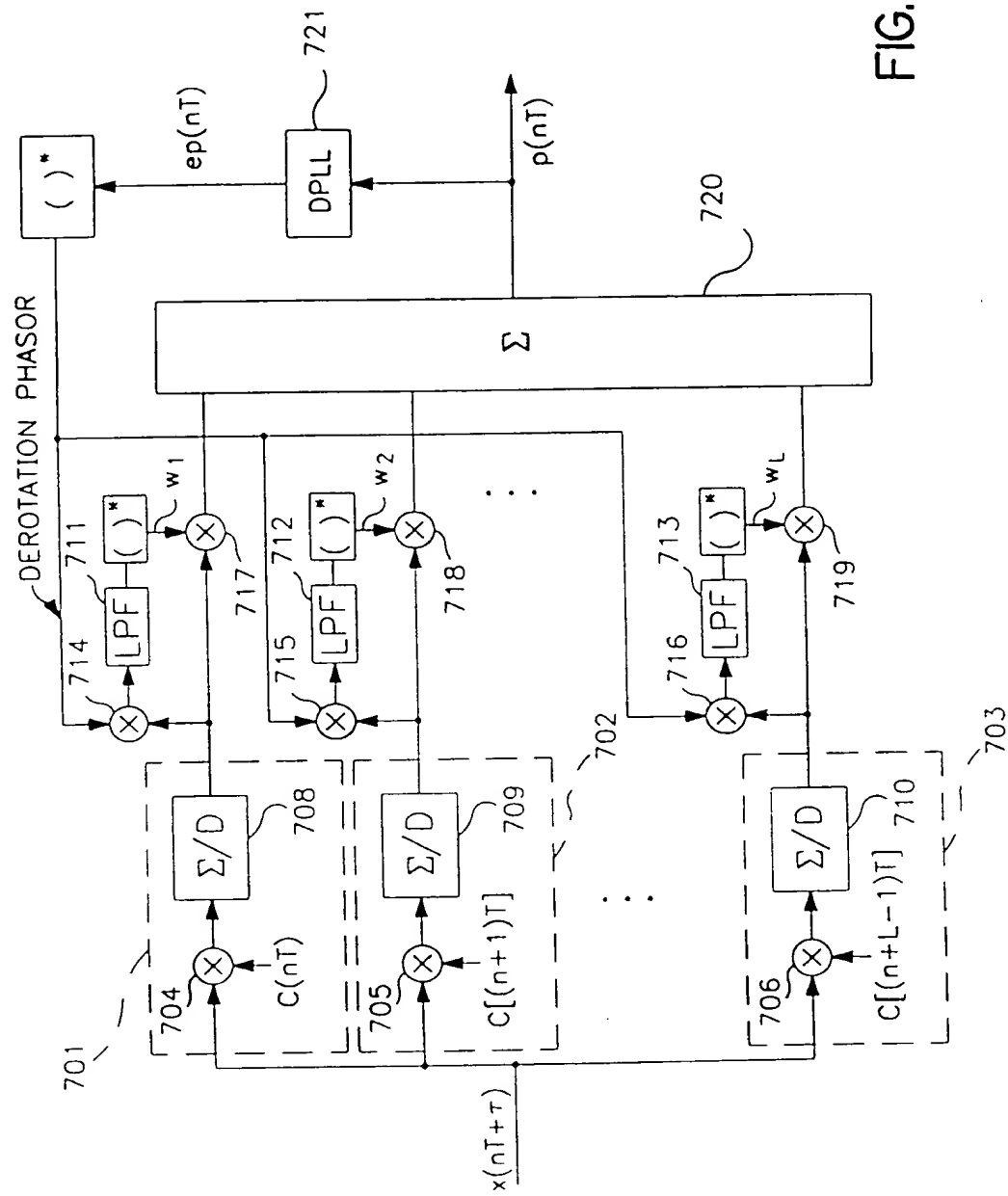


FIG. 7

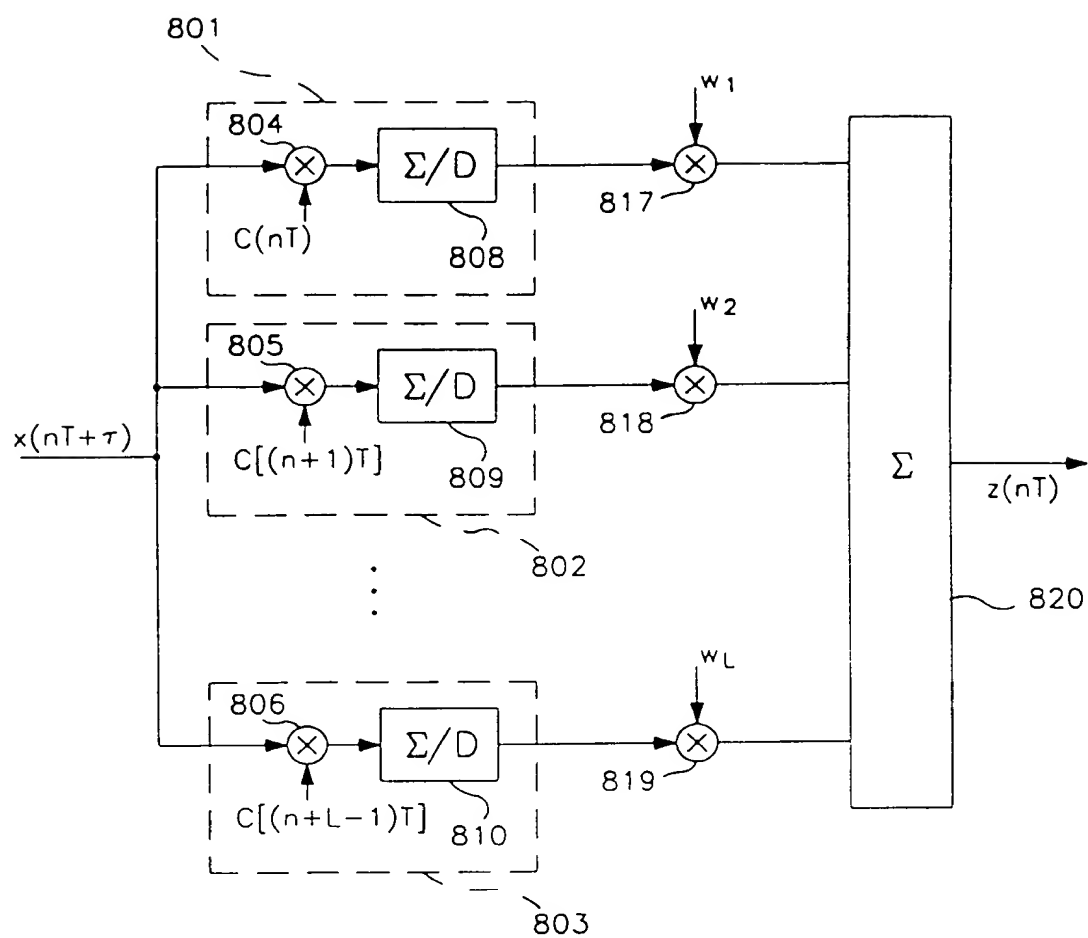


FIG. 8a

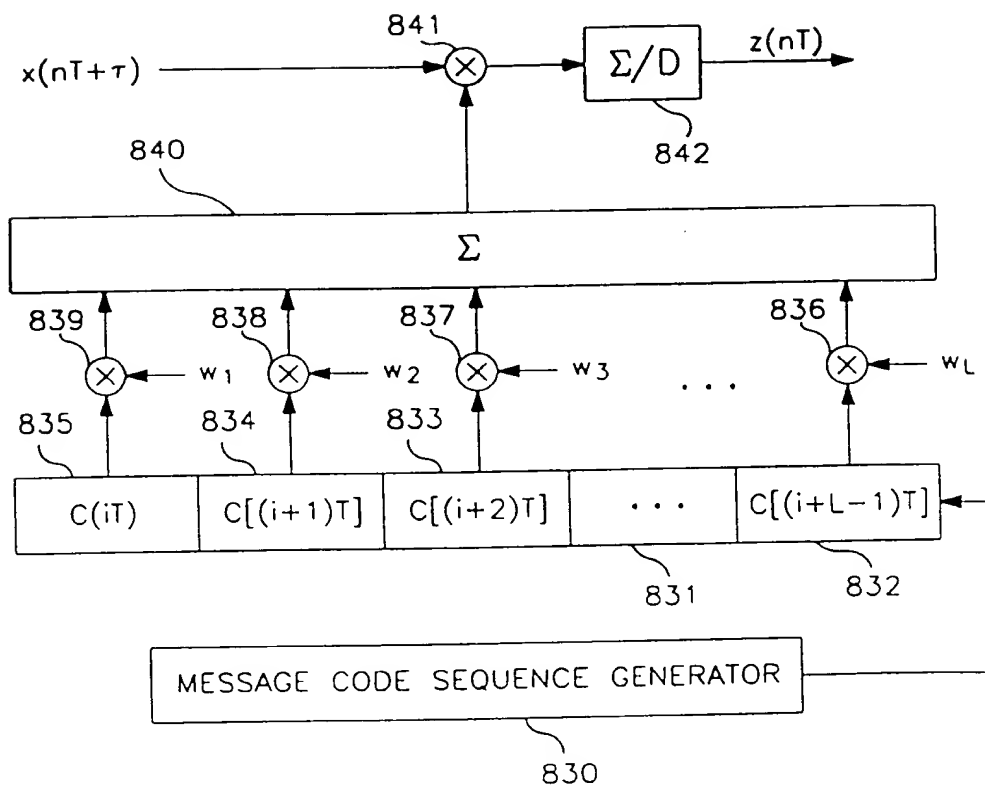


FIG. 8b

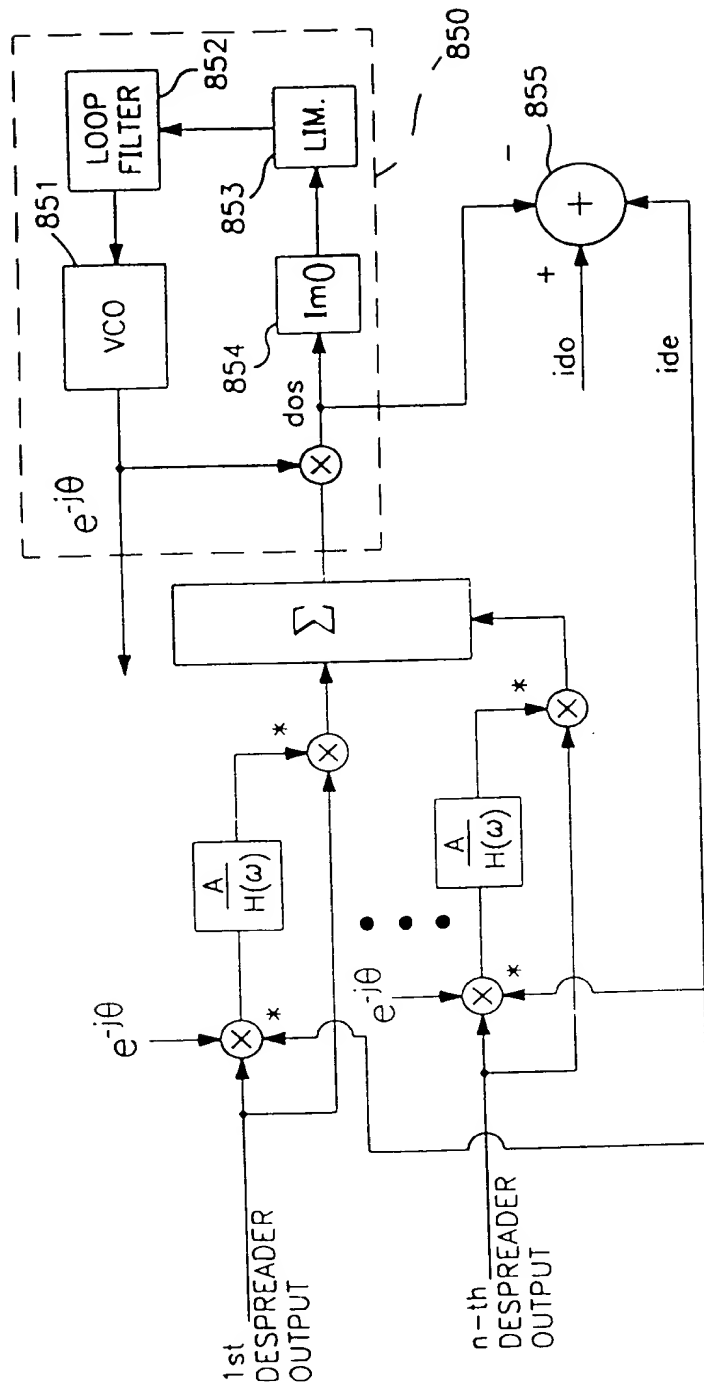


FIG. 8c

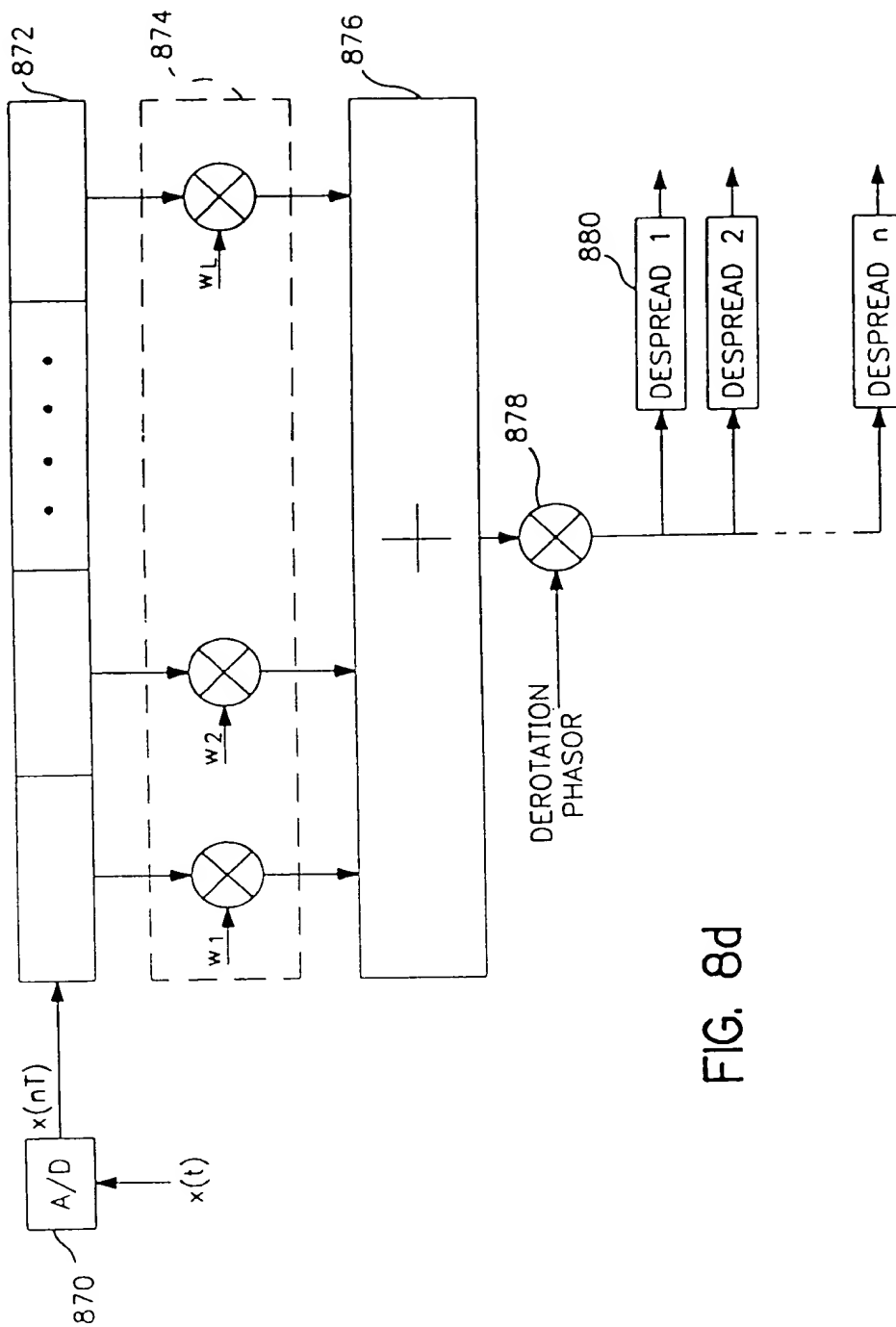
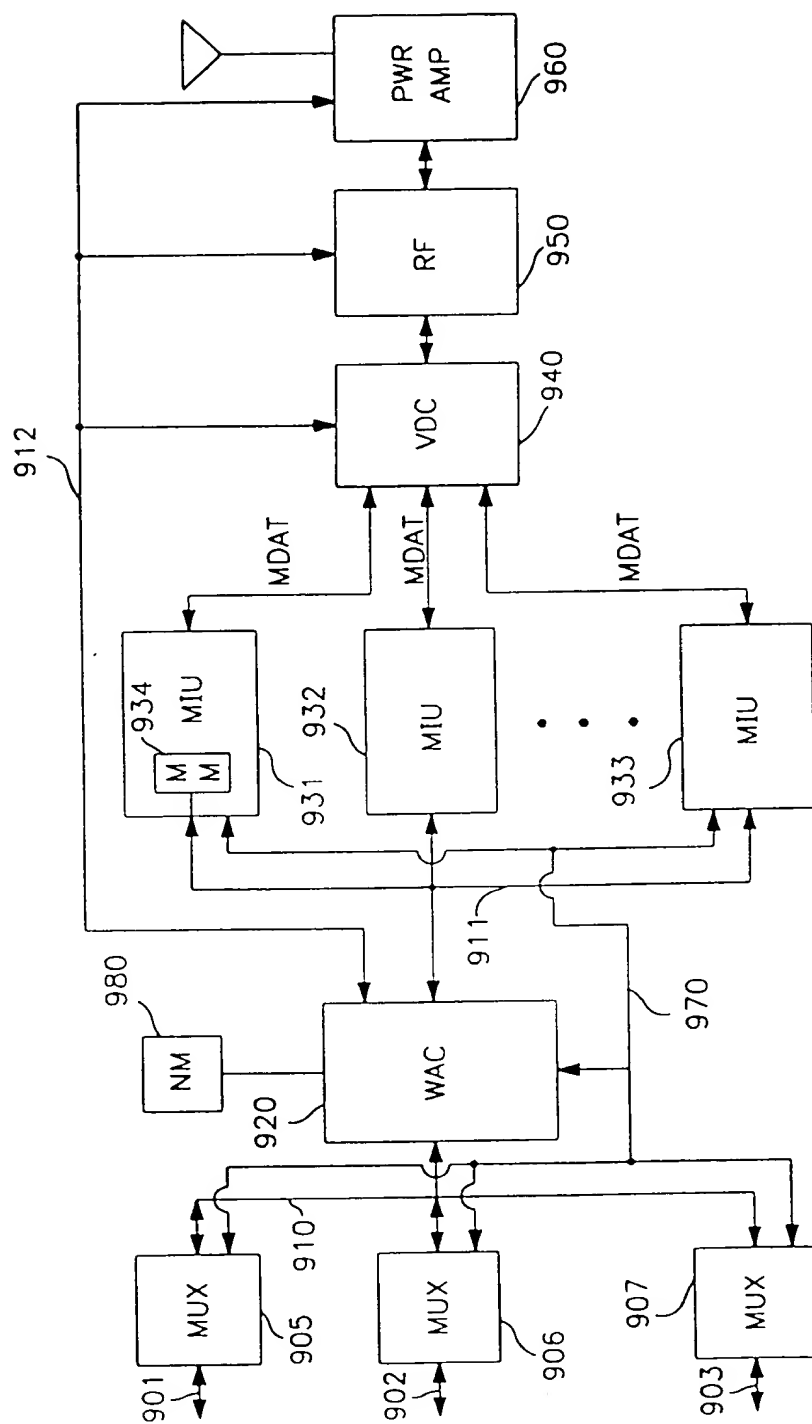


FIG. 8d



எ

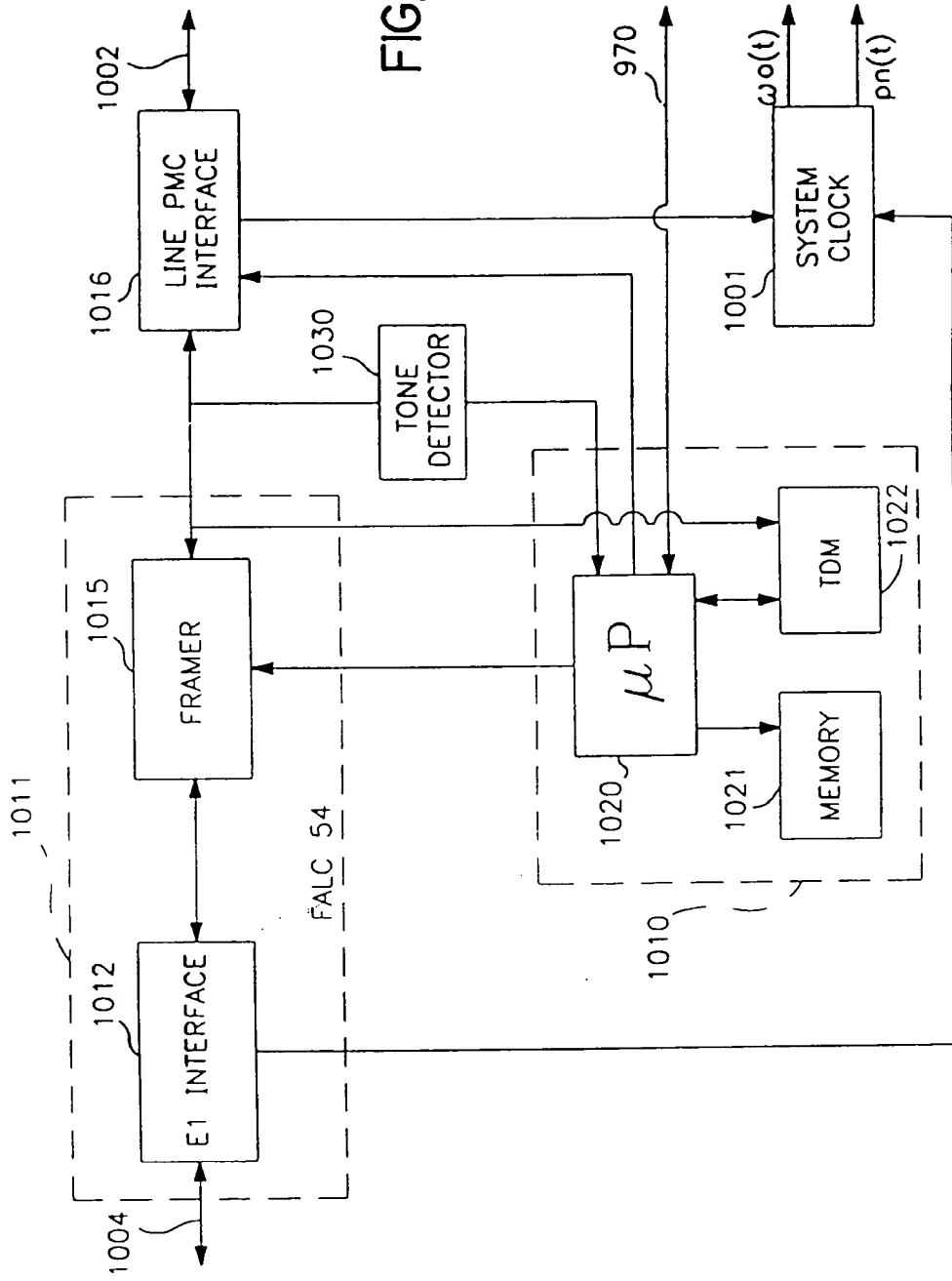


FIG. 10

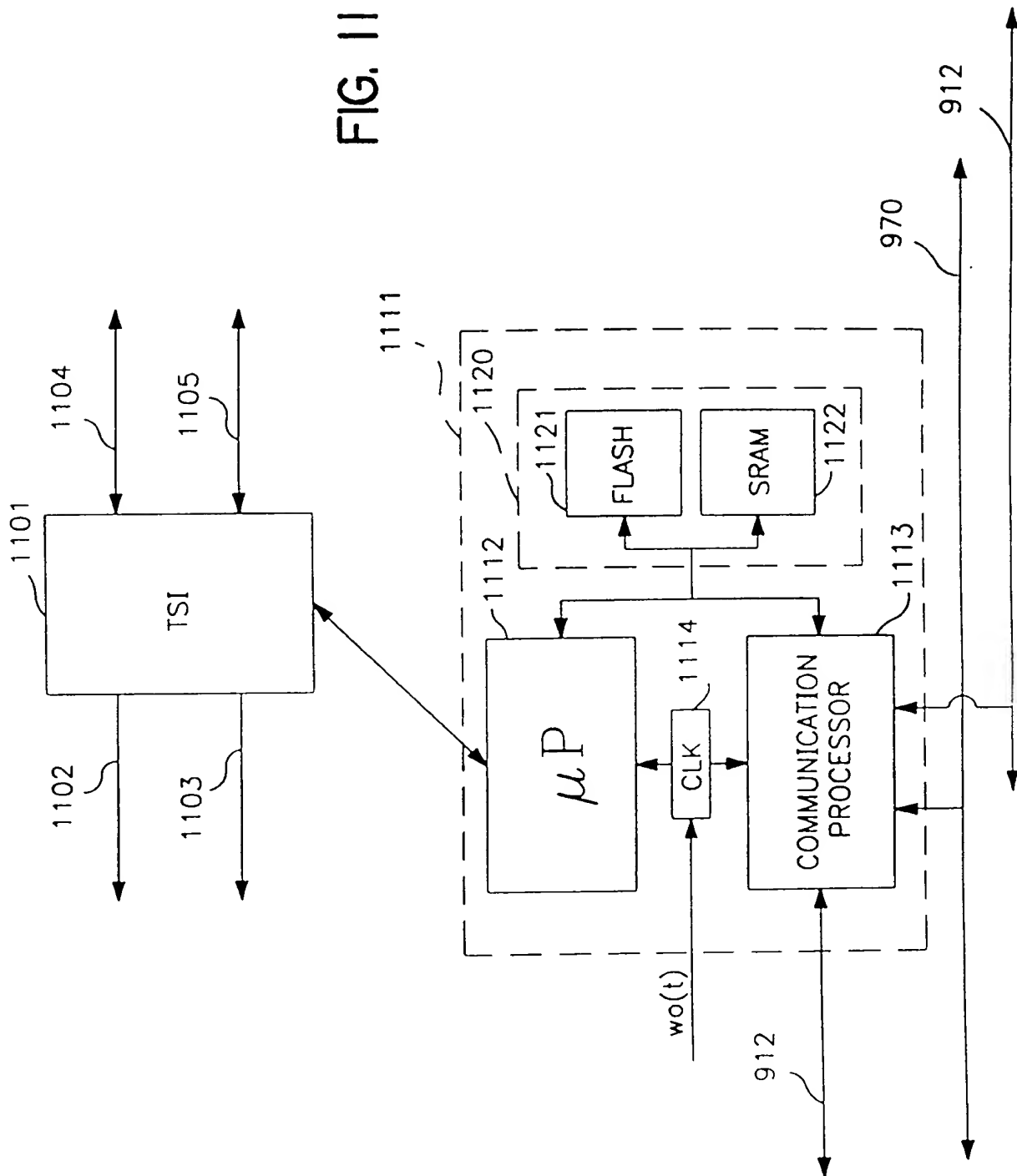


FIG. 11



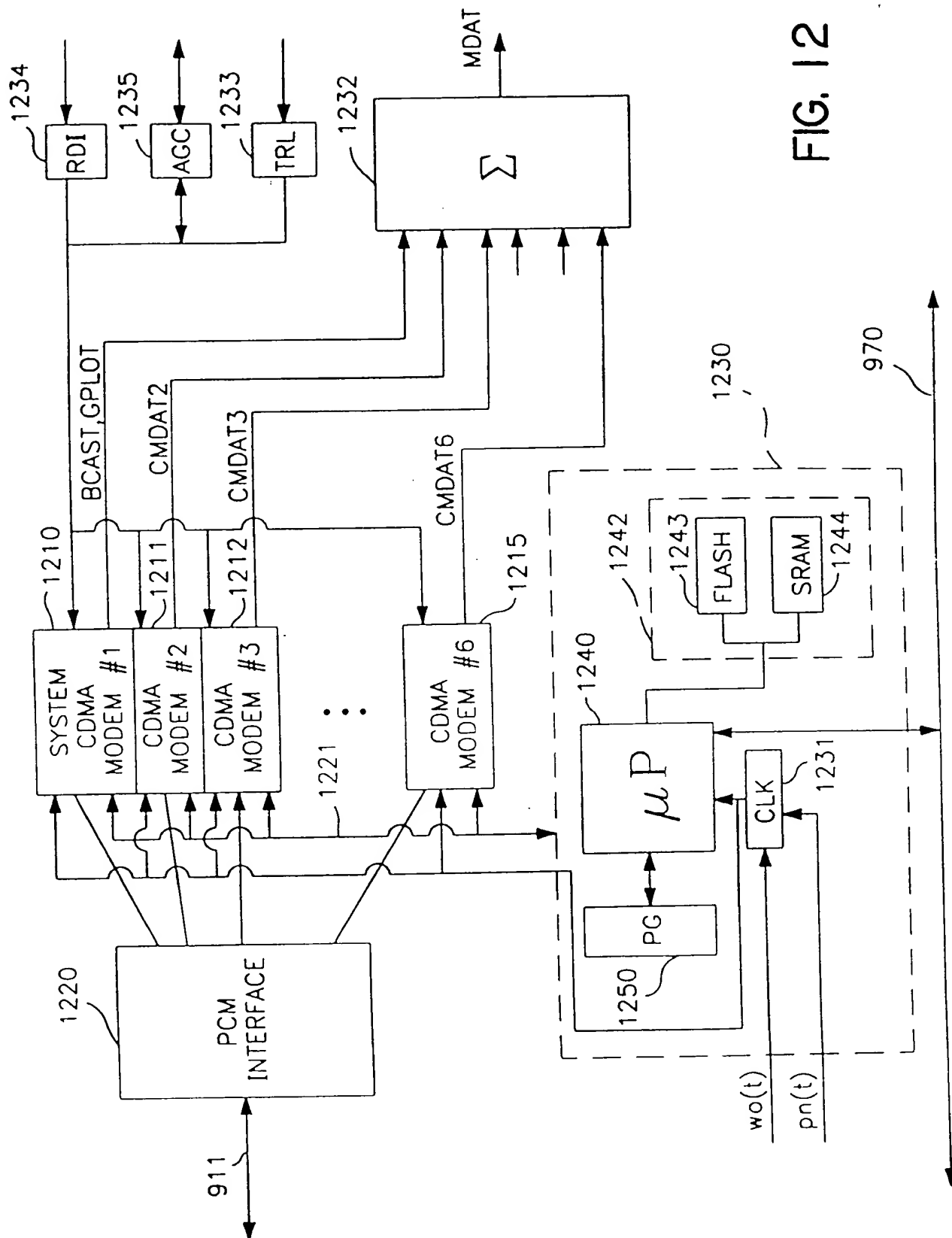


FIG. 12

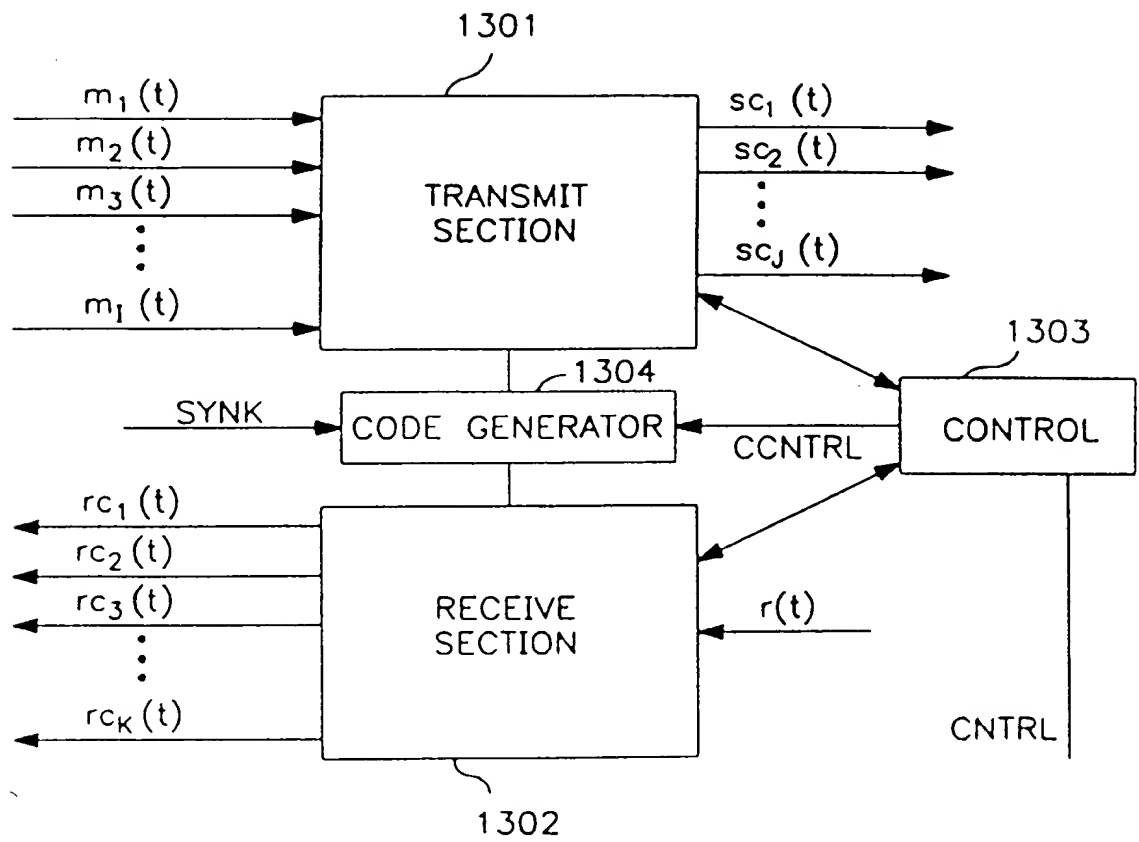


FIG. 13

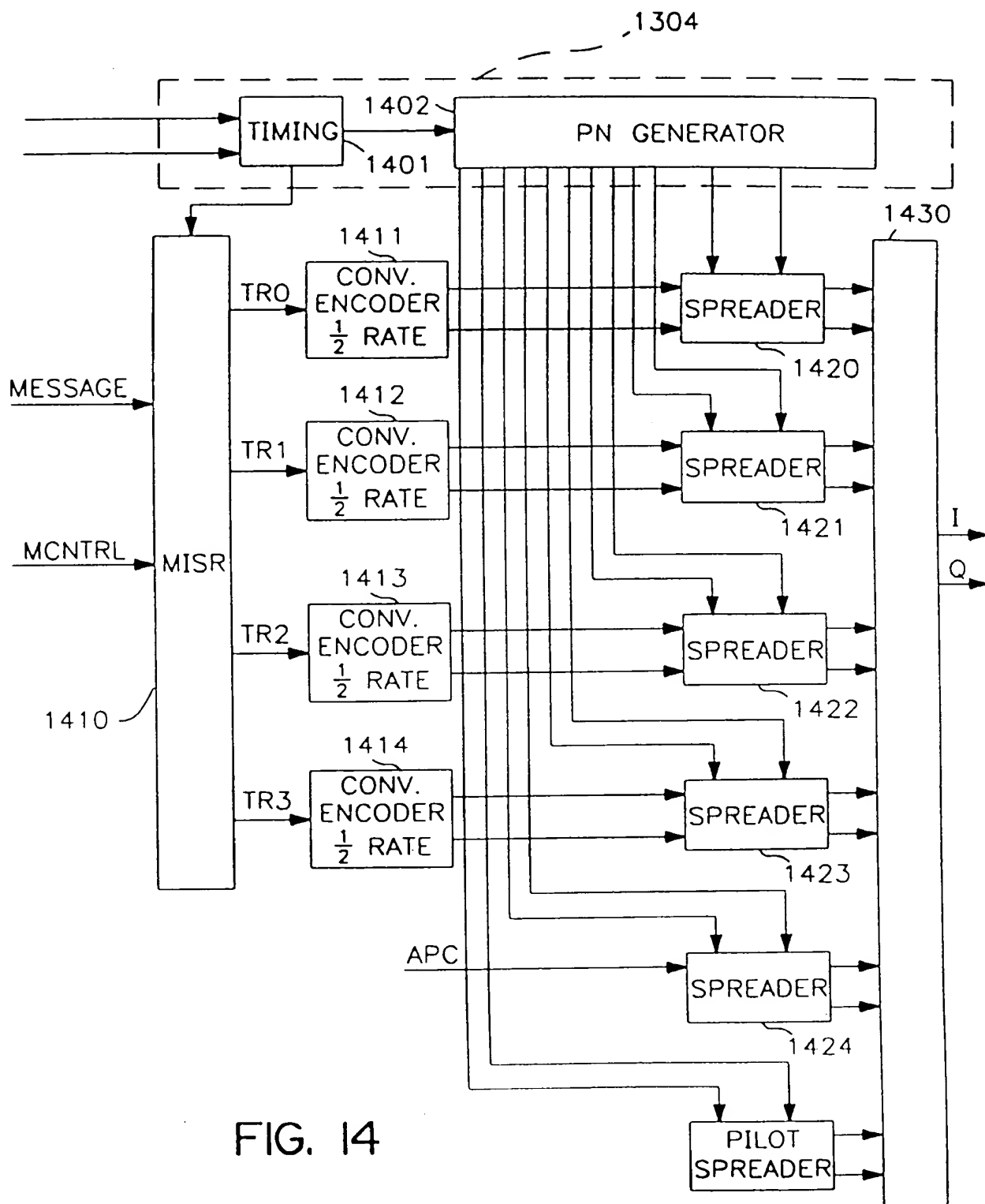
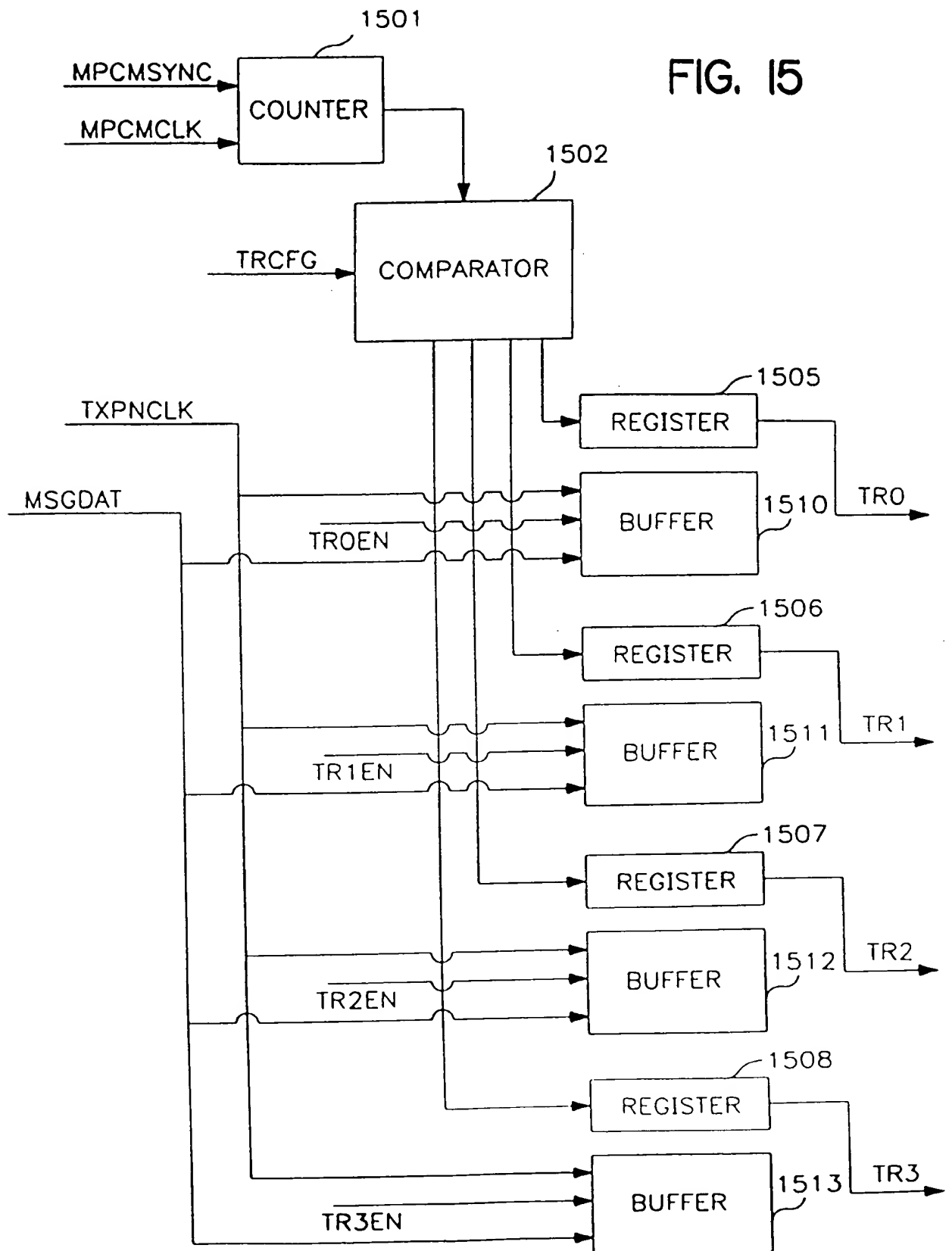


FIG. 14

FIG. 15



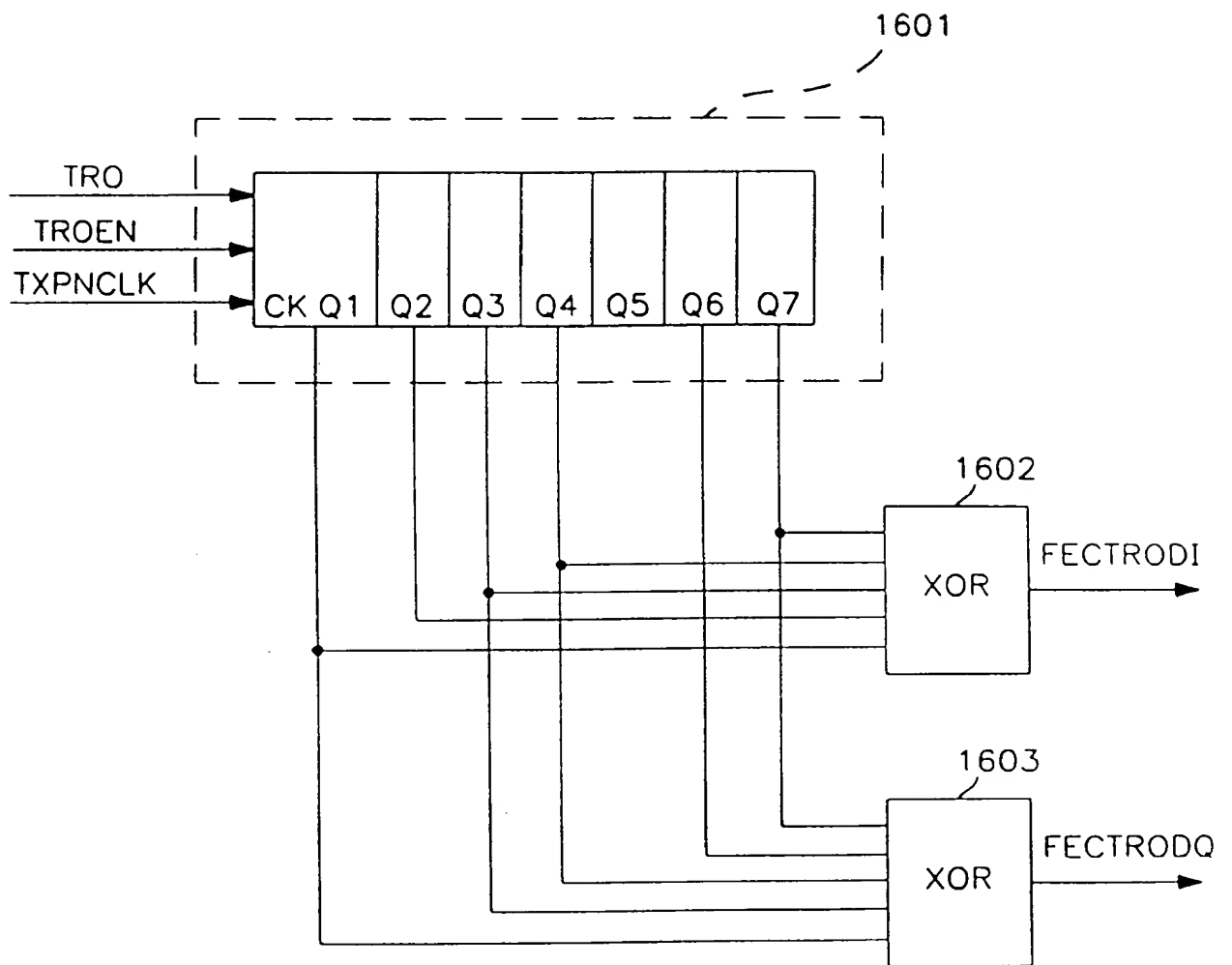


FIG. 16

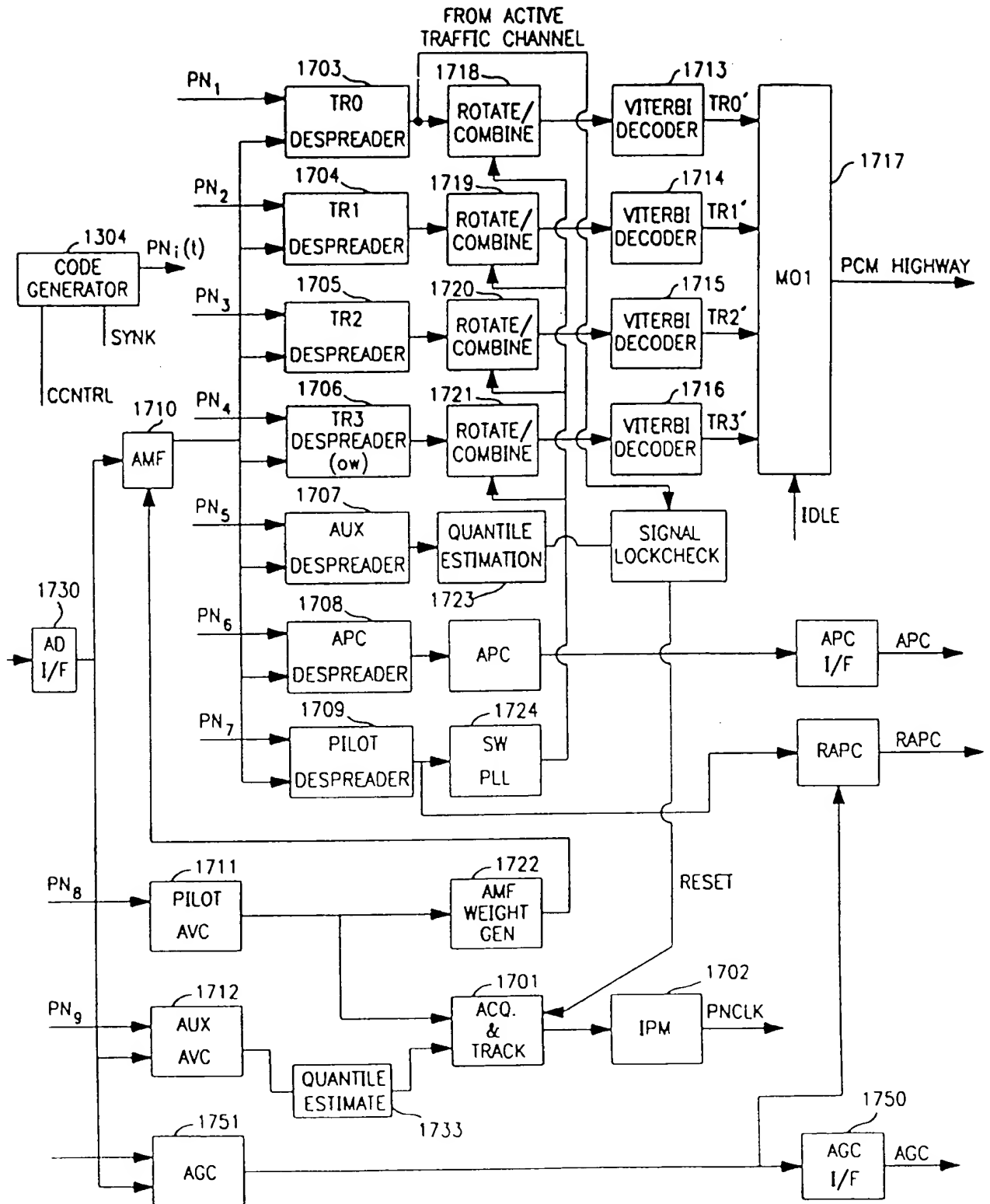


FIG. 17

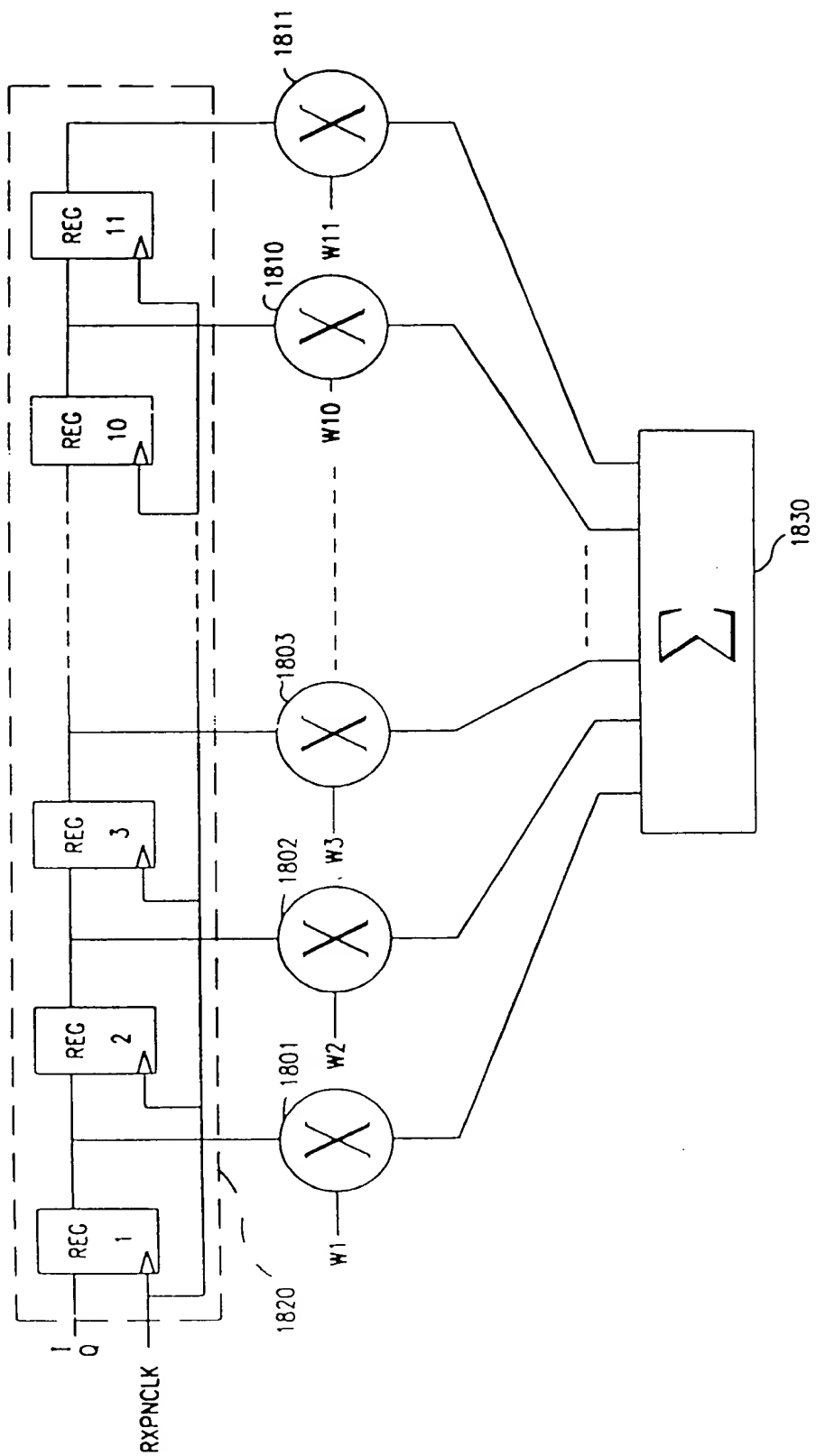


FIG. 18

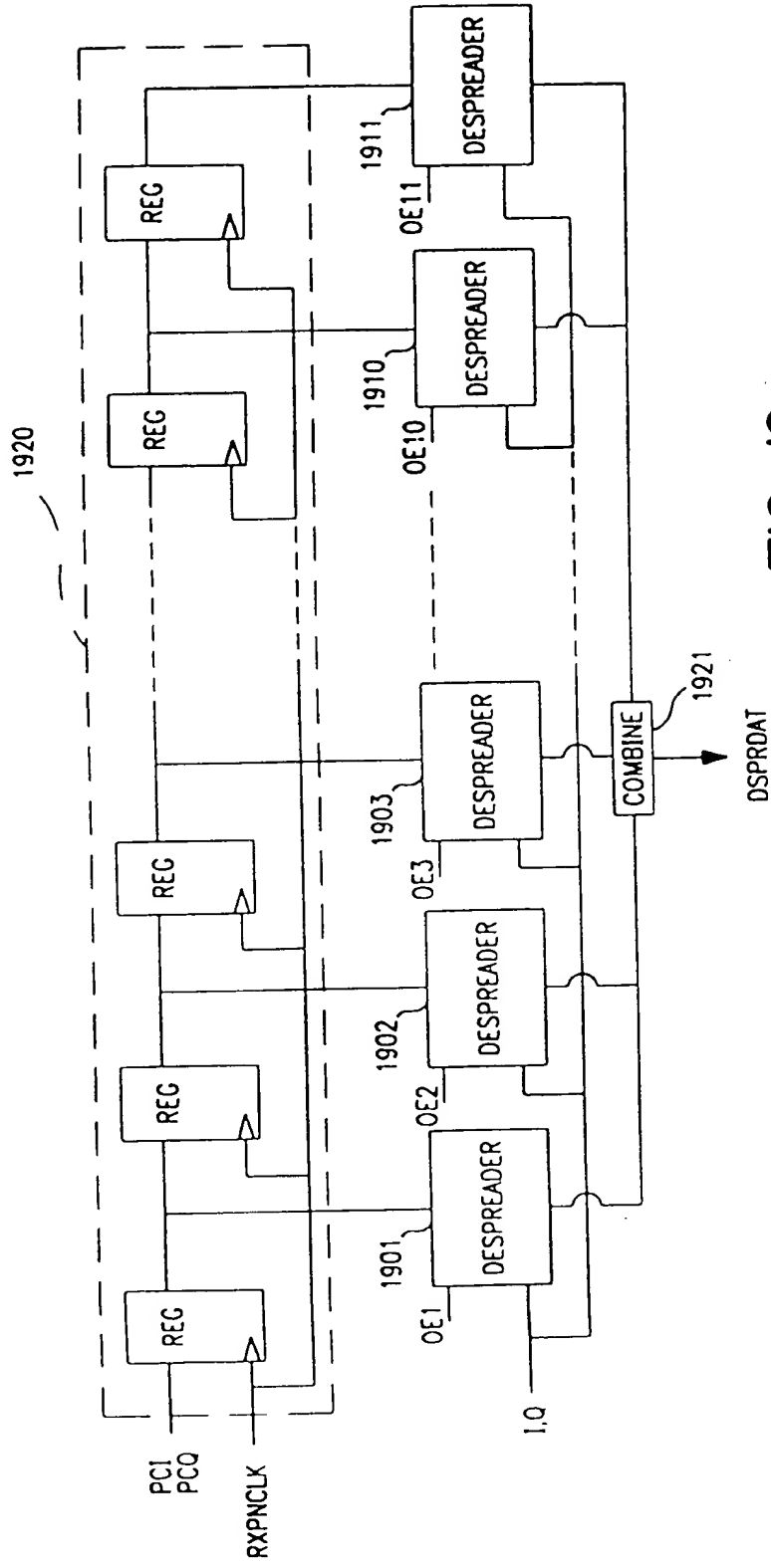


FIG. 19



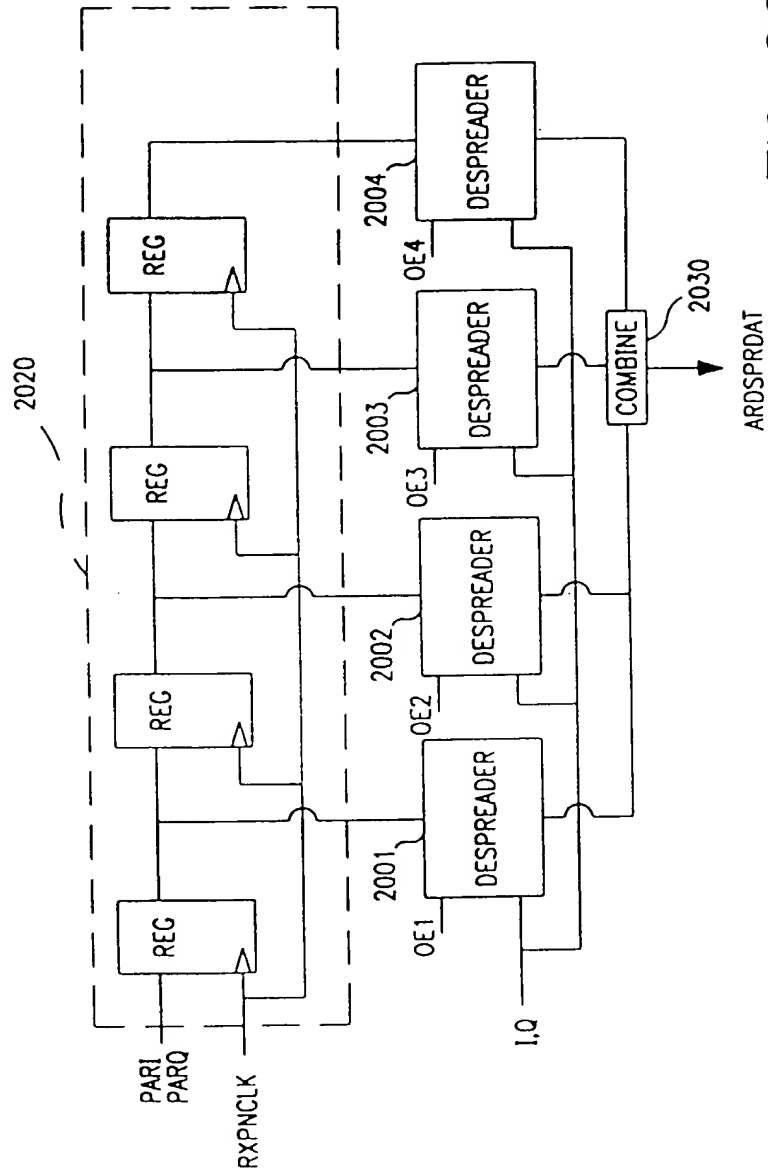
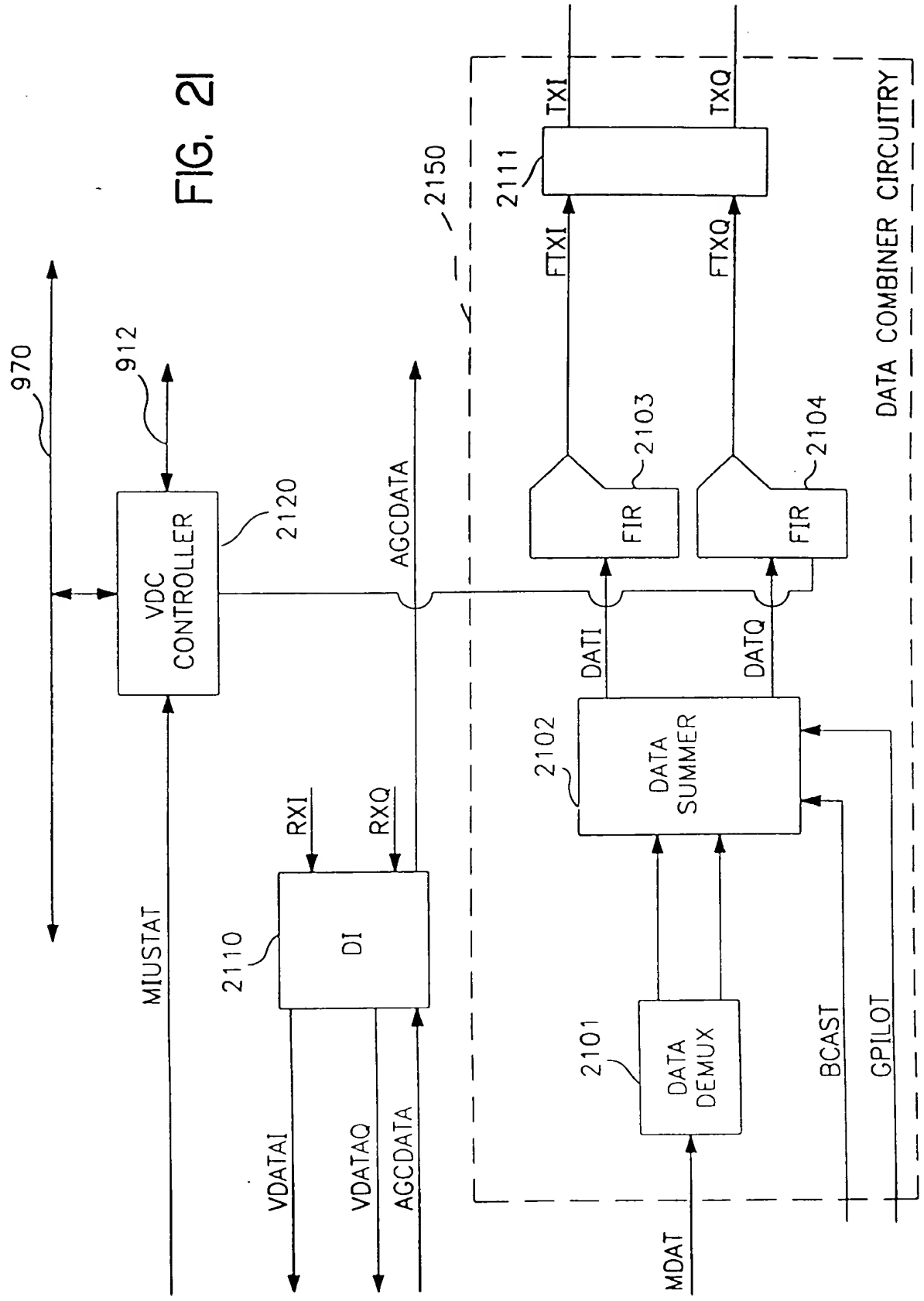


FIG. 20



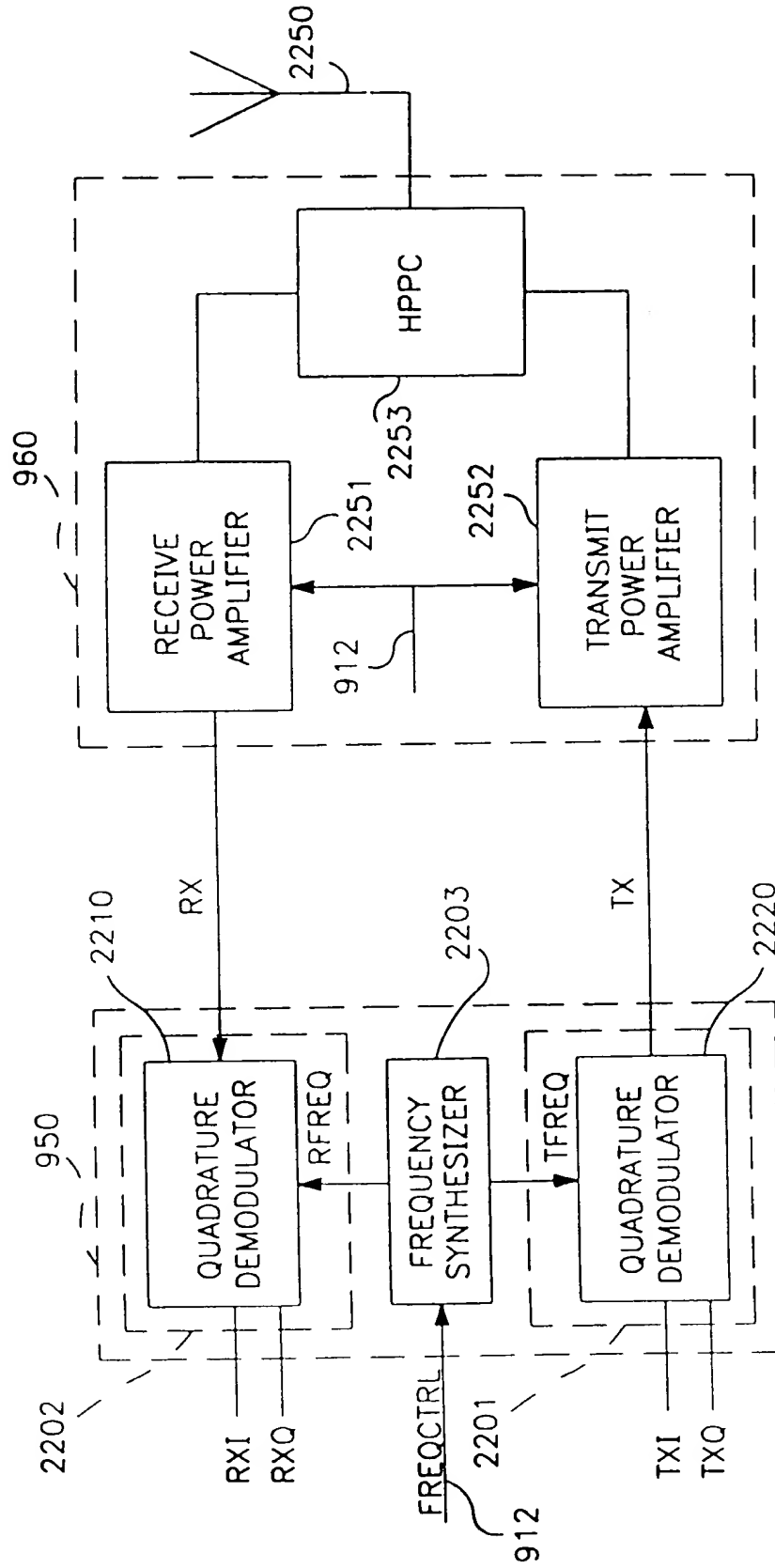


FIG. 22

FIG. 23 is a block diagram of a system architecture. The system includes a STANDARD ADPCM ENCODER/DECODER CHIP (2301) which contains a DATA INT (2320), ADPCM ENCODER (2321), and ADPCM DECODER (2322). The chip is connected to a CDMA MODEM (2340) via RMESS and TMESS signals. The CDMA MODEM is connected to an RF DEMOD (2303) and an RF MOD (2302). The RF DEMOD is connected to an antenna (2305). The RF MOD is connected to a TOSC (2304). The CDMA MODEM is also connected to a CLOCK (2331) and a SU CONTROLLER (2330). The SU CONTROLLER is connected to a MEMORY (2332) and a USER (2350). The SU CONTROLLER is also connected to an IC (2312) and an LI (2313). The IC is connected to a TINF (2311) and an RINF (2313). The LI is connected to a TINF (2311) and an RINF (2313). The IC is also connected to a TDMESS (2310) and an RDMESS (2310). The TDMESS and RDMESS signals are connected to the DATA INT (2320). The TDMESS and RDMESS signals are also connected to the ADPCM ENCODER (2321) and ADPCM DECODER (2322). The TDMESS and RDMESS signals are also connected to the IC (2312) and LI (2313). The TDMESS and RDMESS signals are also connected to the CDMA MODEM (2340). The TDMESS and RDMESS signals are also connected to the RF DEMOD (2303) and RF MOD (2302). The TDMESS and RDMESS signals are also connected to the CLOCK (2331) and SU CONTROLLER (2330). The TDMESS and RDMESS signals are also connected to the MEMORY (2332) and USER (2350).

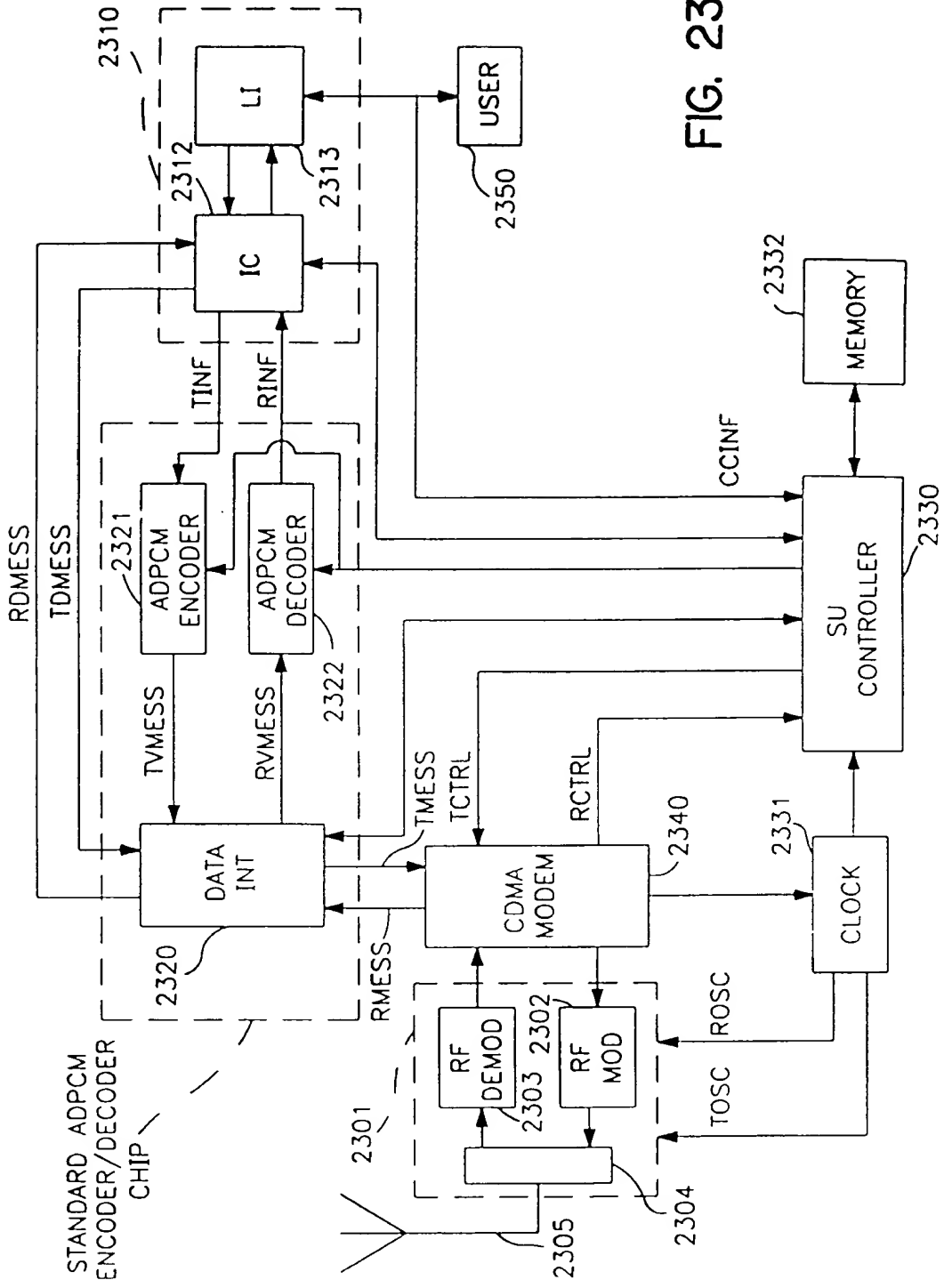


FIG. 23

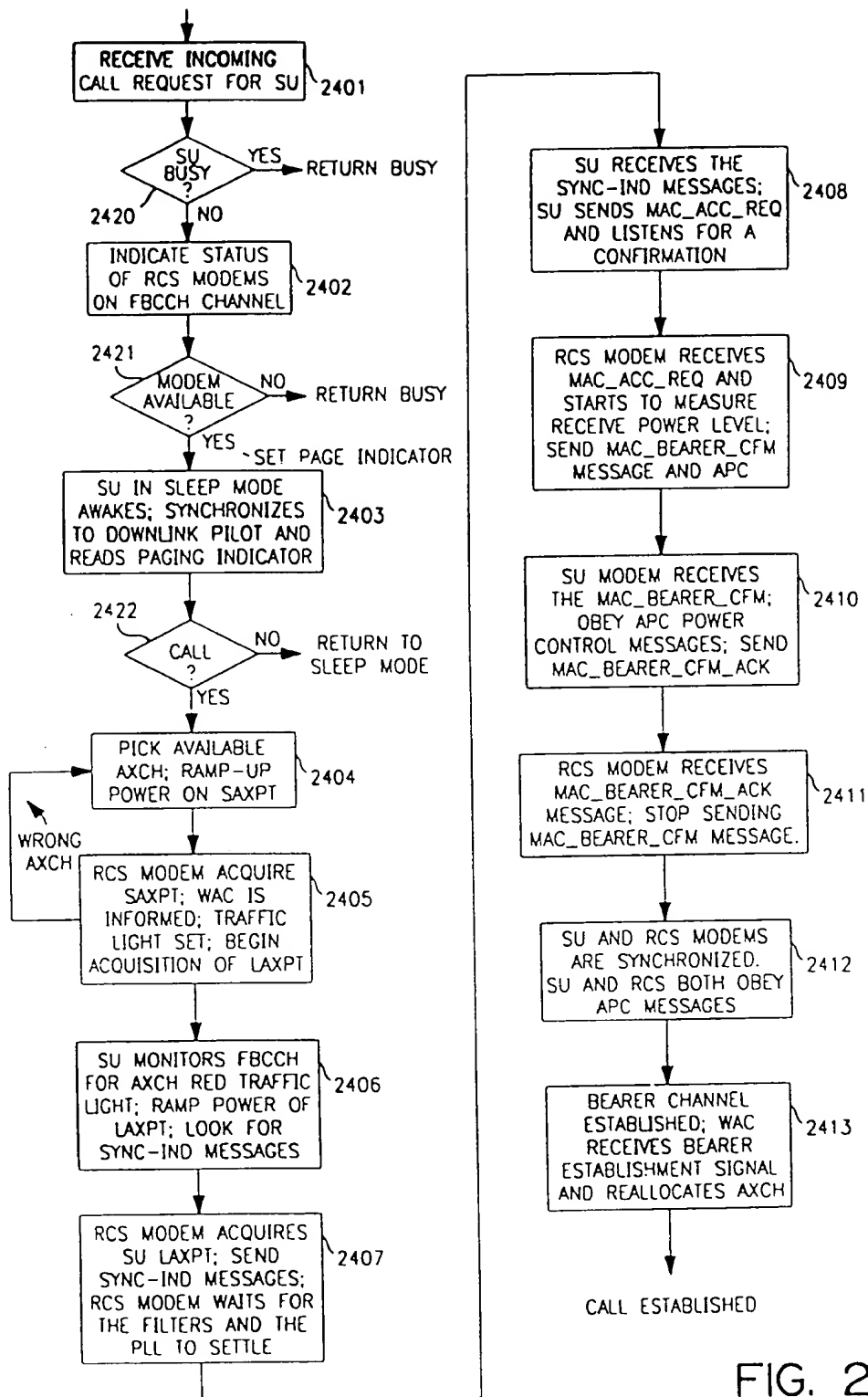


FIG. 24

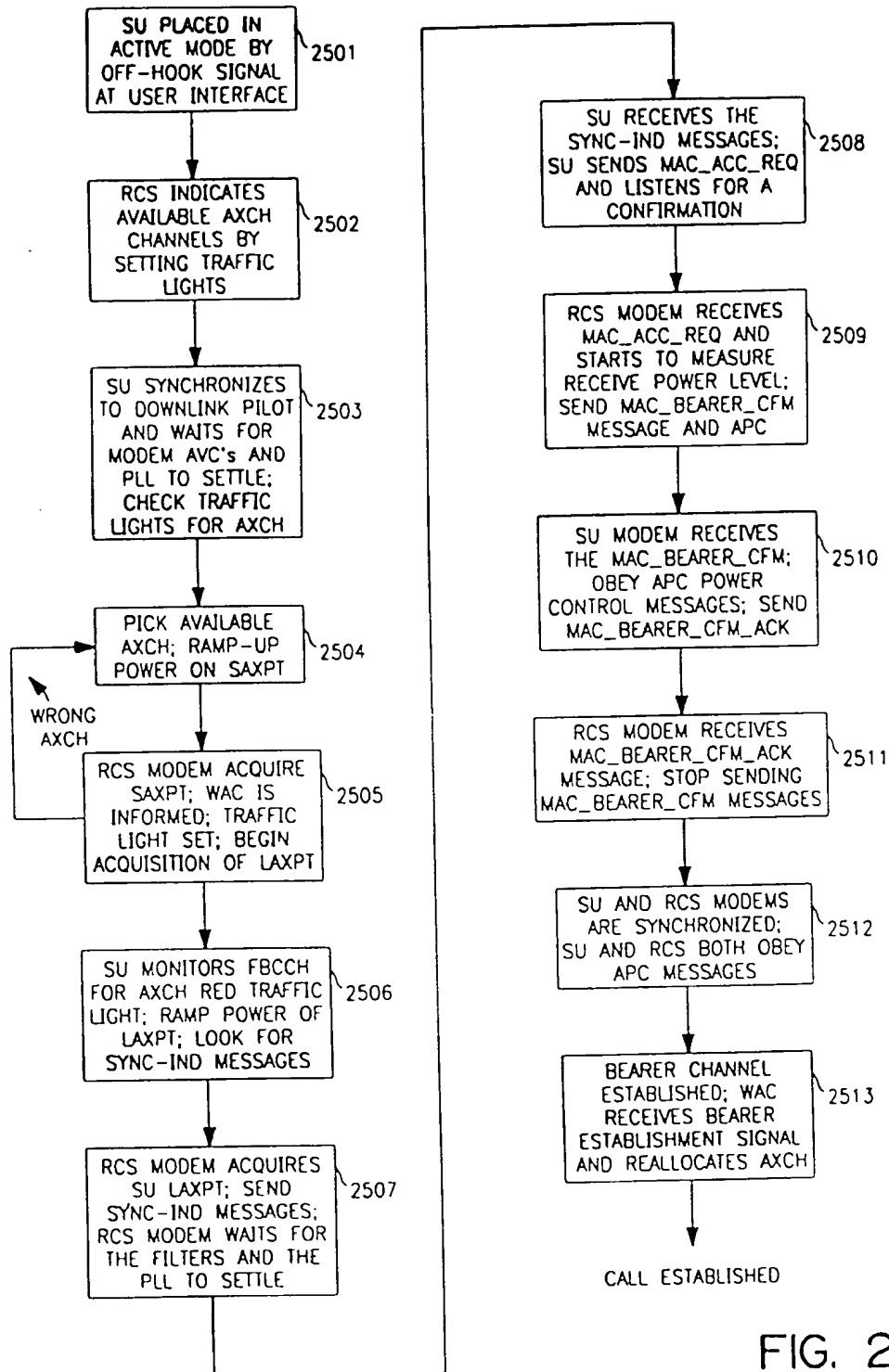


FIG. 25

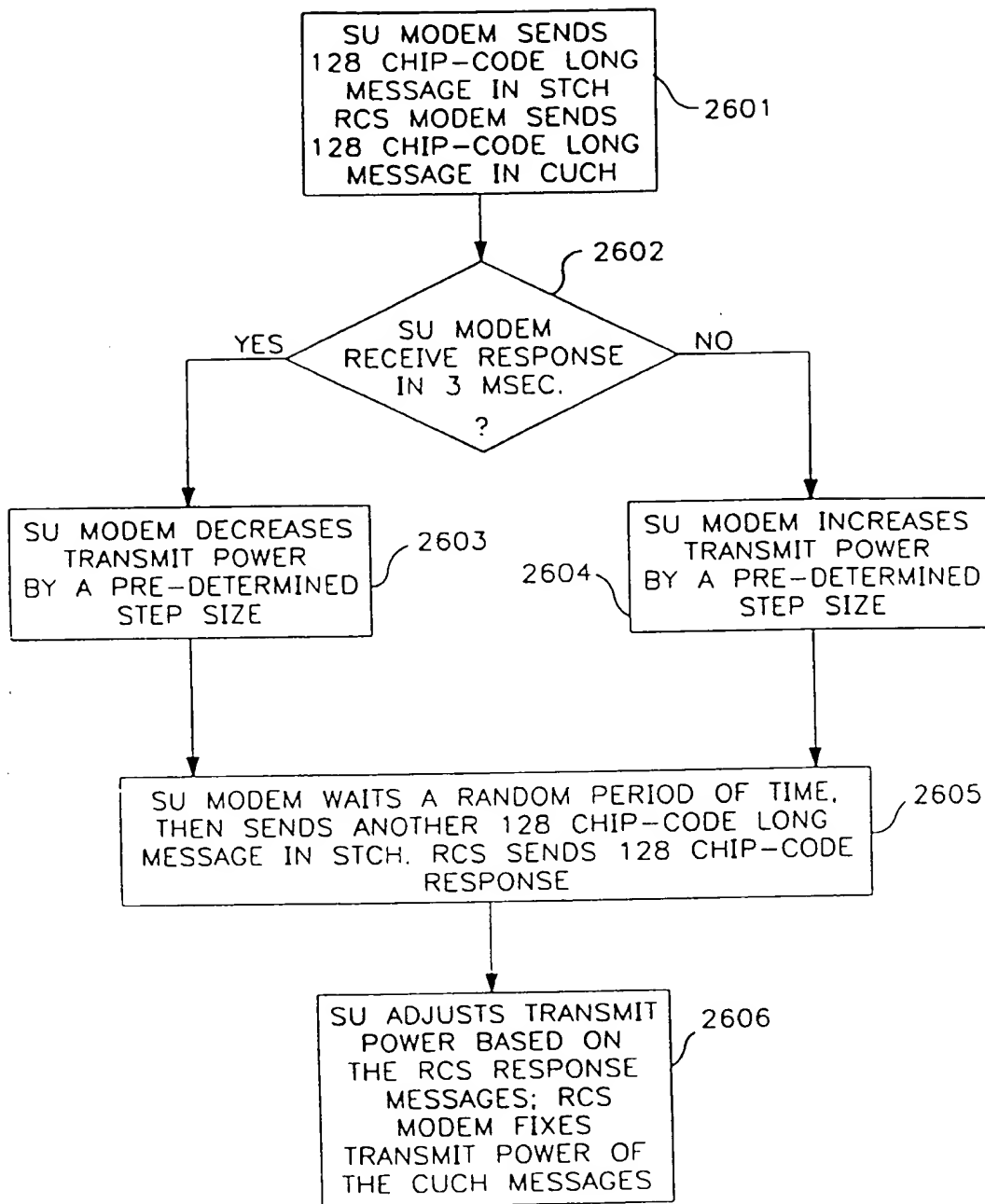


FIG. 26

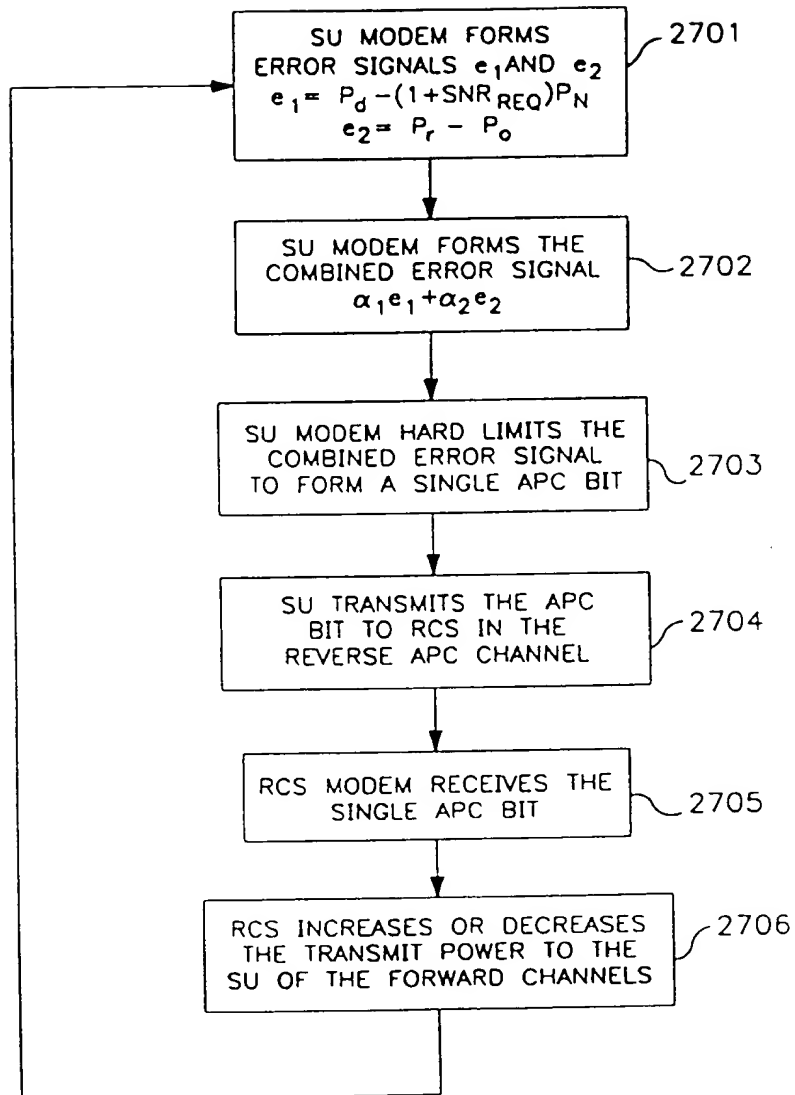


FIG. 27



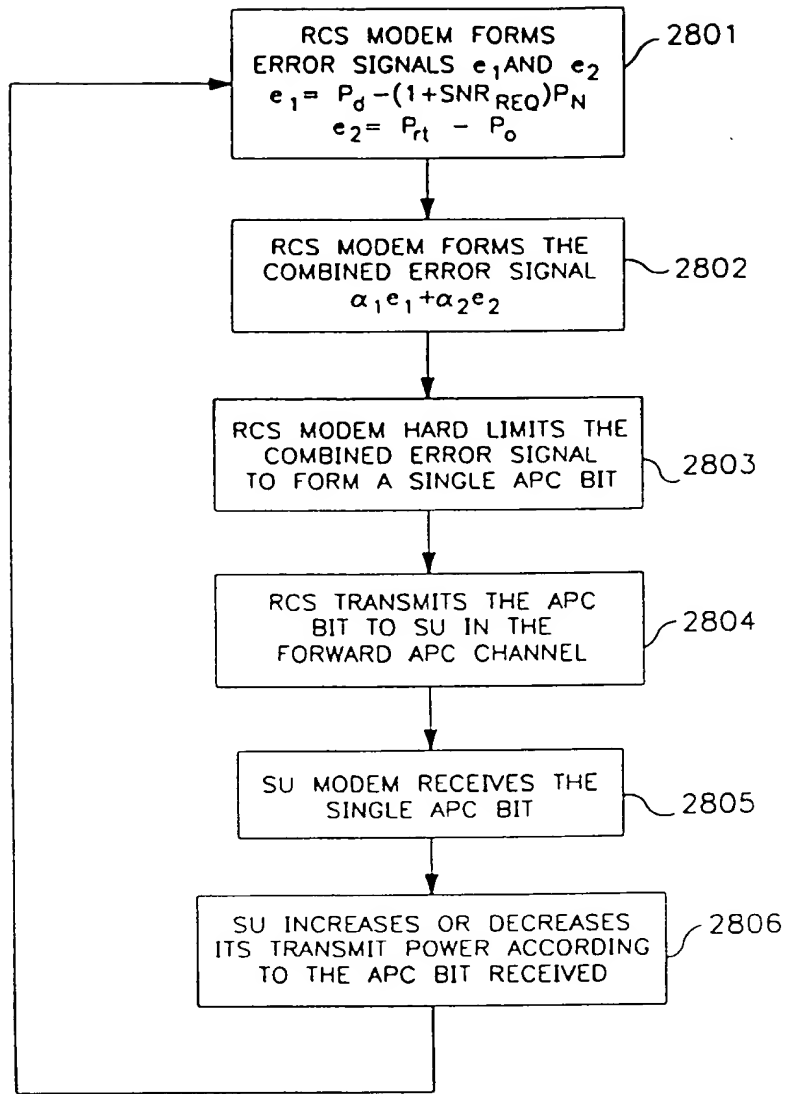


FIG. 28

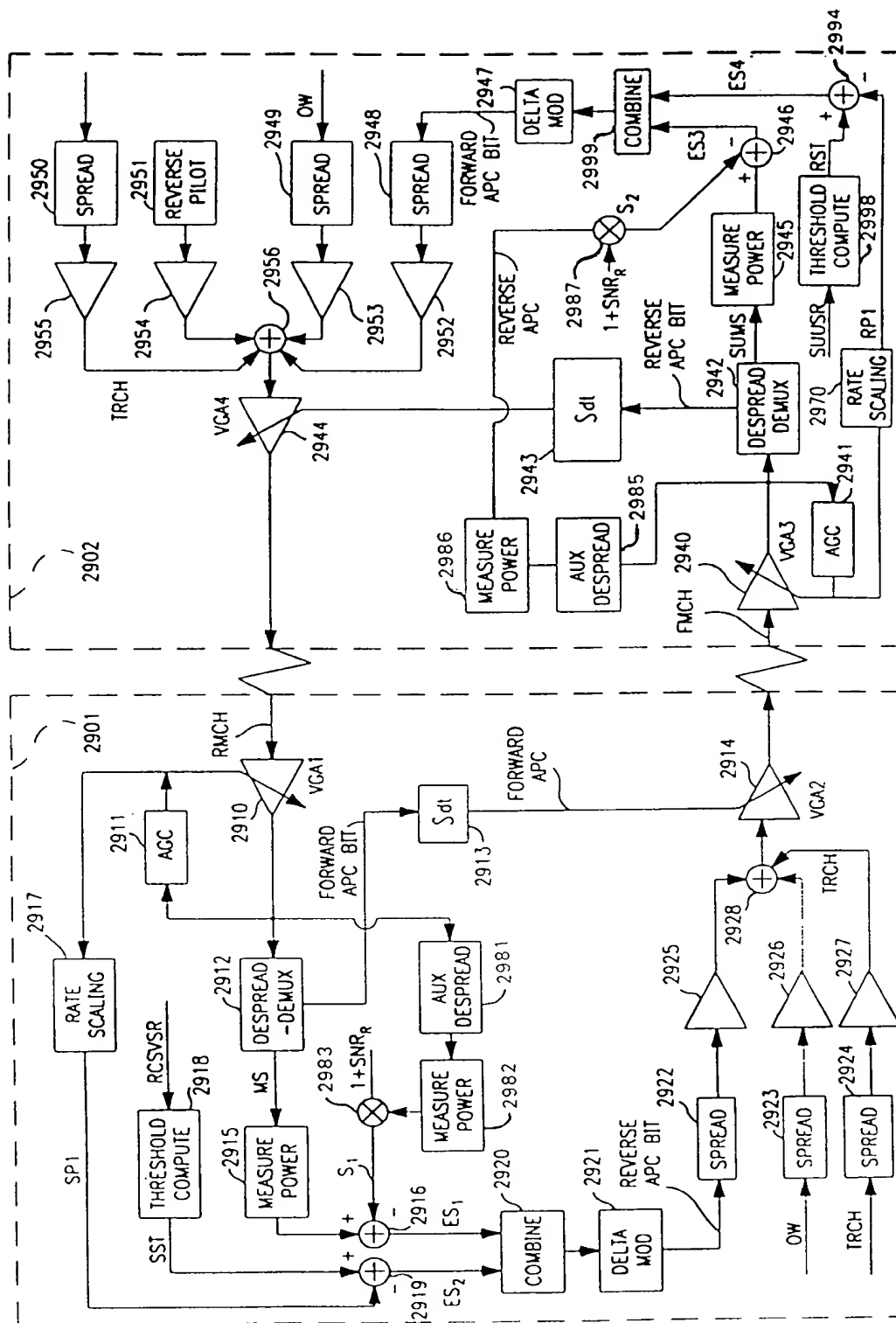


FIG. 29



FIG. 31

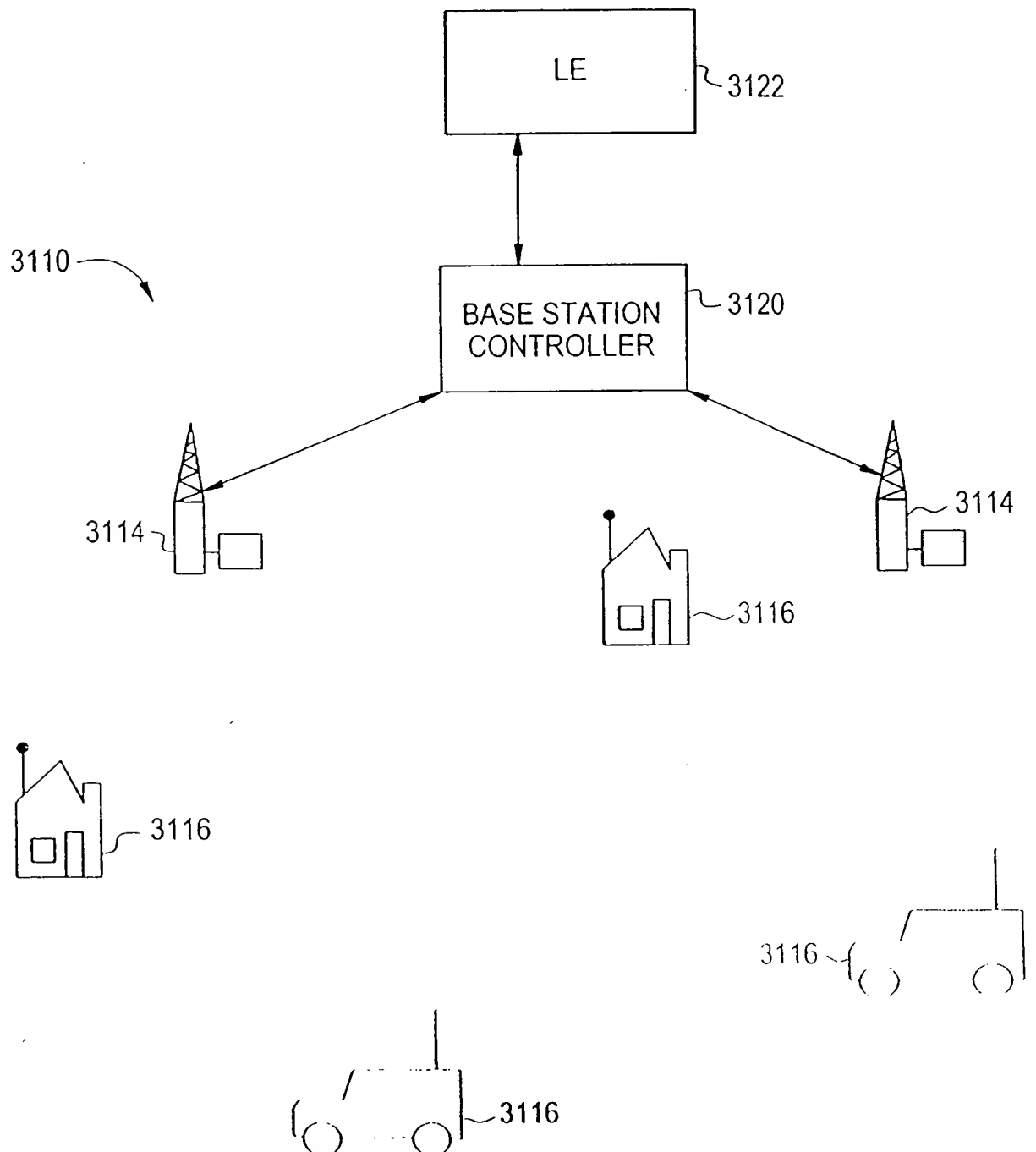


FIG. 32

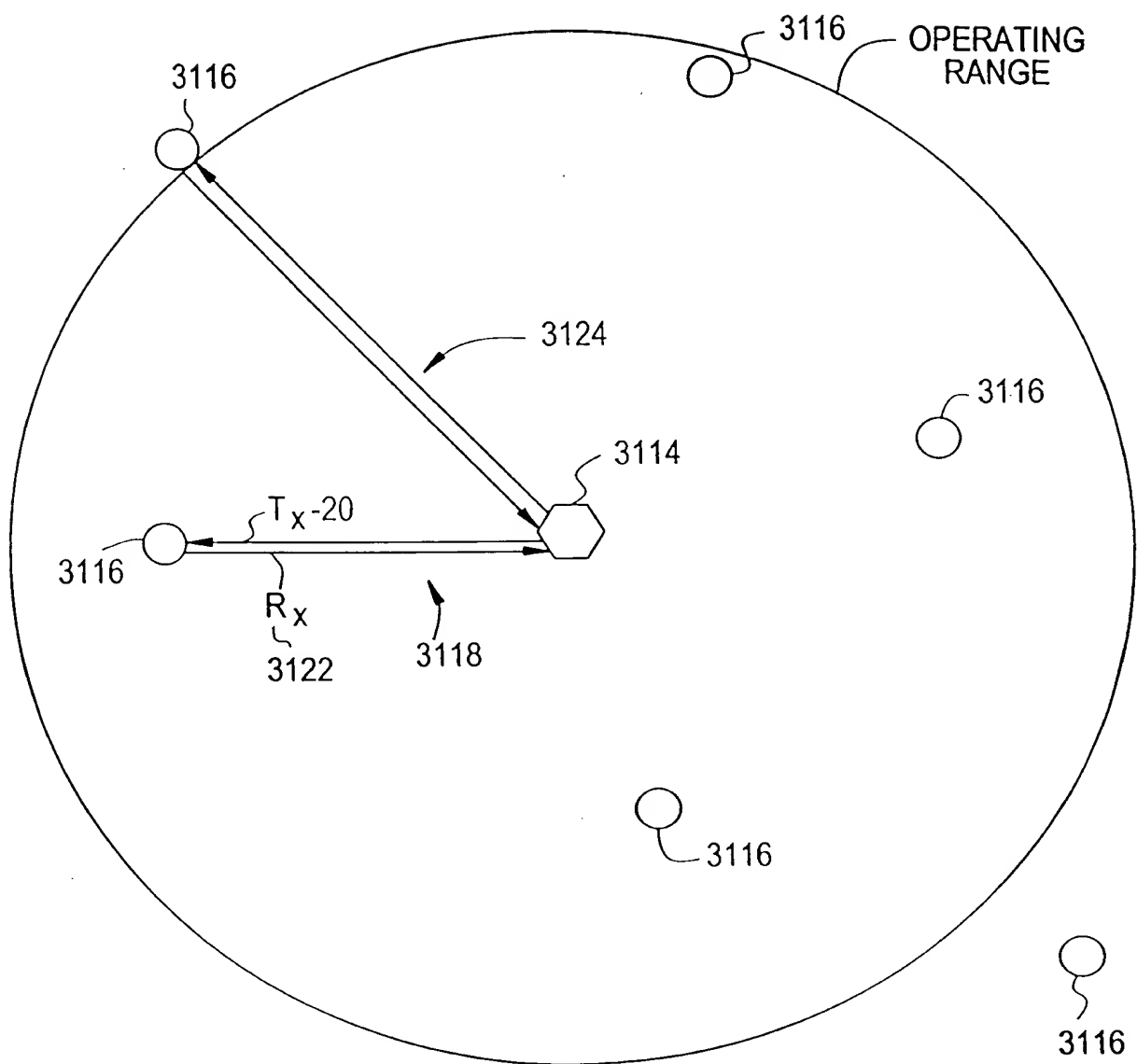
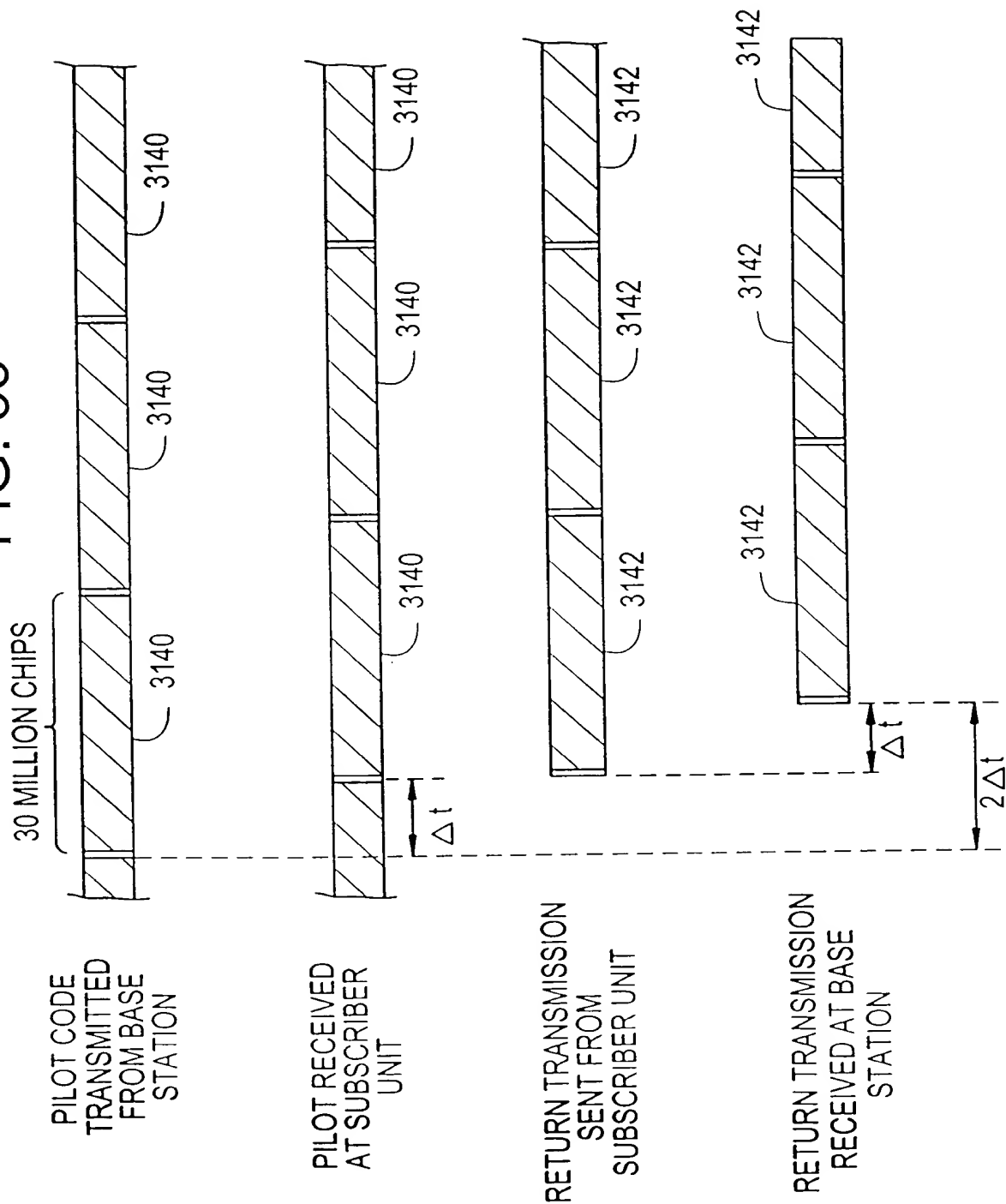


FIG. 33

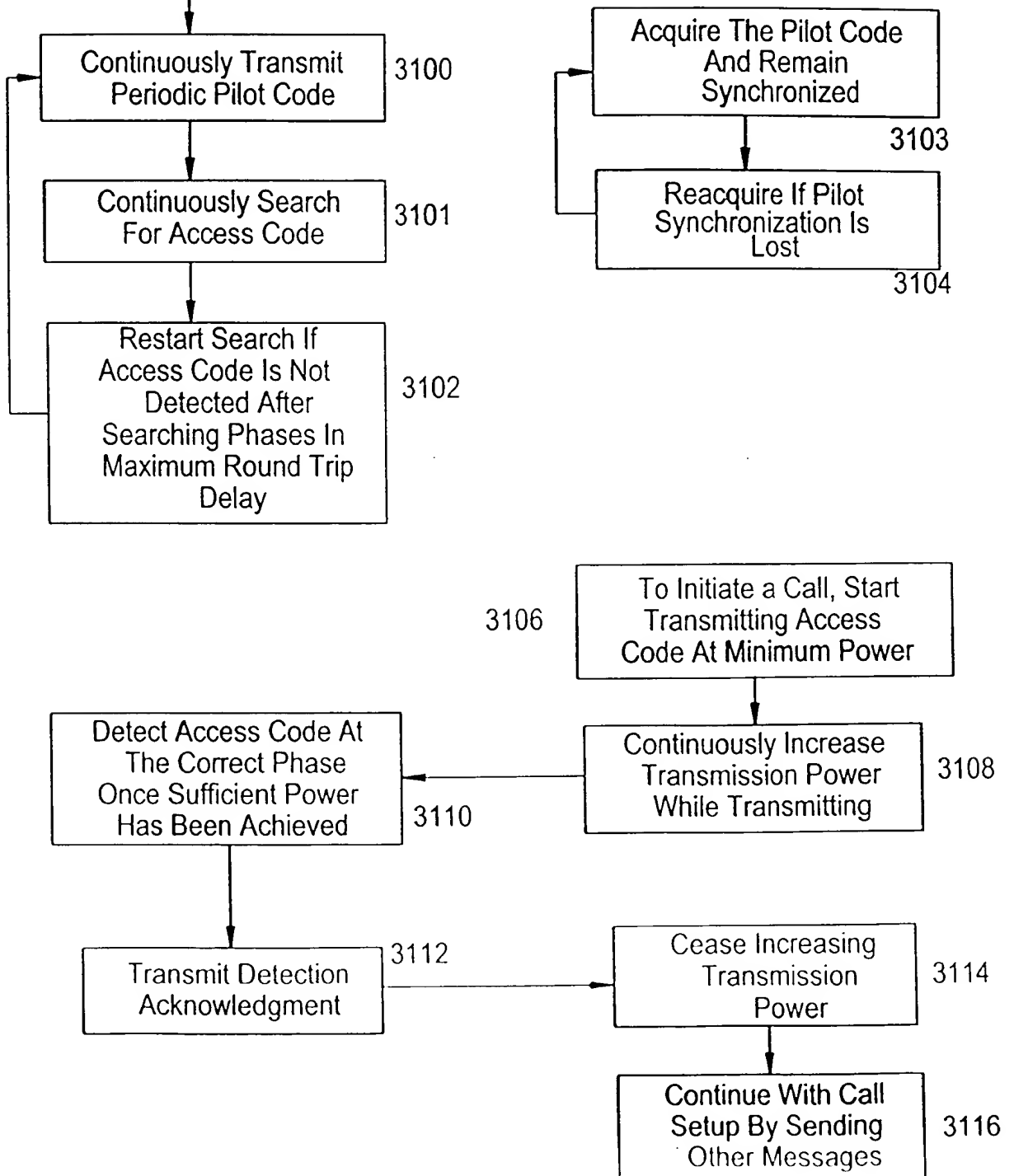


# FIG. 34

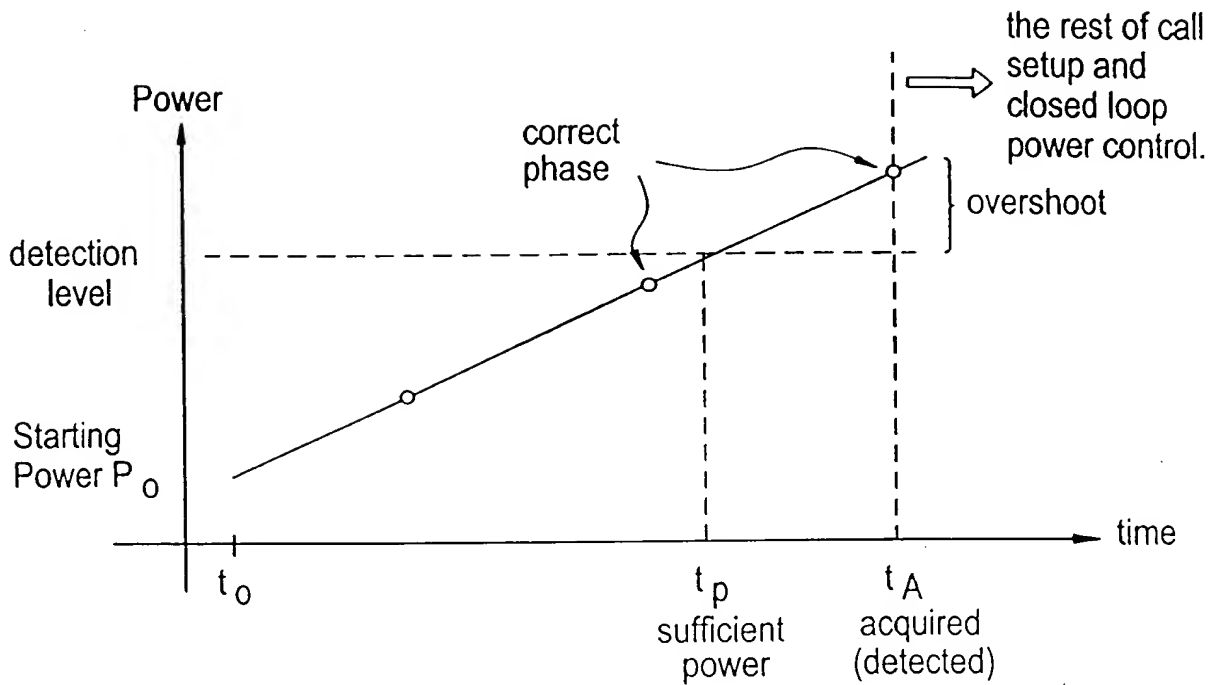
BASE STATION

SUBSCRIBER UNIT

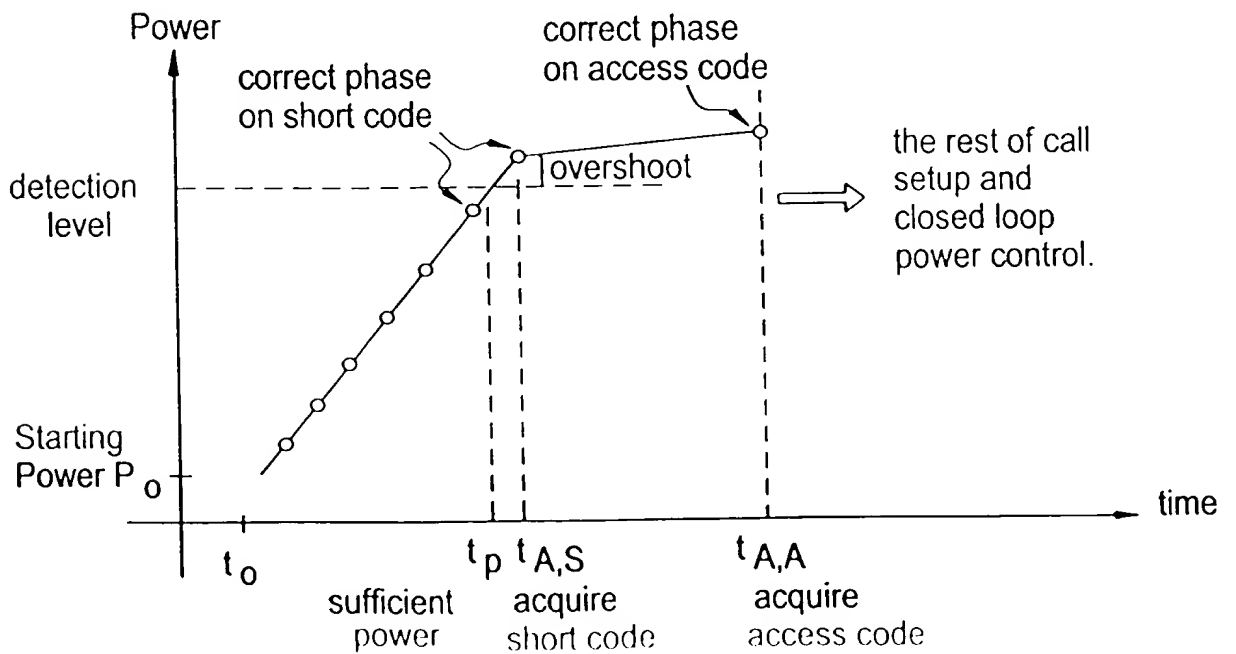
START



# FIG. 35



# FIG. 37





# FIG. 36A

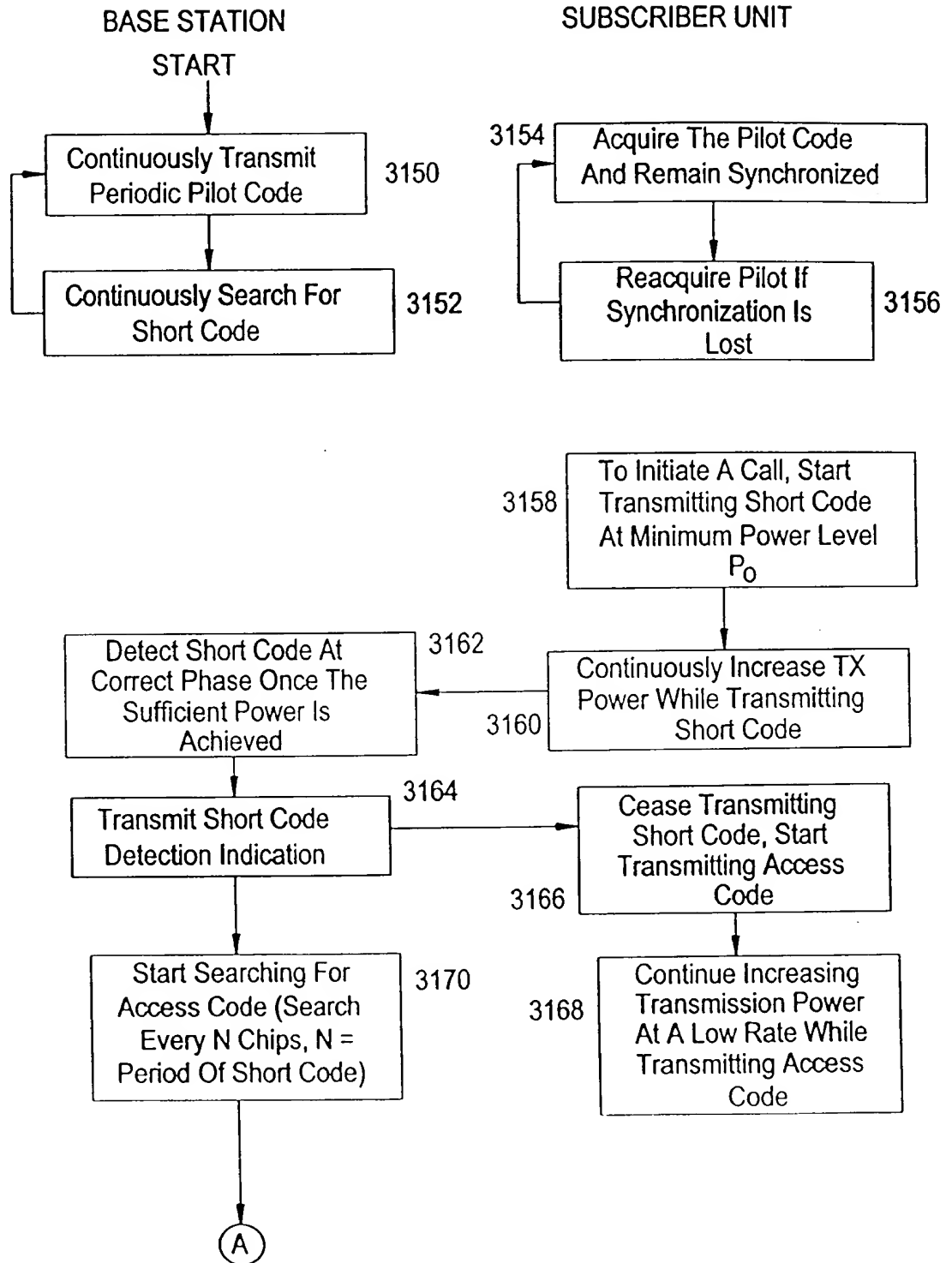


FIG. 36B

BASE STATION

SUBSCRIBER UNIT

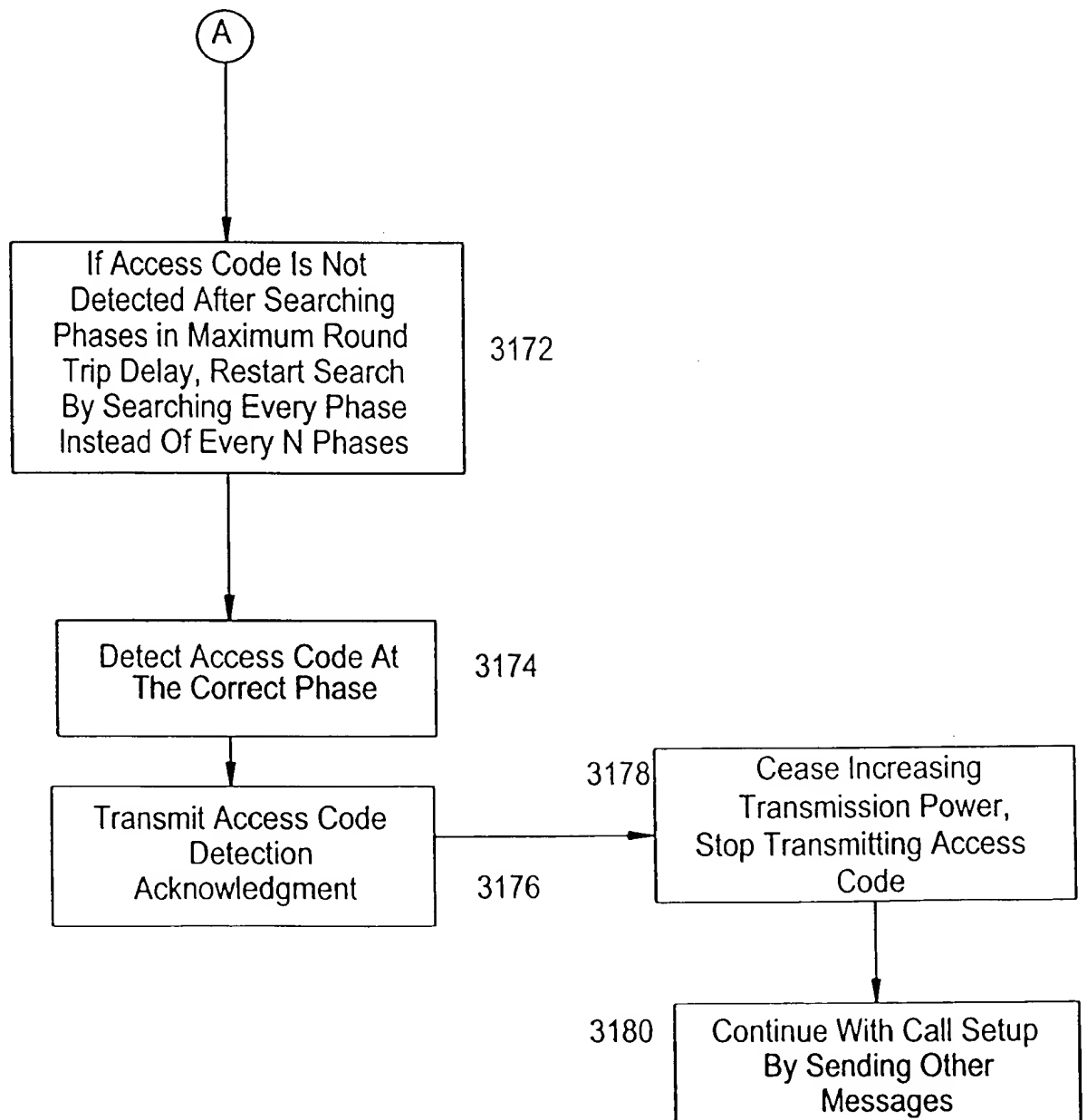


FIG. 38

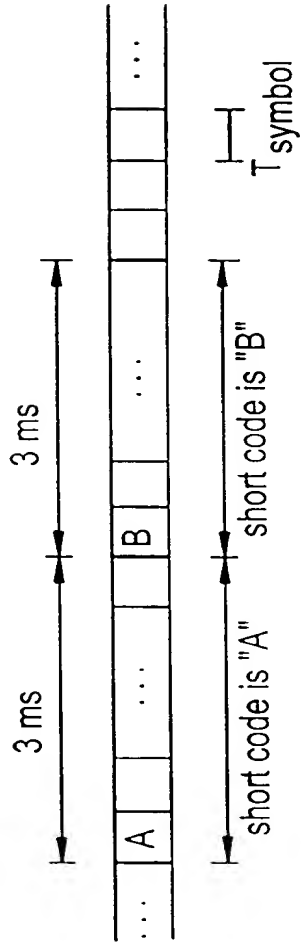


FIG. 39

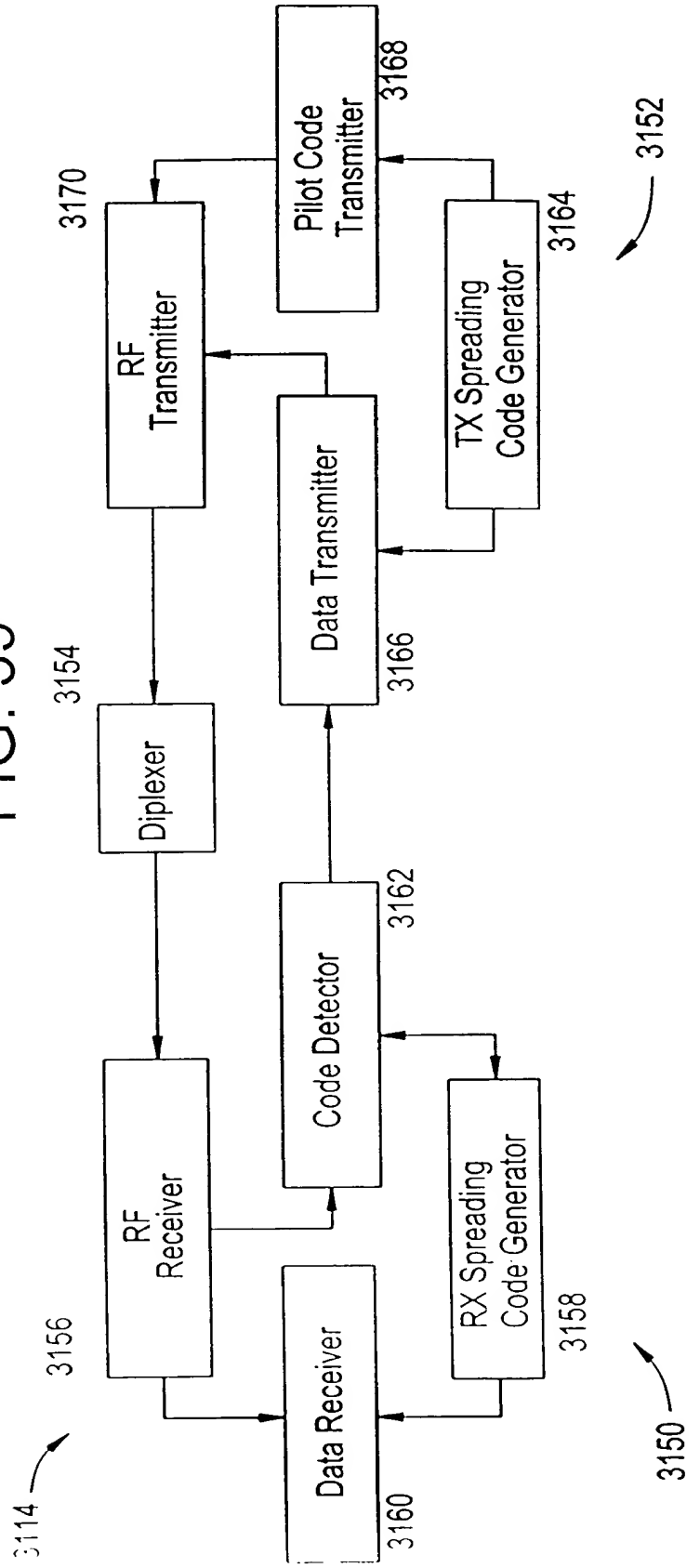


FIG. 40

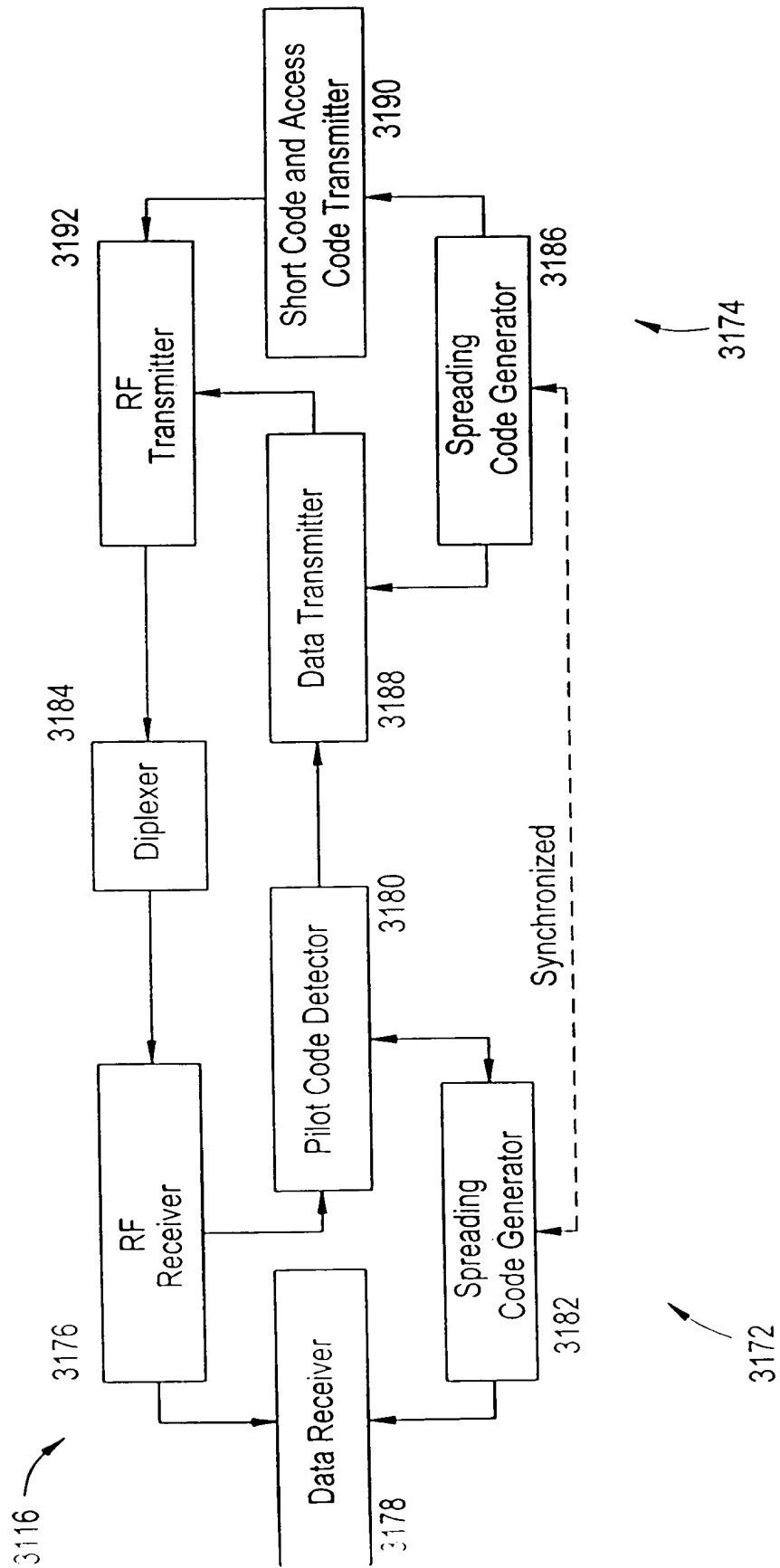


FIG. 41A

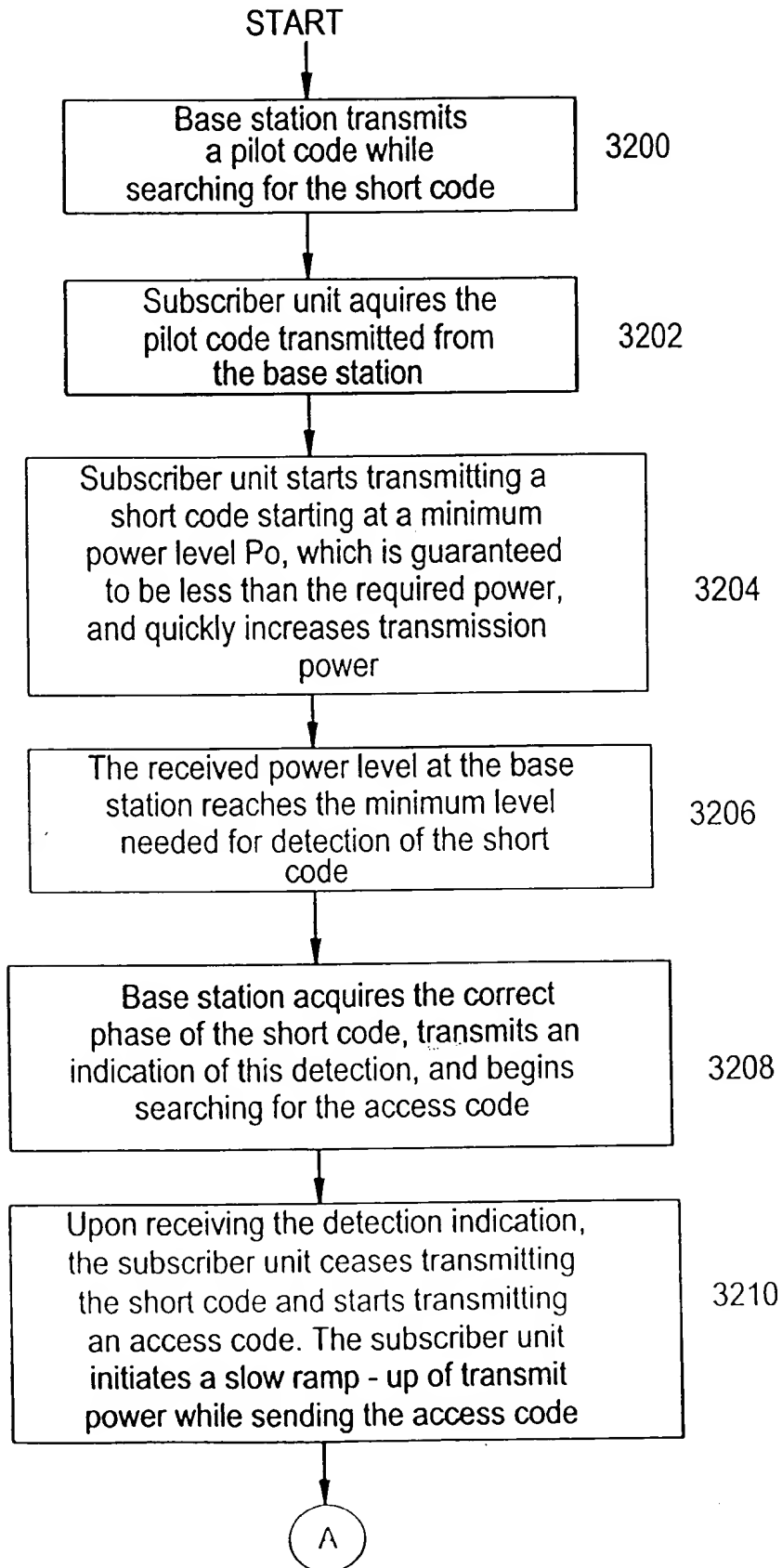


FIG. 41B

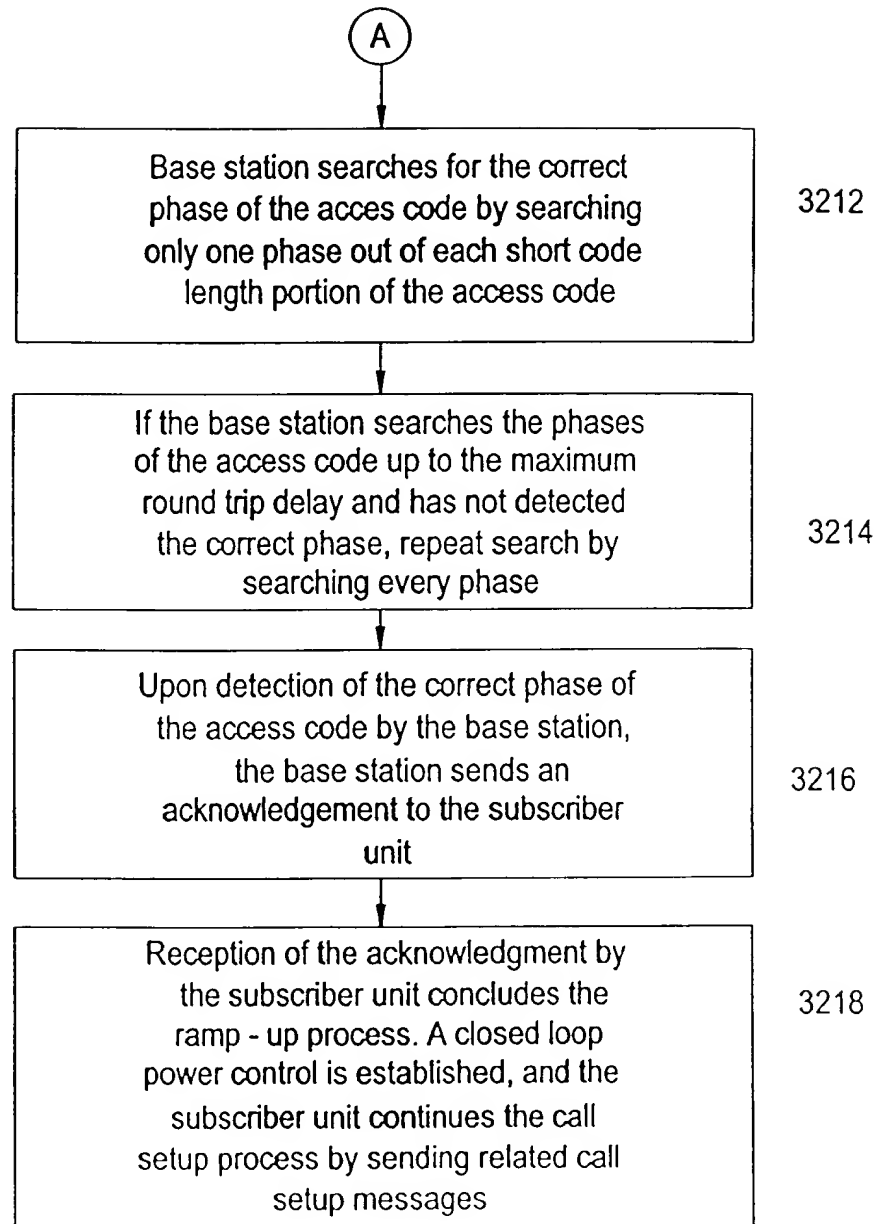


FIG. 42  
PRIOR ART

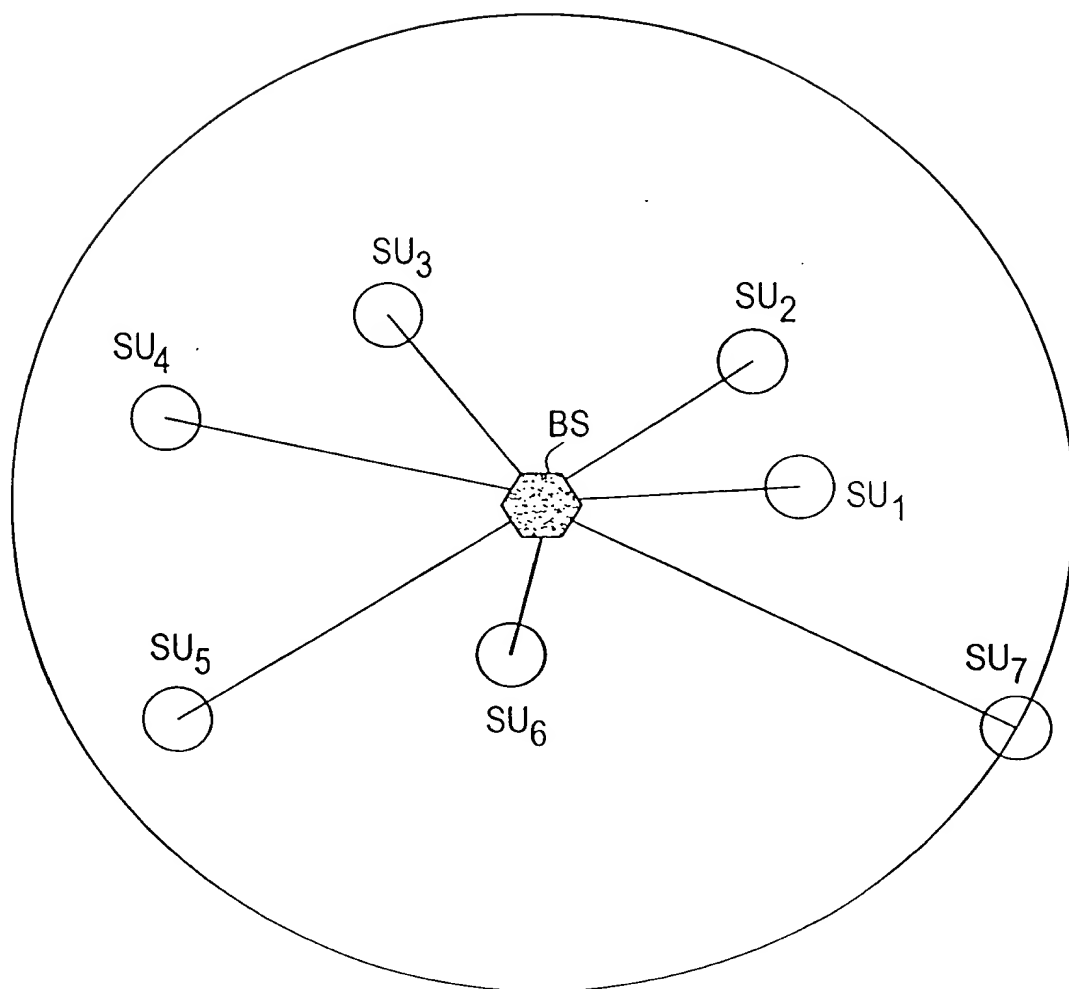


FIG. 43  
(PRIOR ART)

Mean Cell Sweep Time, FSU @ 20 KM

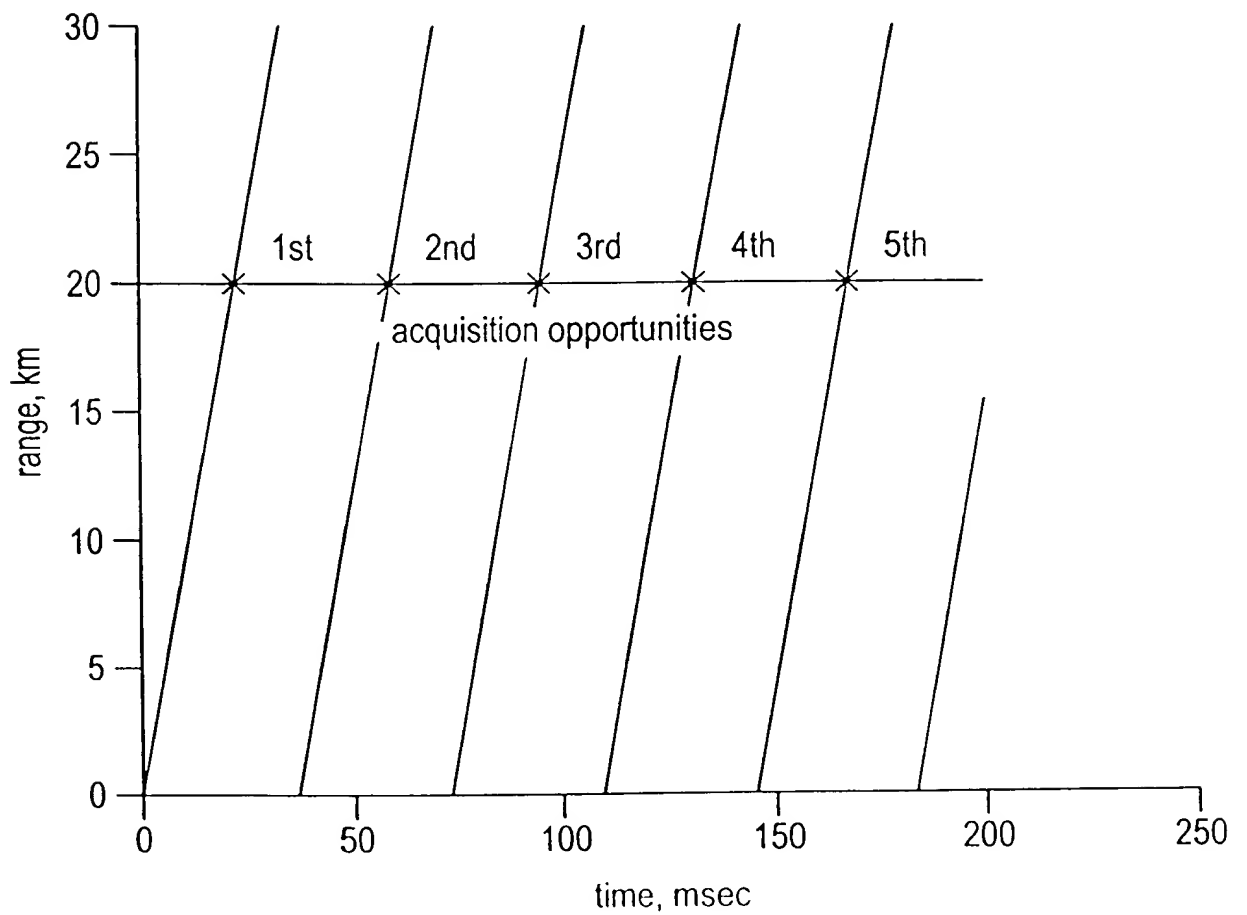




FIG. 44

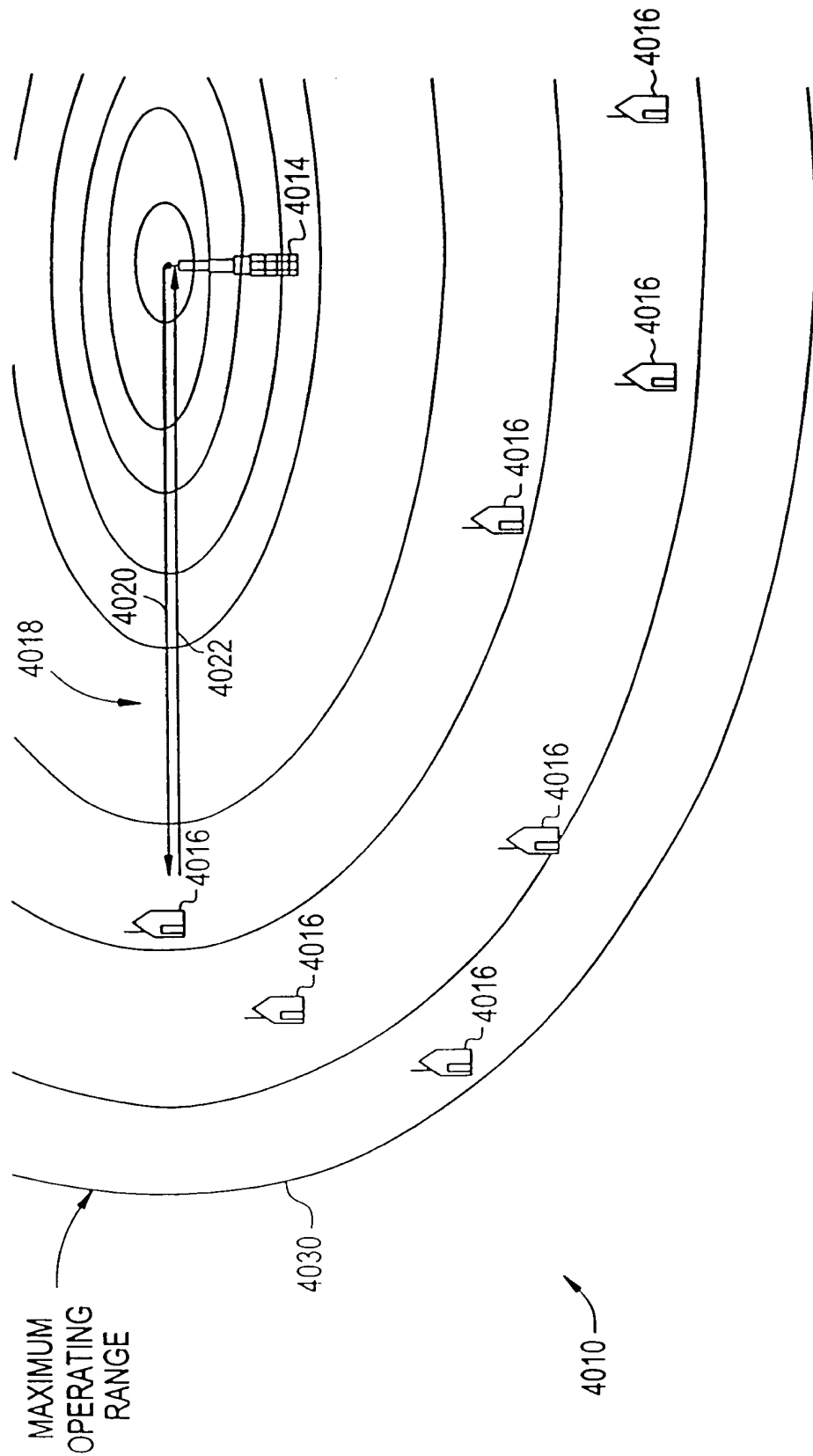


FIG. 45

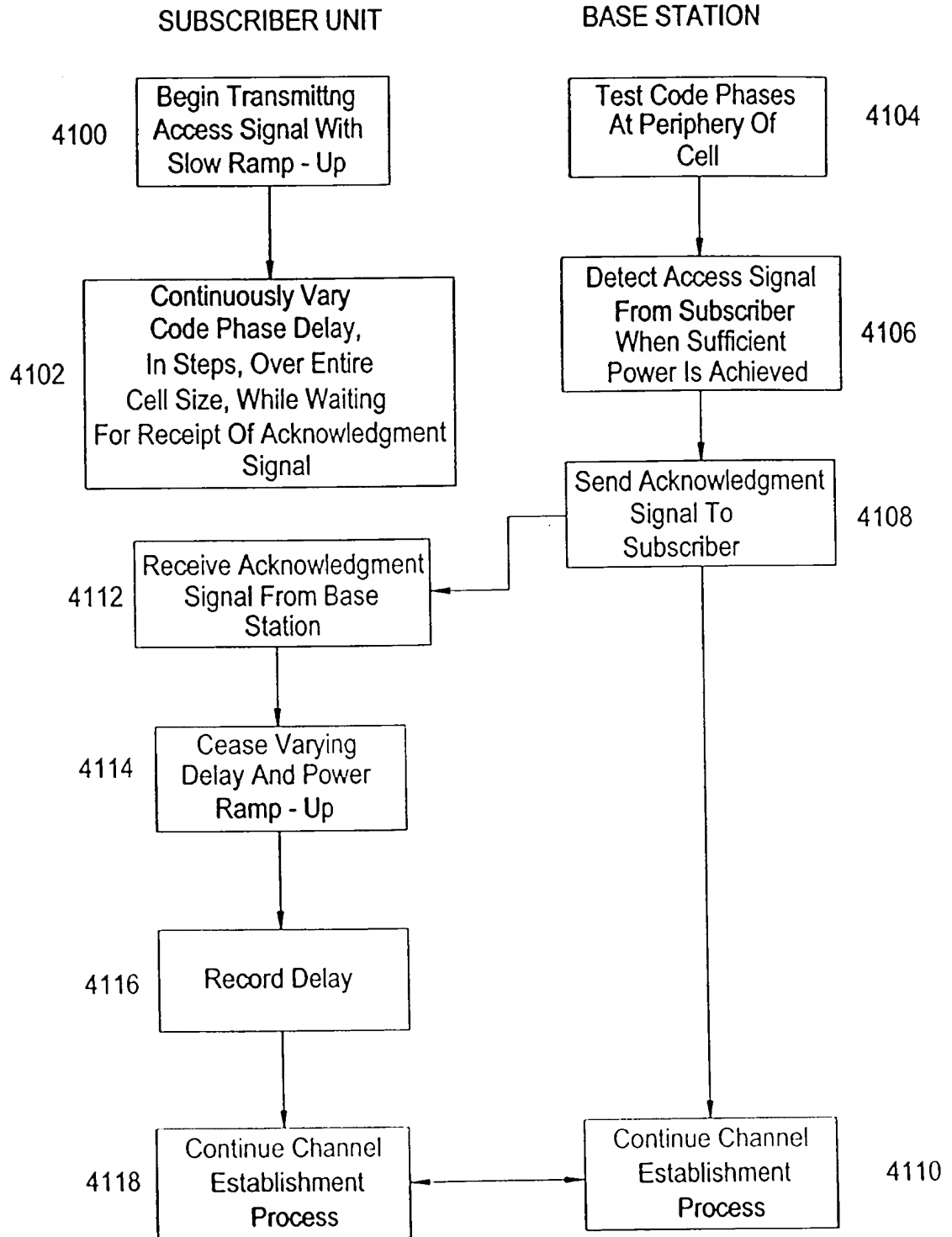


FIG. 46

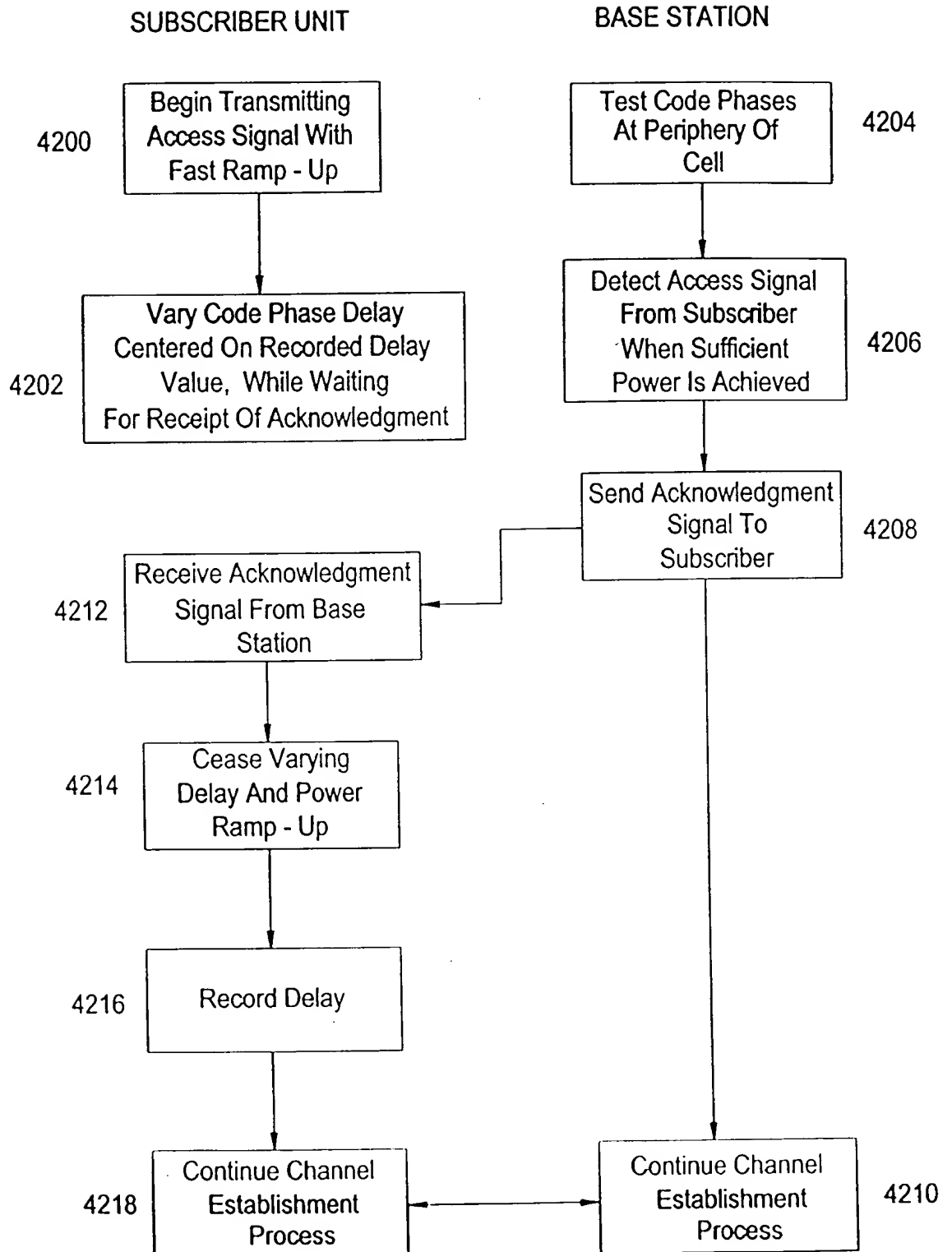


FIG. 47

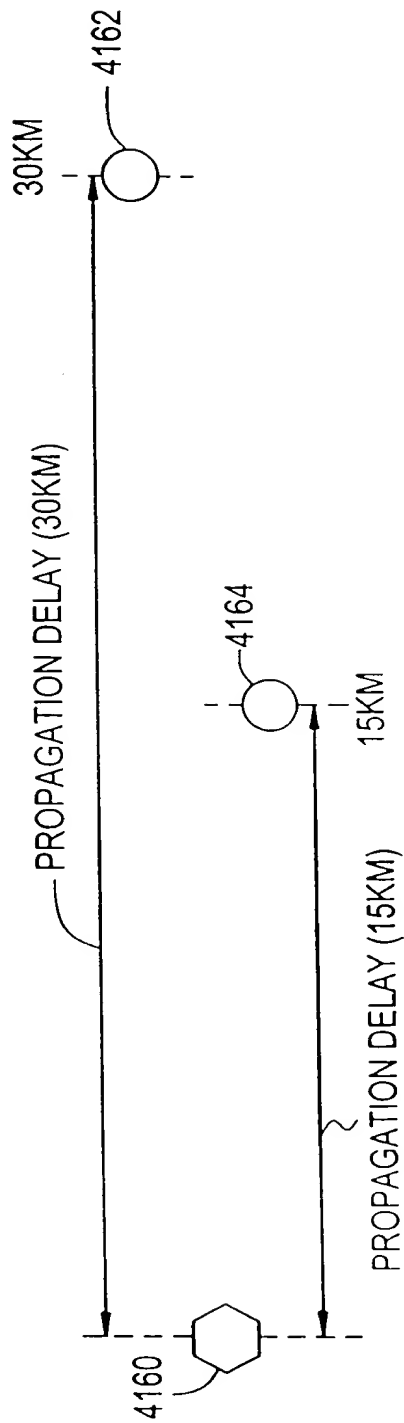


FIG. 48

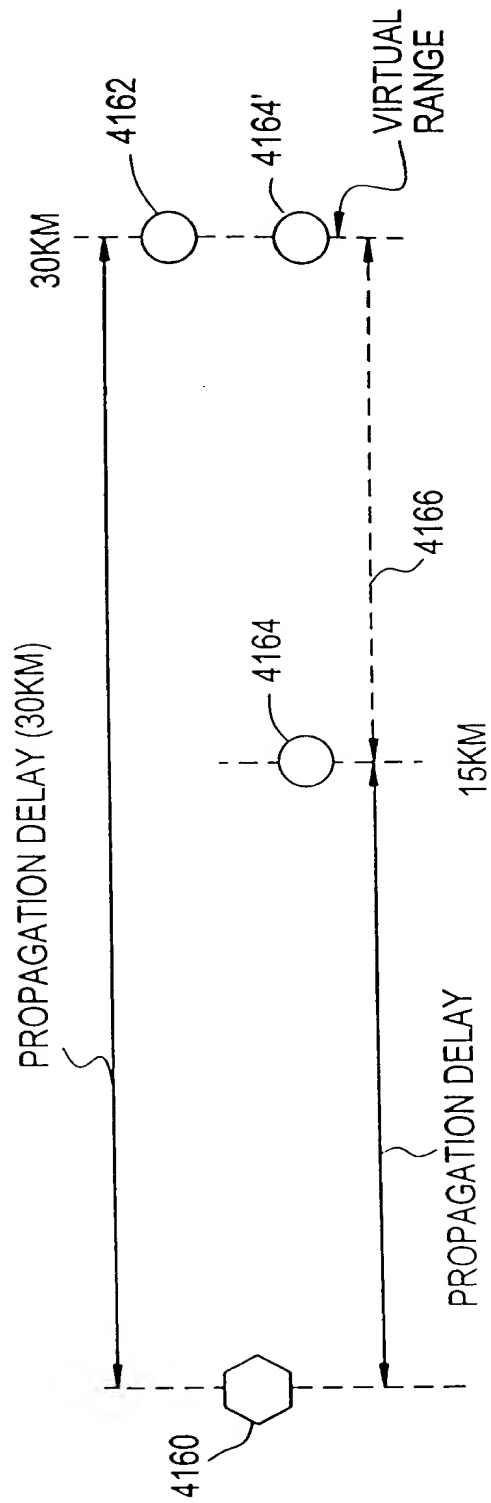


FIG. 49

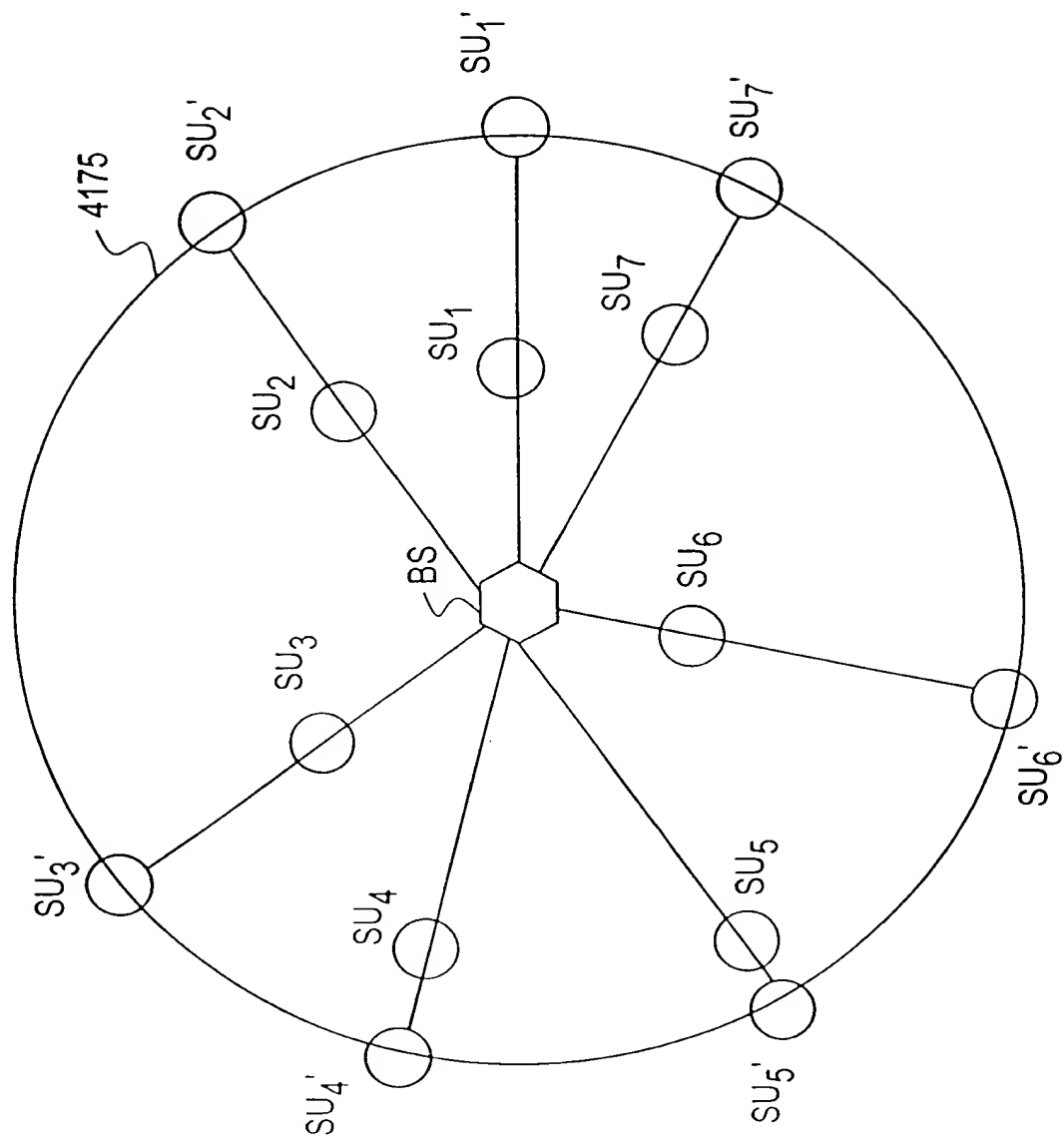


FIG. 50

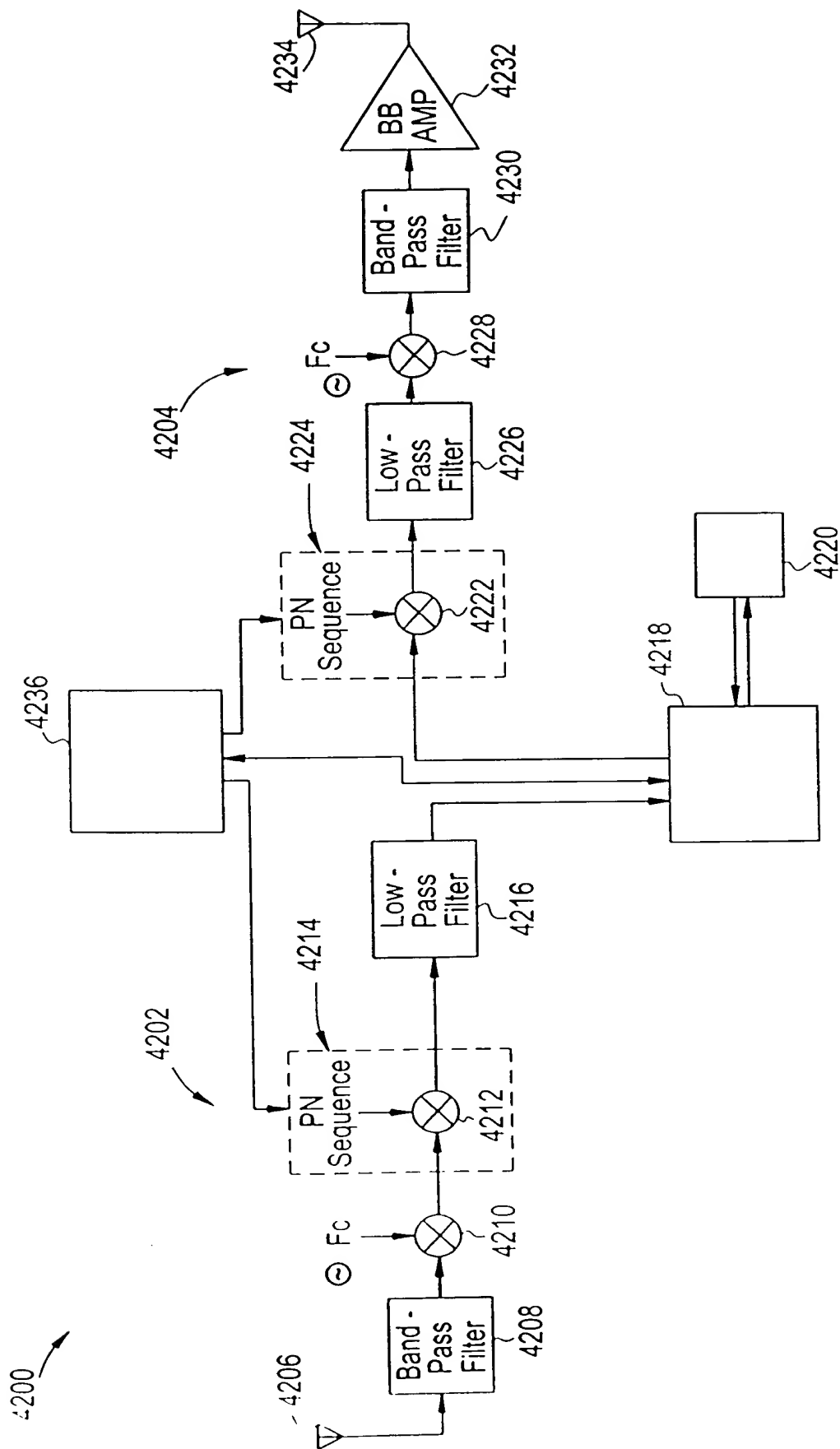


FIG. 51

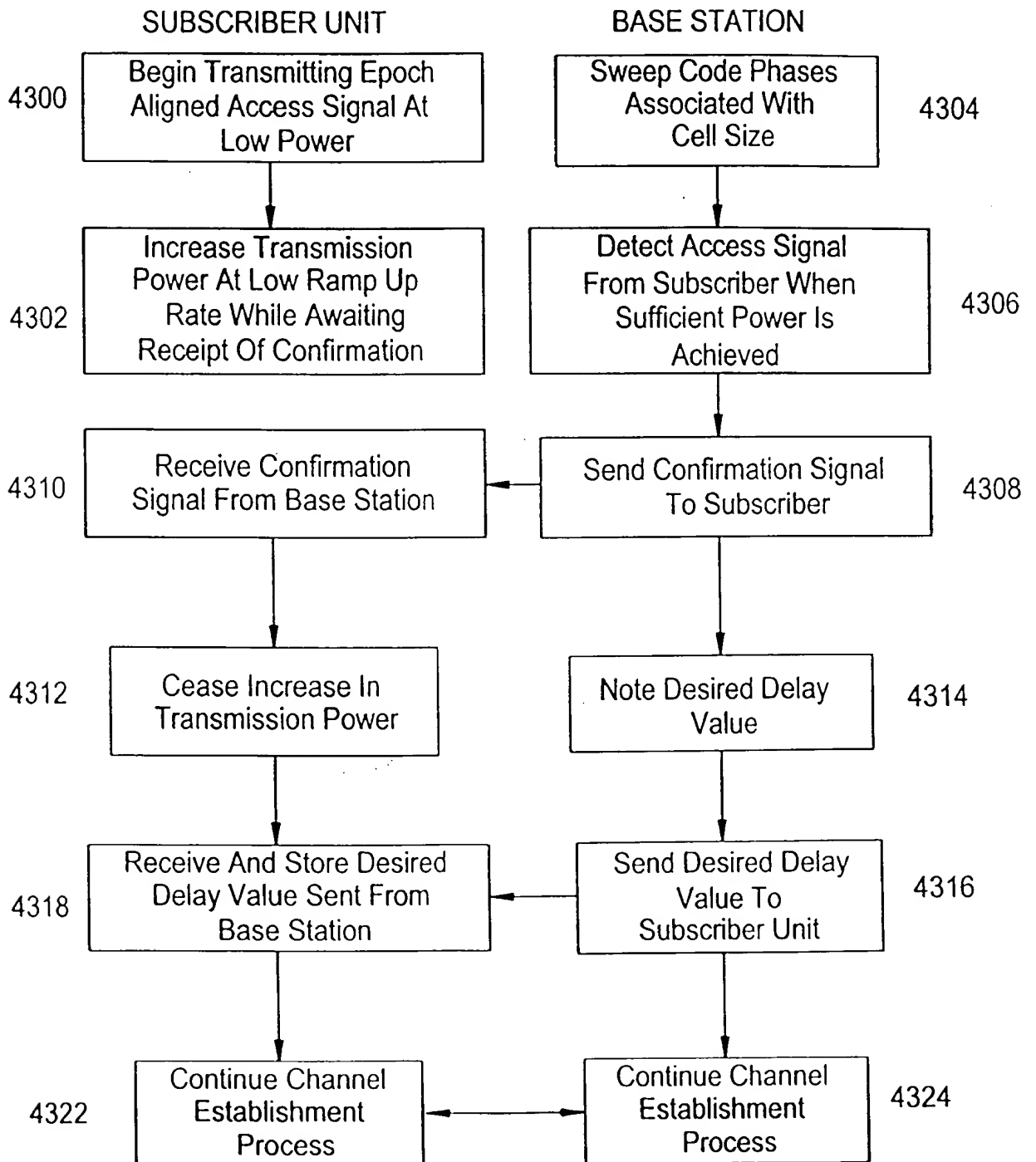
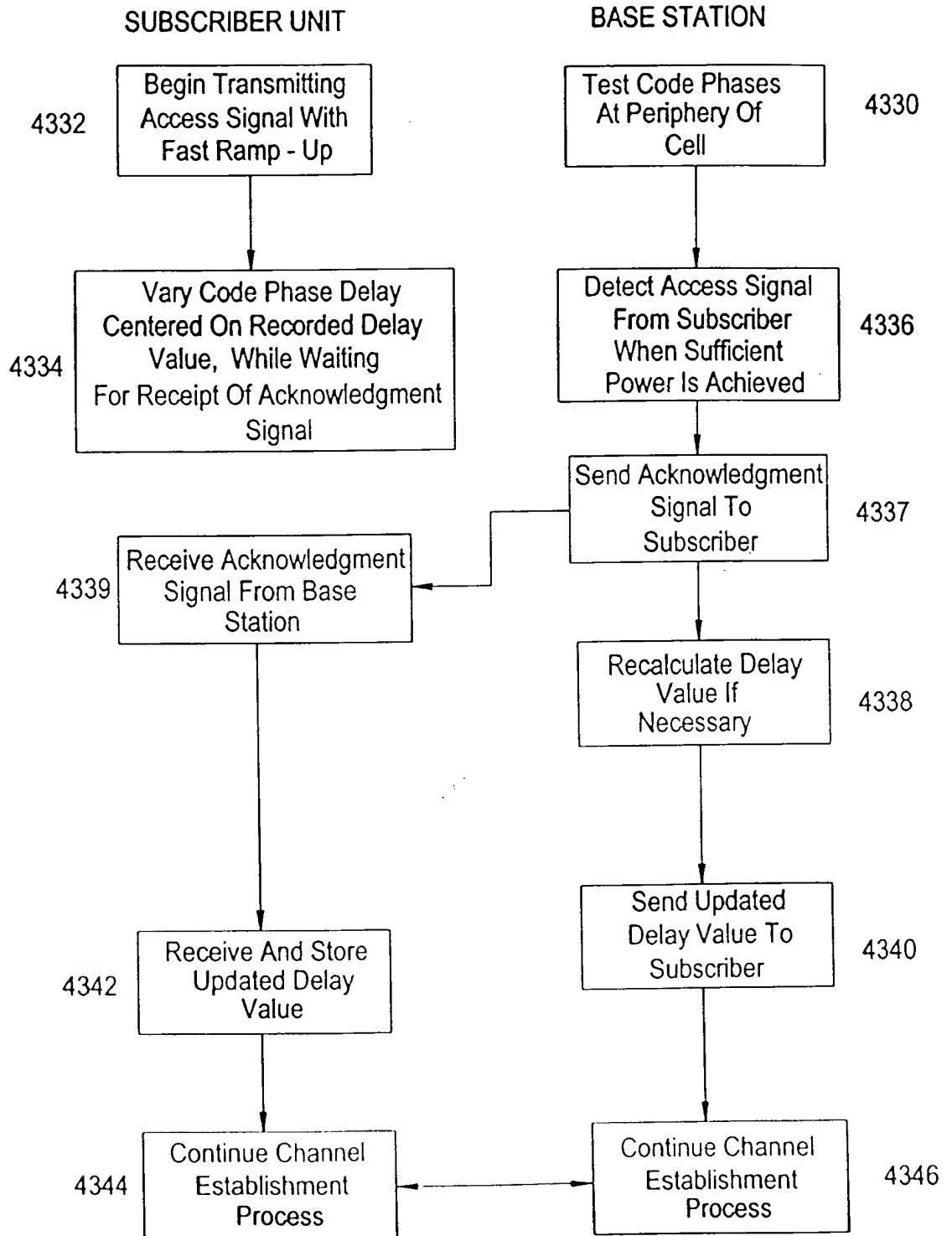


FIG. 52





# FIG. 53

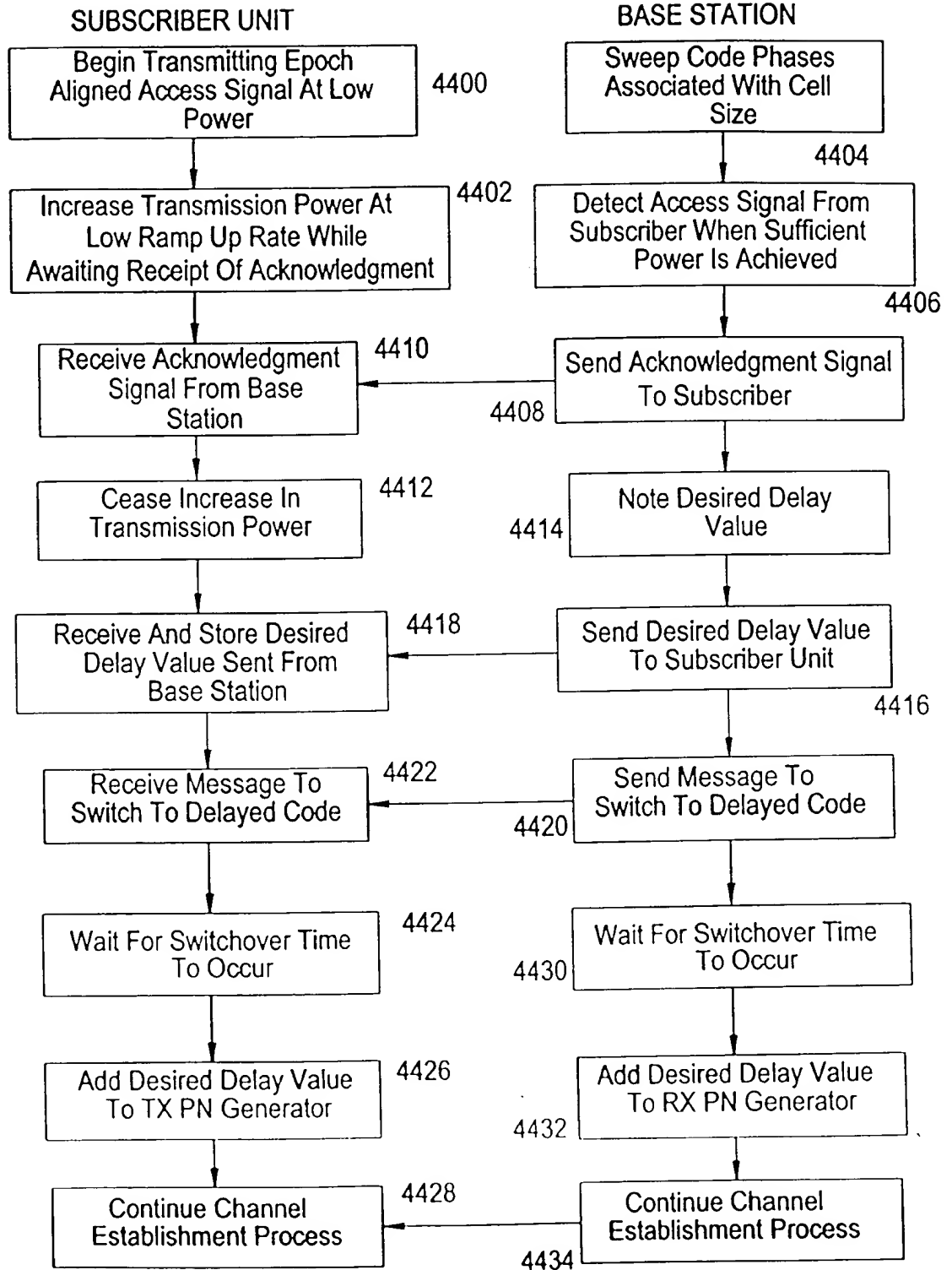


FIG. 54  
PRIOR ART

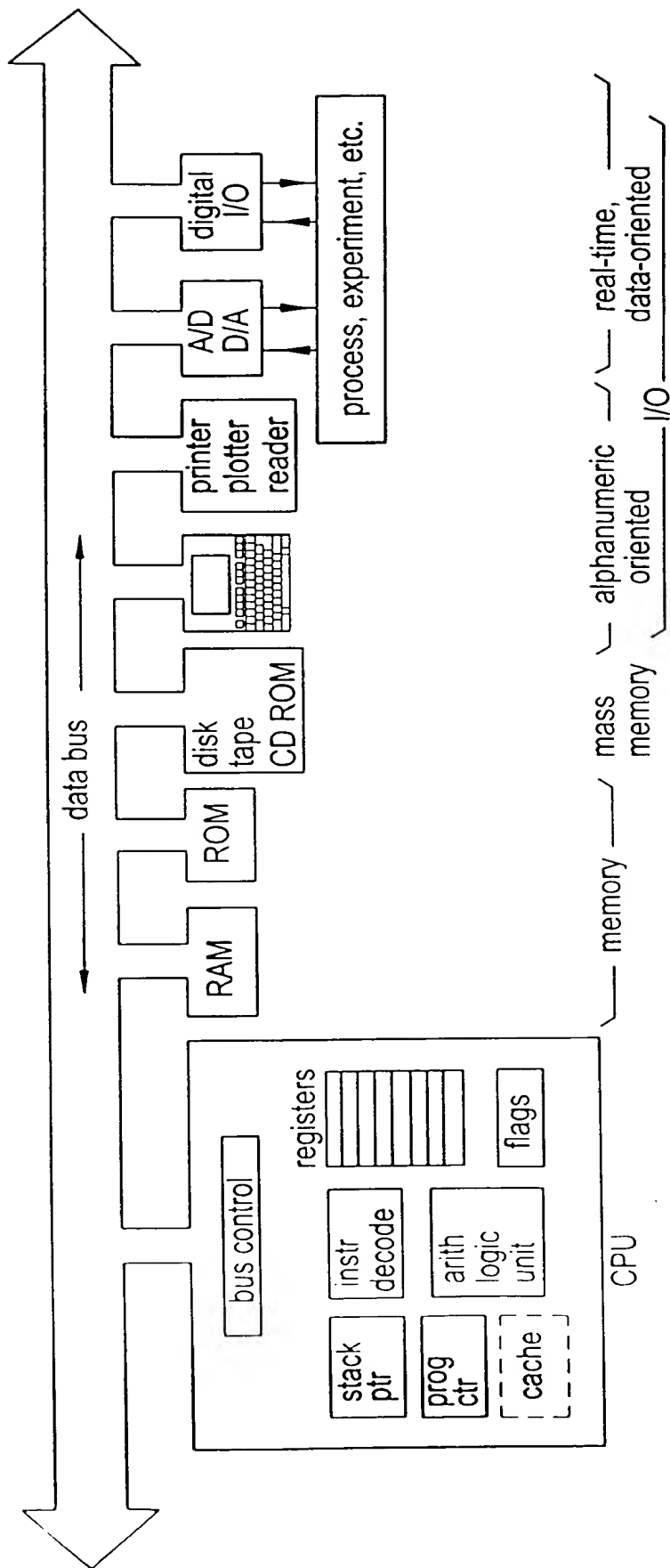
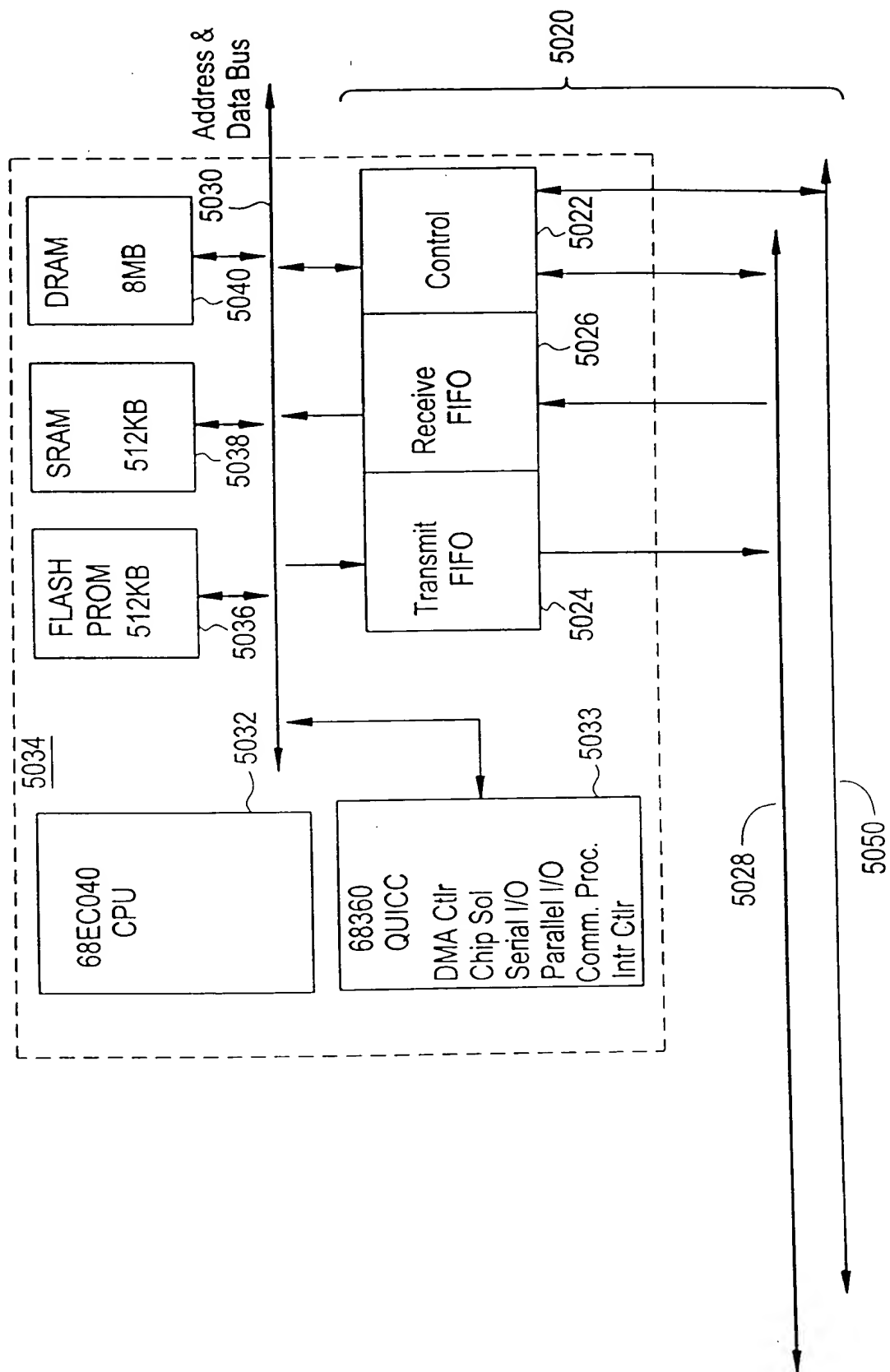


FIG. 55  
PRIOR ART

BUS	RAW bandwidth (Mbyte/s)	Data width	Address width	Block xfer?	MUXed data/adr?	Multimaster?	Sync/Async	IRQ Lines a	Drivers	Connector b	Comments
STD bus		8	16	—	—	—	S	1	TTL	CE	controller-type applications
PCXT	1.2	8	20	—	—	—	S	5E	TTL	CE	original IBM PC & compatibles
PCAT	5.3	8,16	20,24	—	—	(c)	S	10E	TTL	CE	accepts PC/XT cards
EISA	33	8,16,32	20,24,32	•	—	•	S	11P	TTL	CE	enhanced PC/AT; auto-configure
MicroChannel	20	8,16,(32)	24,(32)	•	—	•	A	11	TTL	CE	IBM PS/2; auto-configure
Q-bus	2	16	22	•	•	•	A	4	(d)	CE	LSI-11, $\mu$ VAX-I, II; daisy-chained IACK
Multibus I	10	8,16	20,24	—	—	•	A	8	TTL	CE	Intel; SUN-I and others
CA-MAC	3	24	9	•	—	—	S	L	TTL/OC	CE	data acquisition & control bus
VAX BI	13.3	8,16,24,32	32	•	•	•	S	4	TTL	ZIF	VAX 780, 8600 series; parity
Multibus II	40	8,16,24,32	16,32	•	•	•	S	M	TTL	DIN	parity; 40MB/s for blk xfer, 20M otherwise
NuBus	40	32	32	•	•	•	S	M	TTL	DIN	Macintosh II adds 1 dedicated INT per slot; <sup>nm</sup>
VME	40	8,16,32	16,24,32	•	—	•	A	7	TTL	DIN	daisy-chained IACK; SUN-3
Futurebus	120			•	•	•	A	—	(d)	H	communication across many crates
Fastbus	160	32	32	•	•	•	A	M	ECL	H	

- (a) E-edge-sensitive; L-LAM ("look at me"); M-"int" via bus mastership; P-programmable edge-or level-sensitive interrupts.  
 (b) CE-card-edge; DIN-2-part "Eurocard" 96-pin connector; H-high density 2-part conn. (c) almost. (d) National Semi special.

# FIG. 56



Year	1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100
1970	1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100

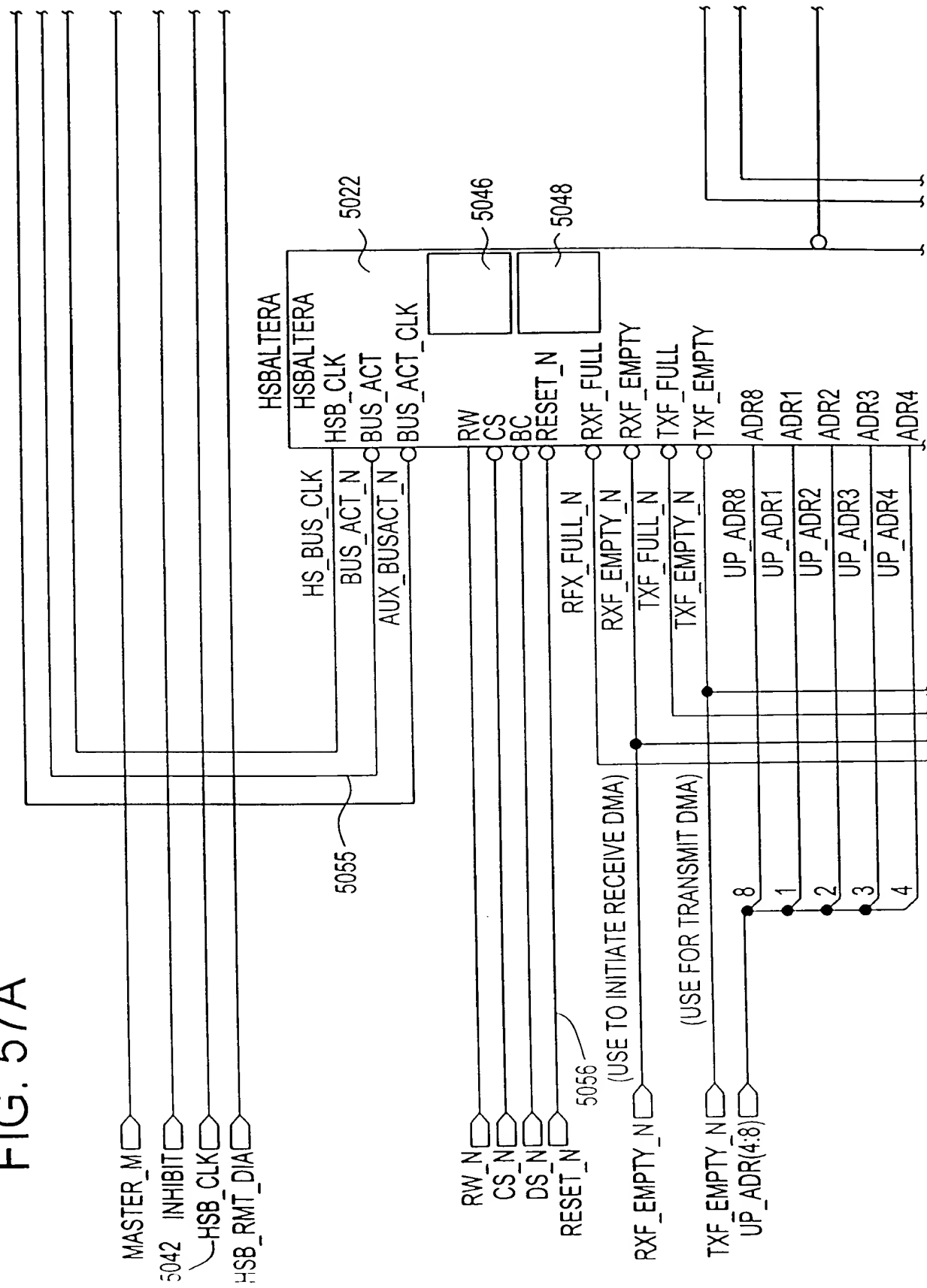


FIG. 57B

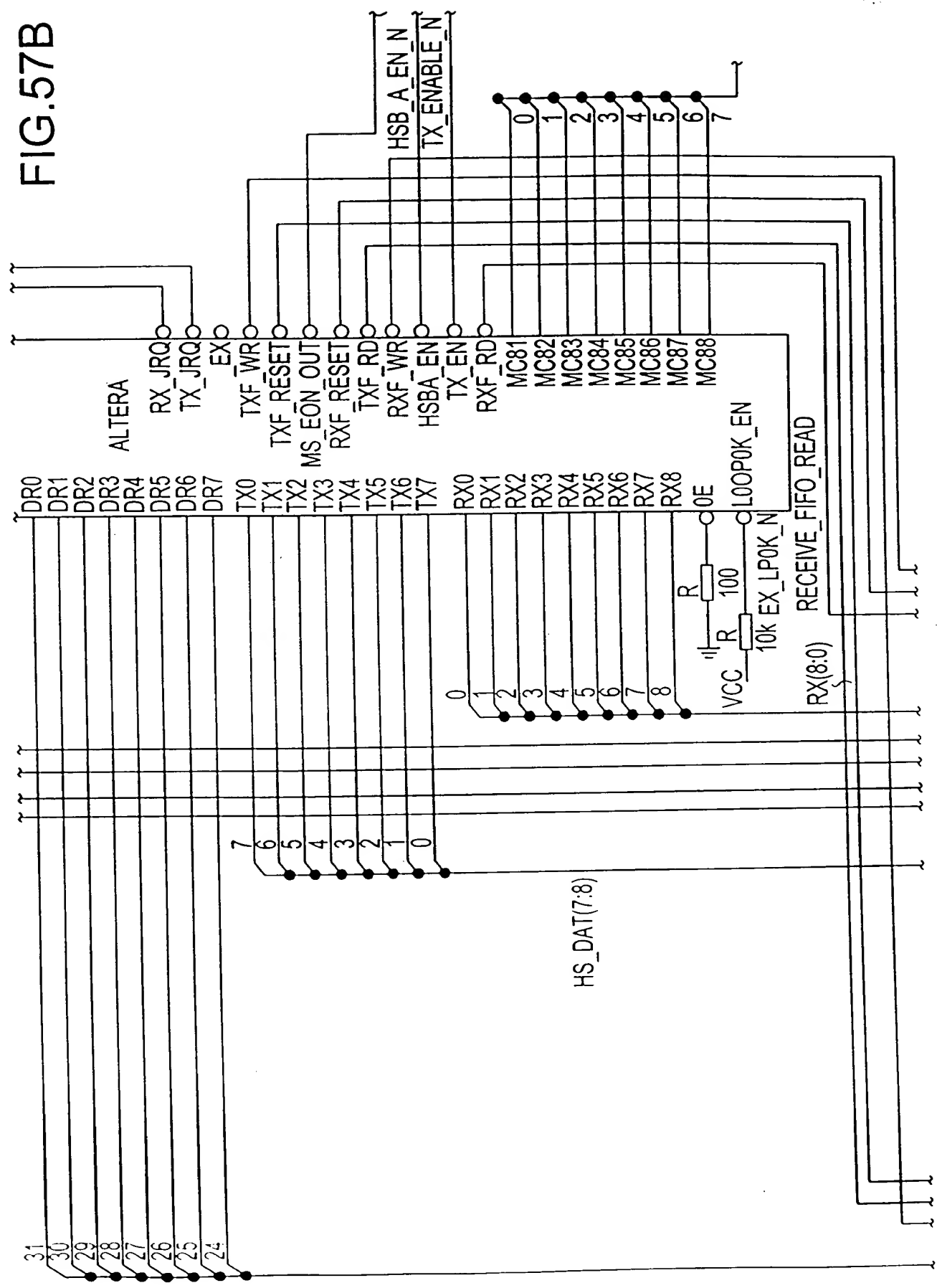
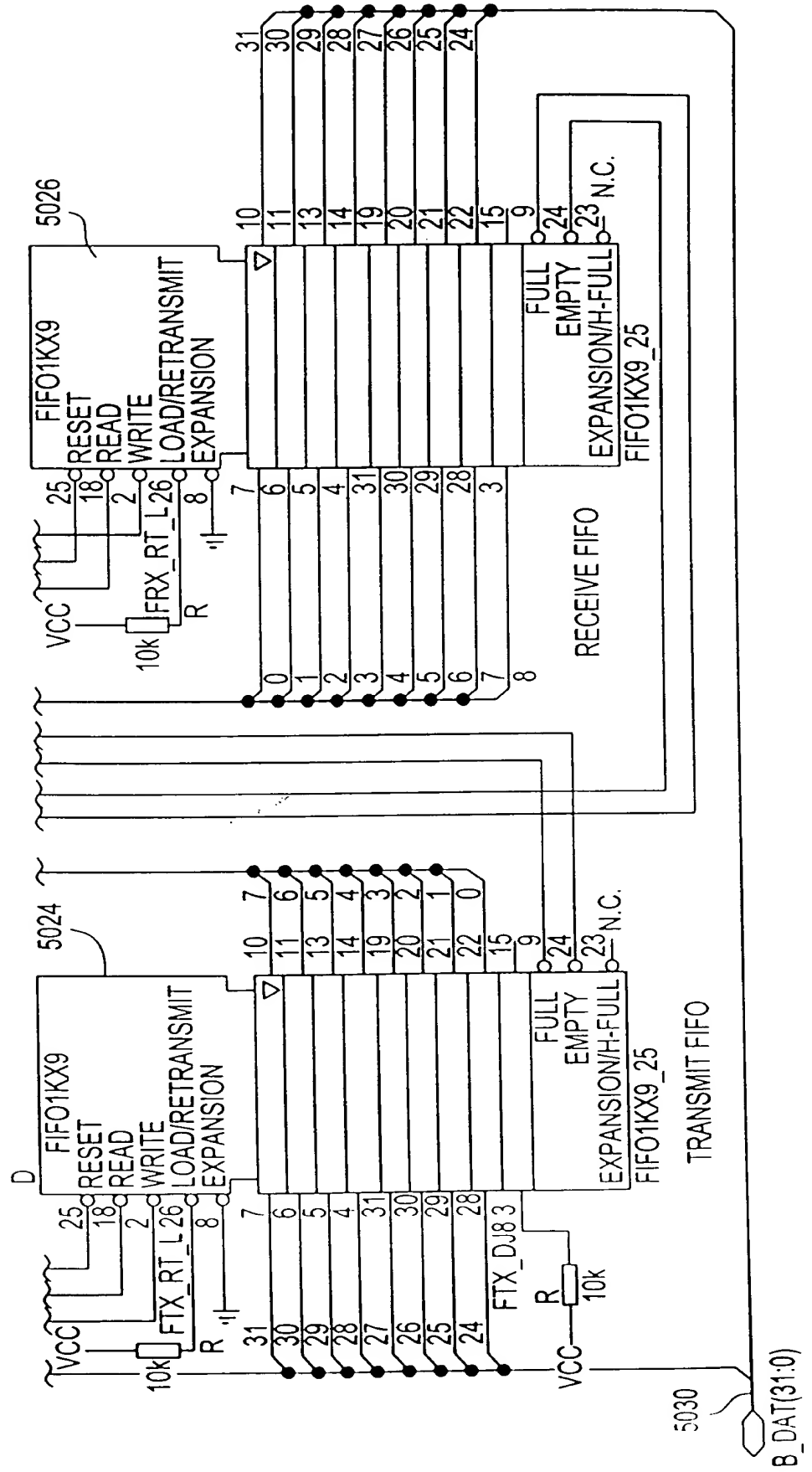
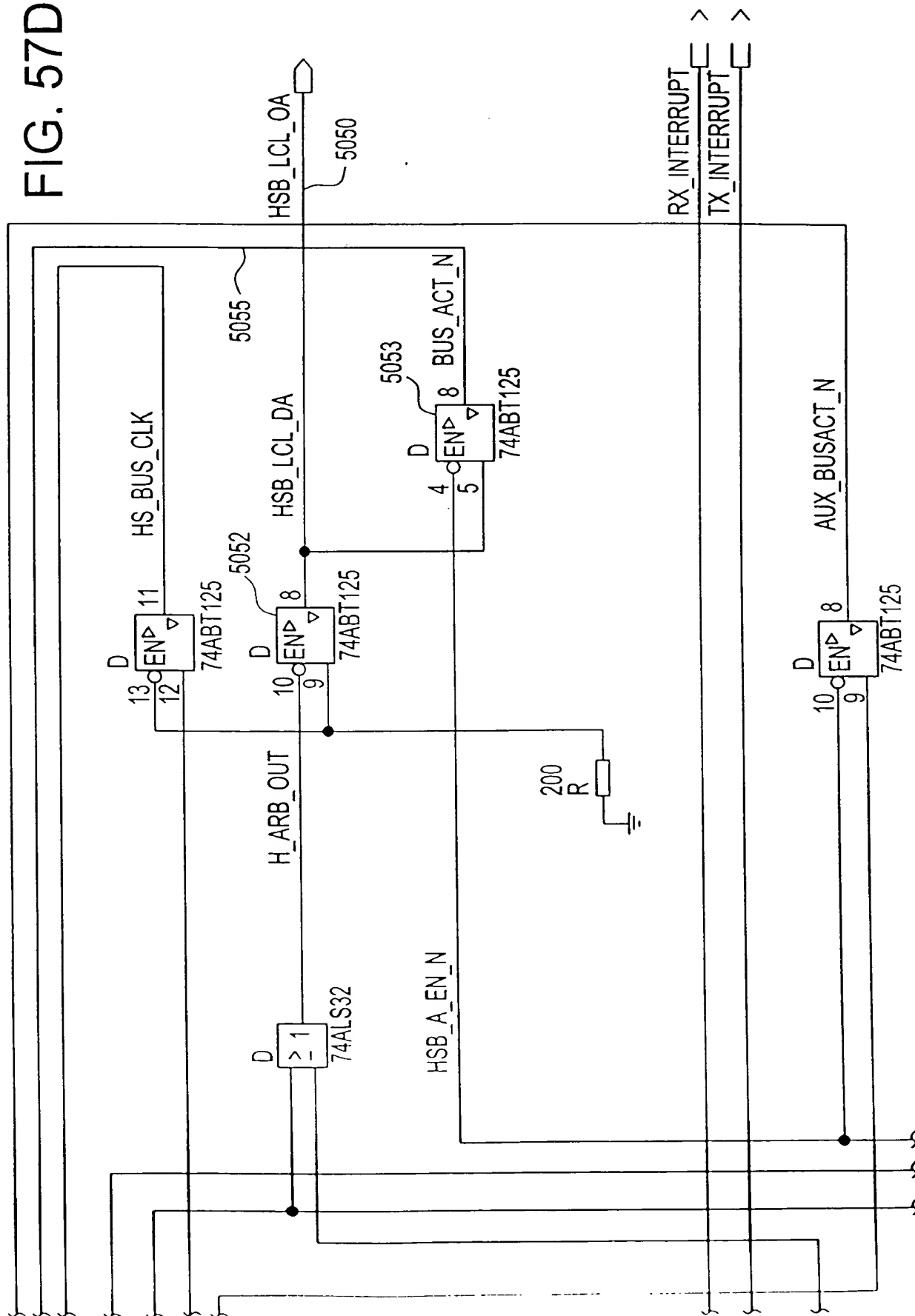


FIG. 57C







# FIG. 57E

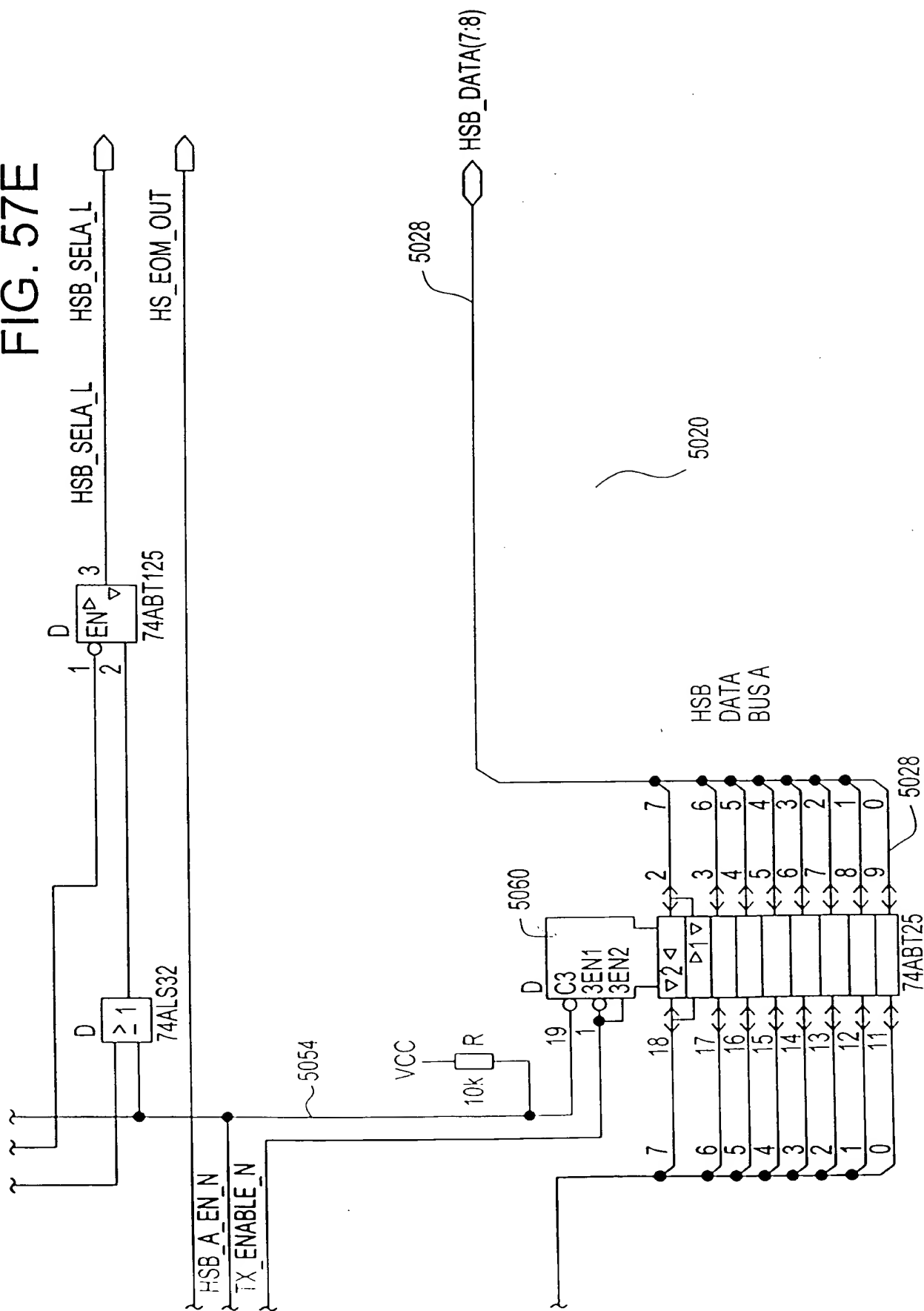


FIG. 58

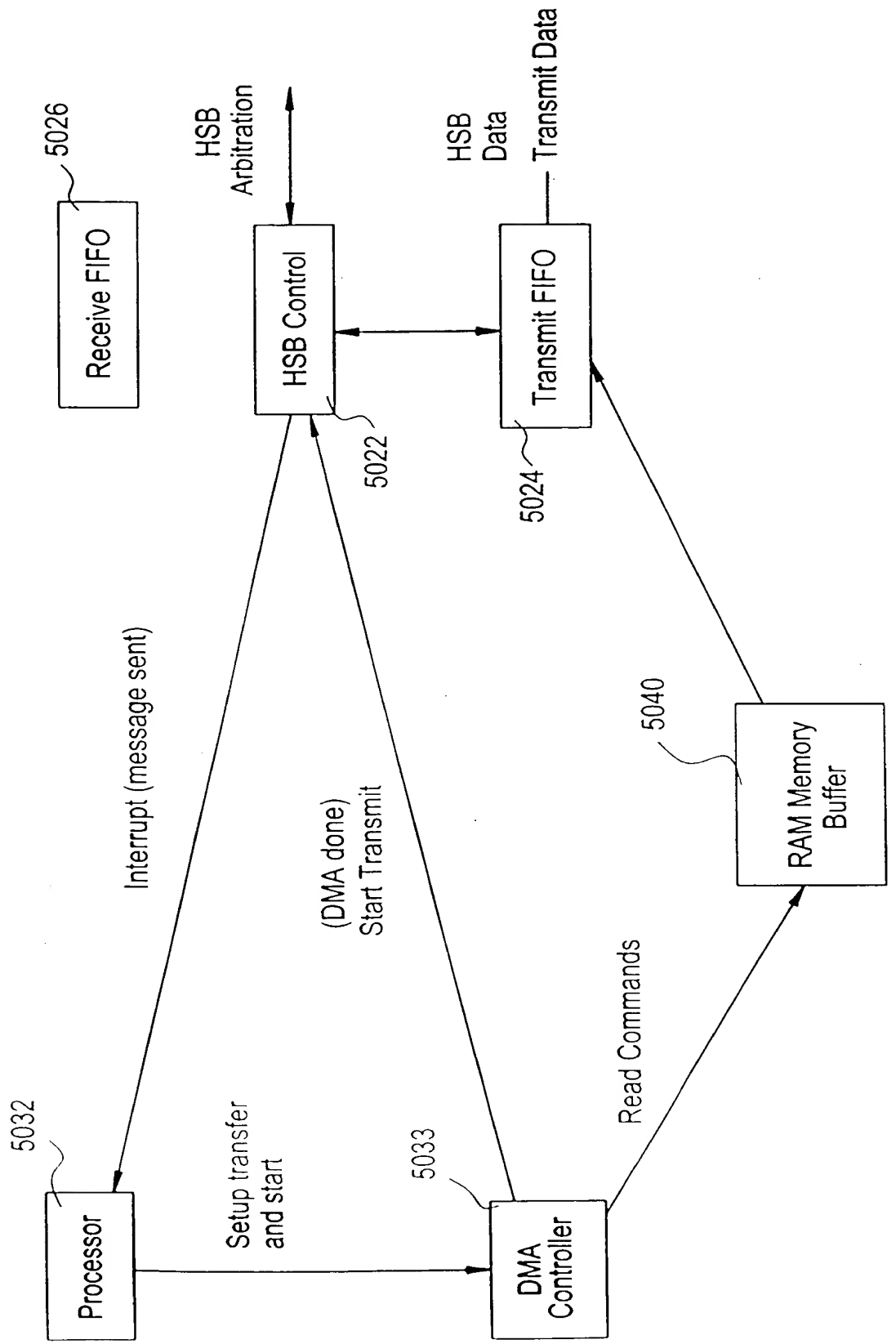


FIG. 59

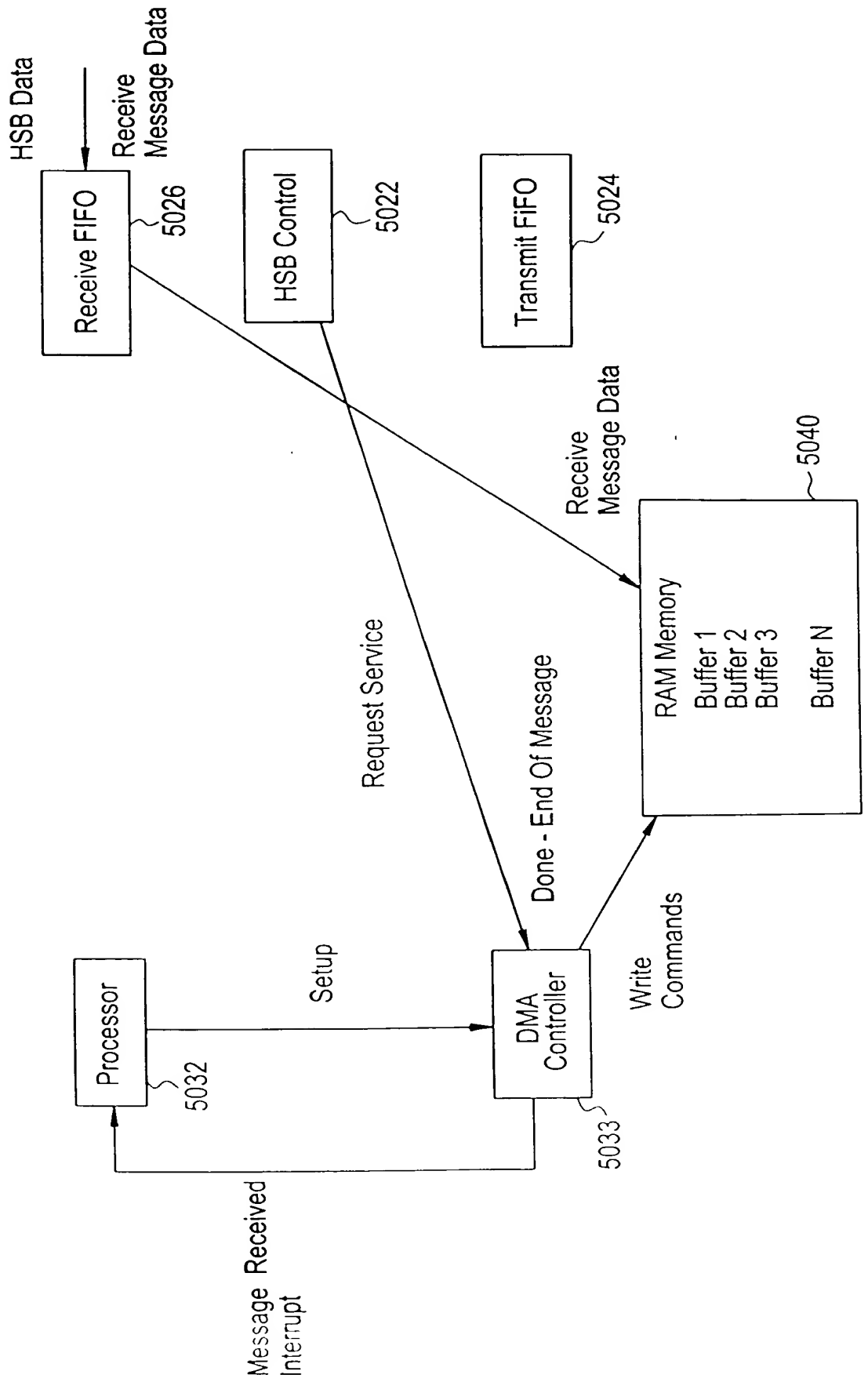


FIG. 60

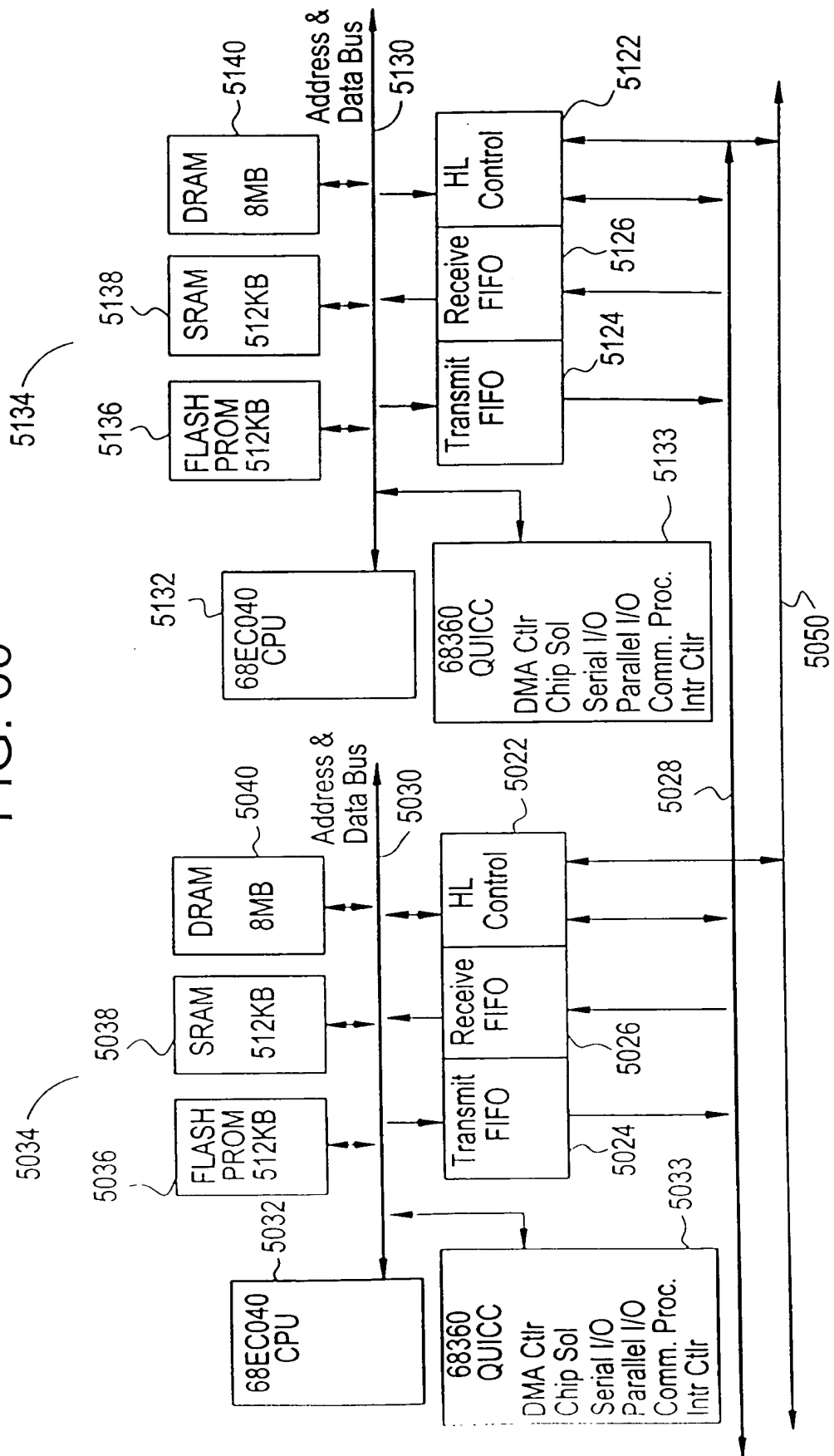


FIG. 61

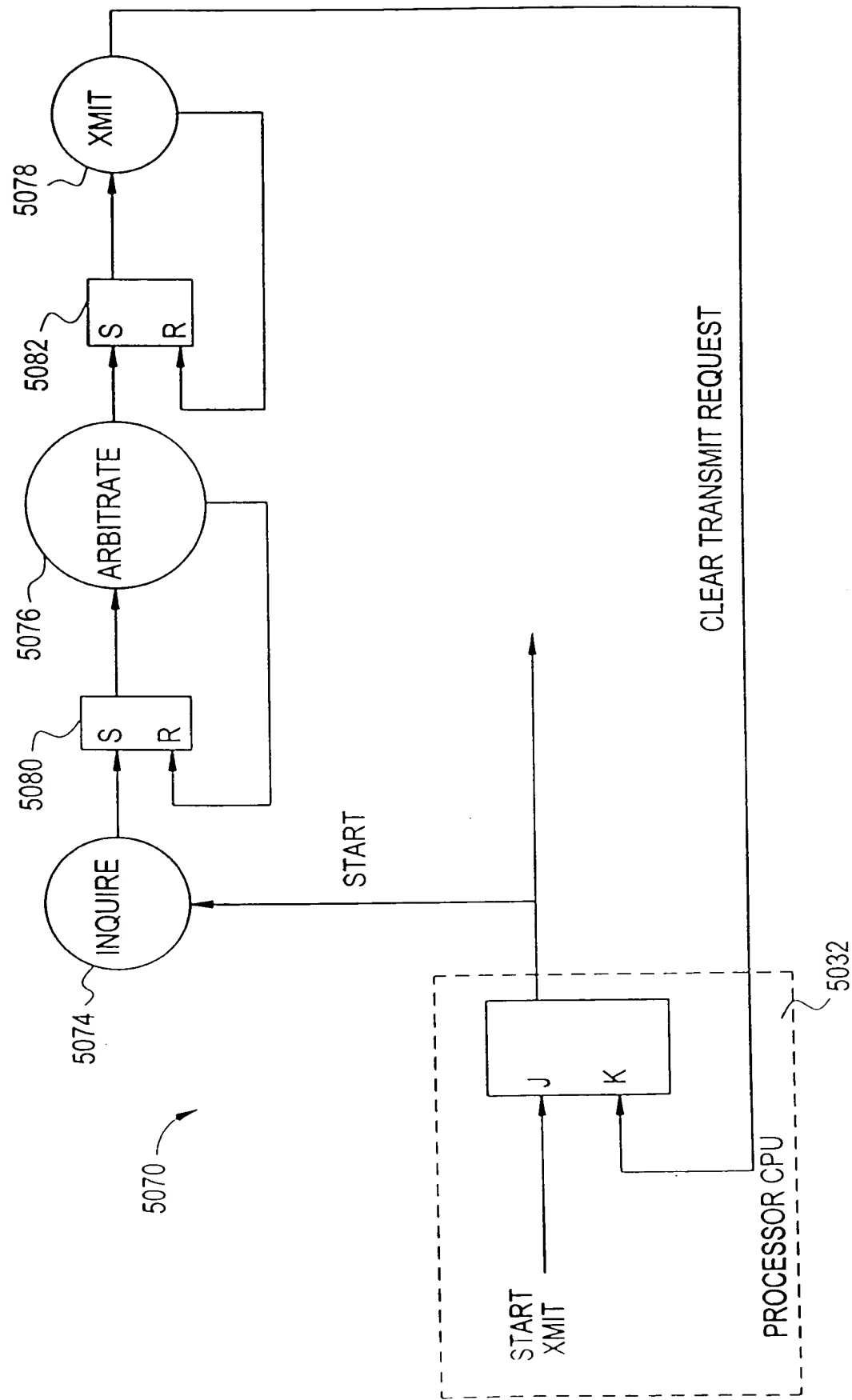


FIG. 62

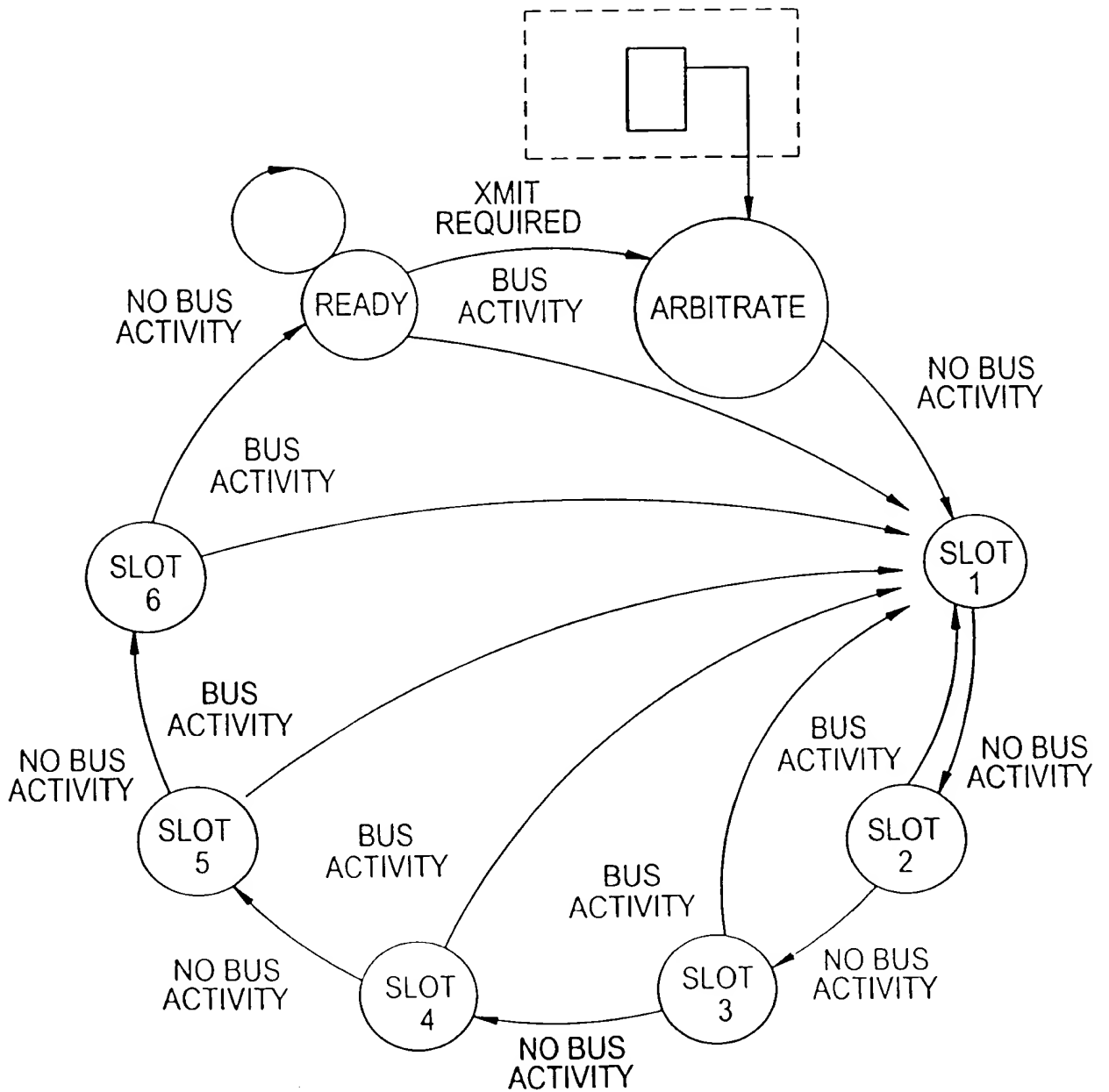


FIG. 63

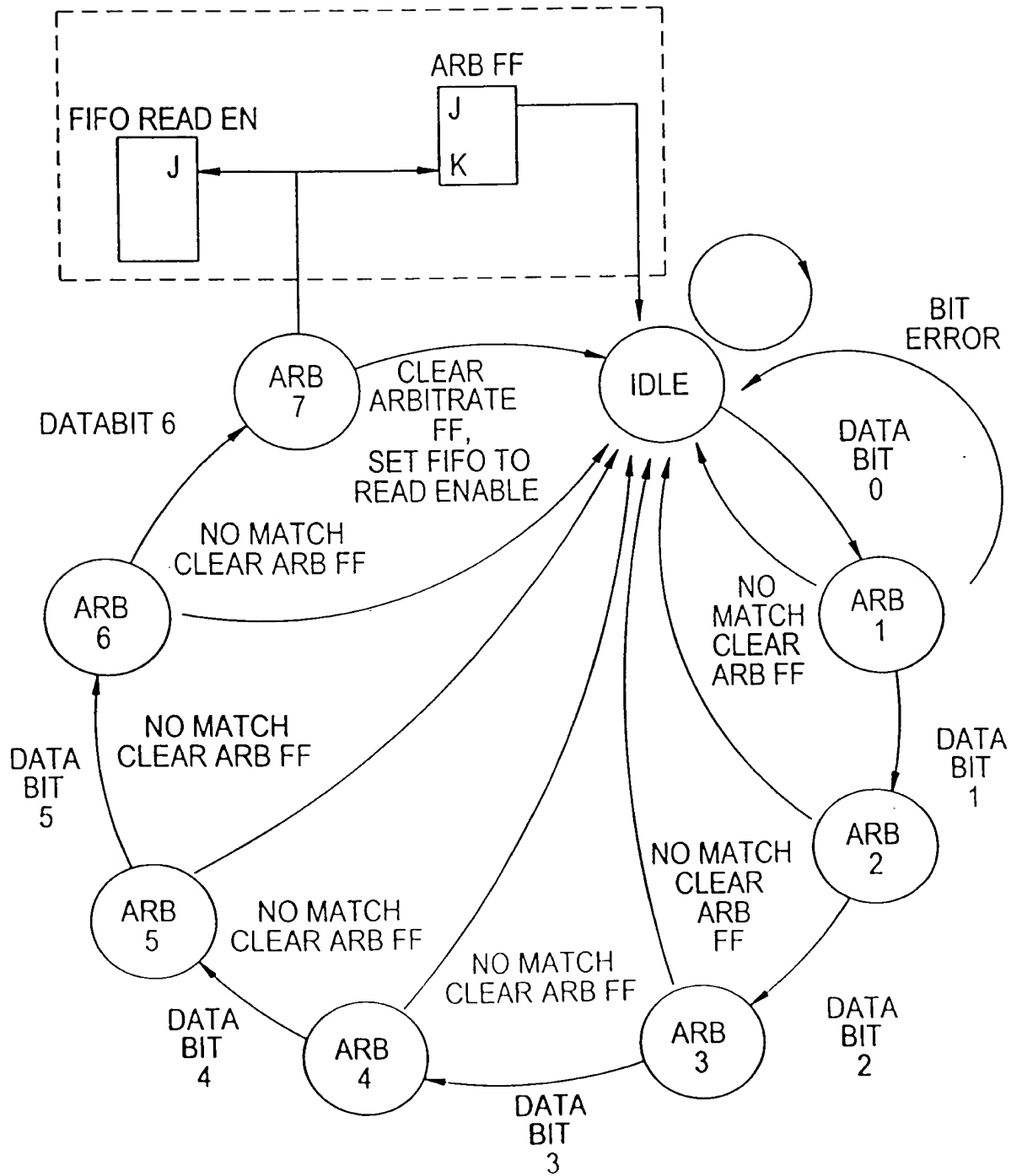


FIG. 64

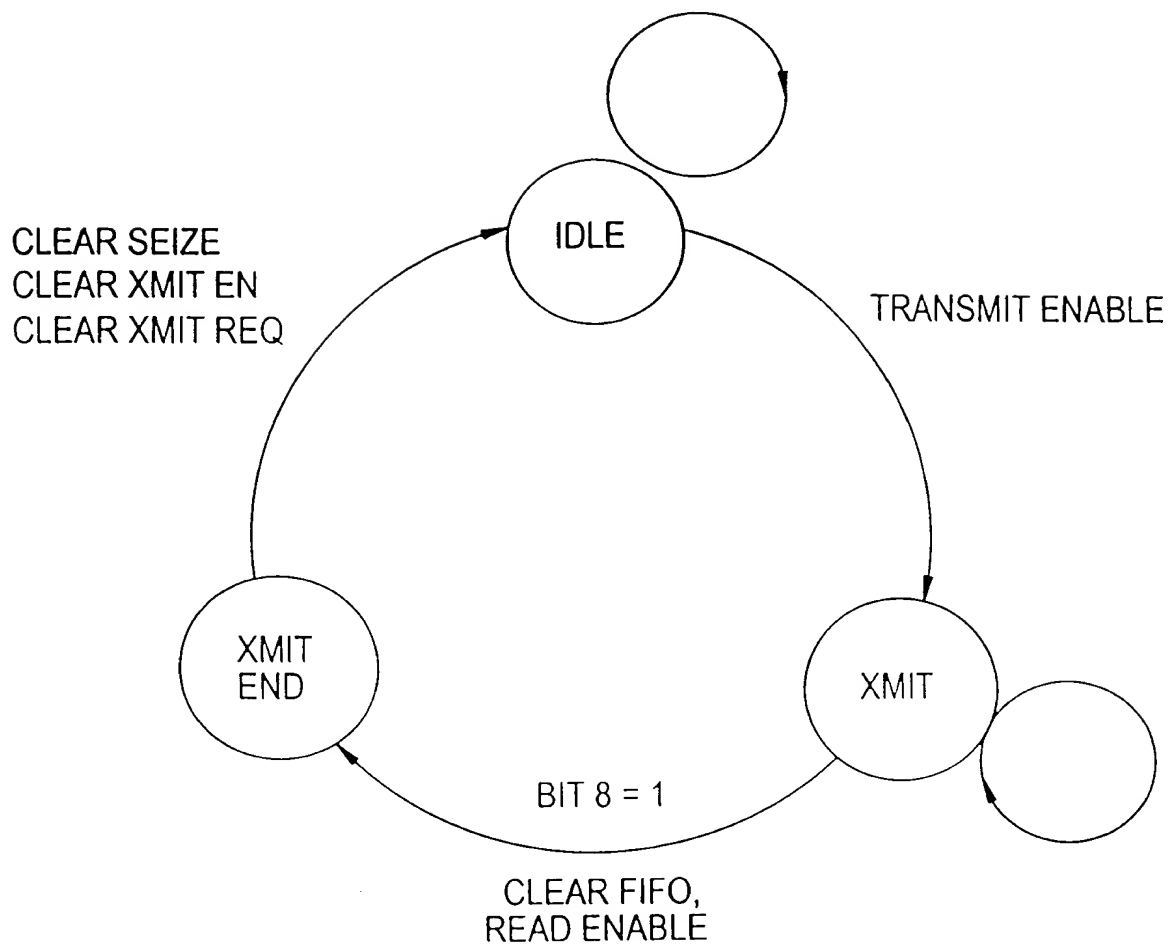


FIG. 65

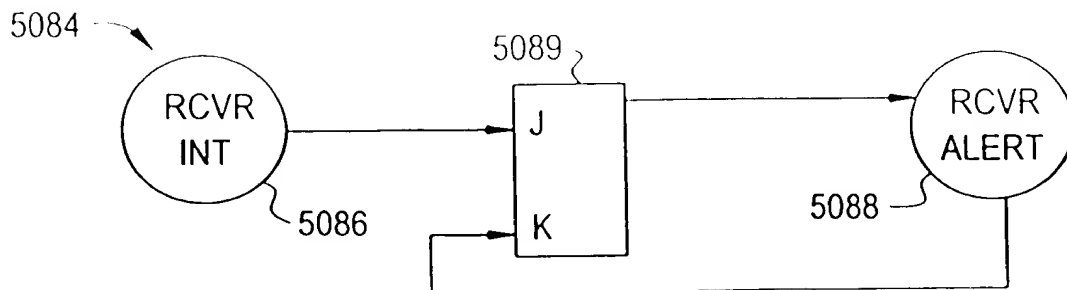




FIG. 66

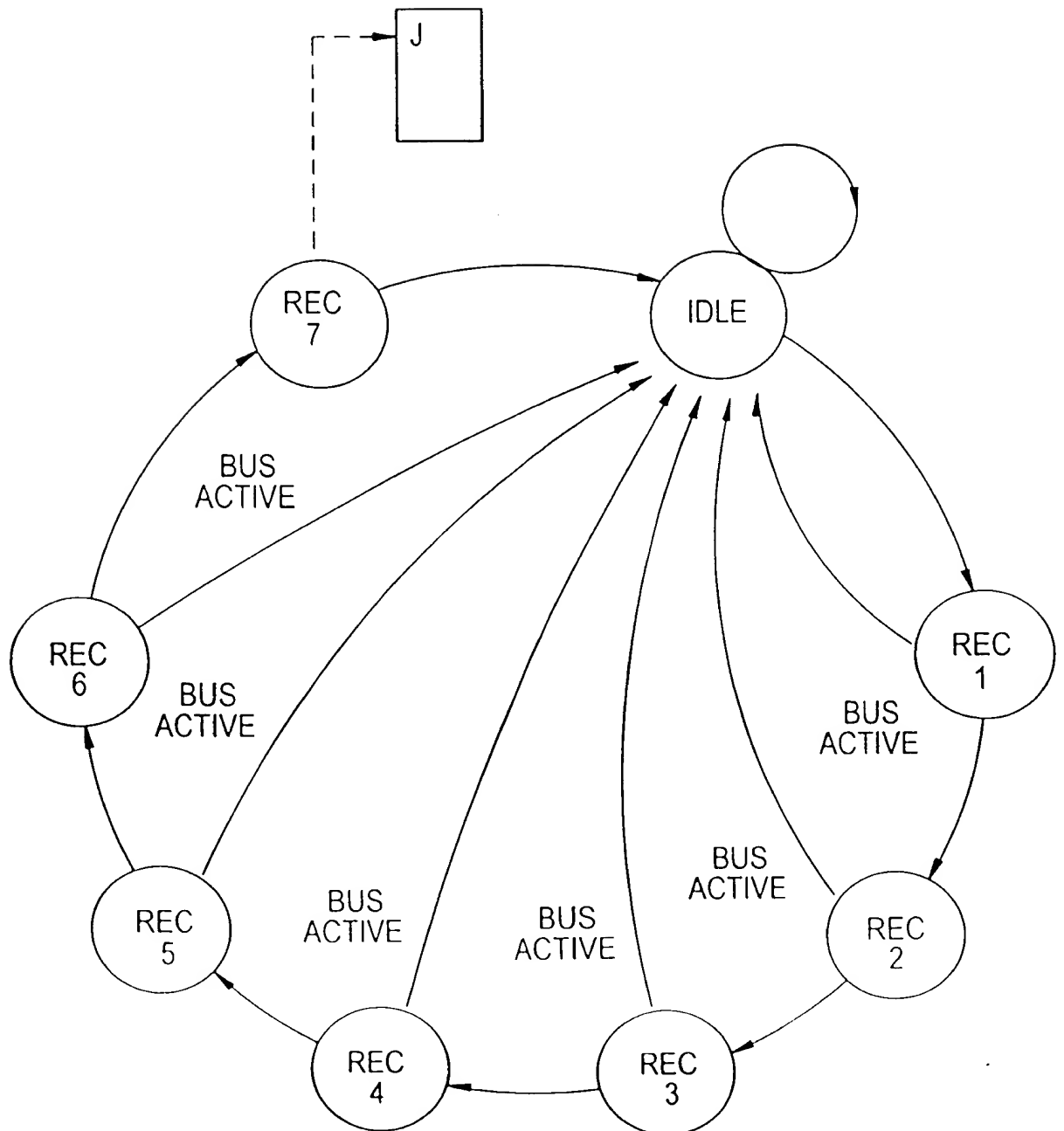


FIG. 67

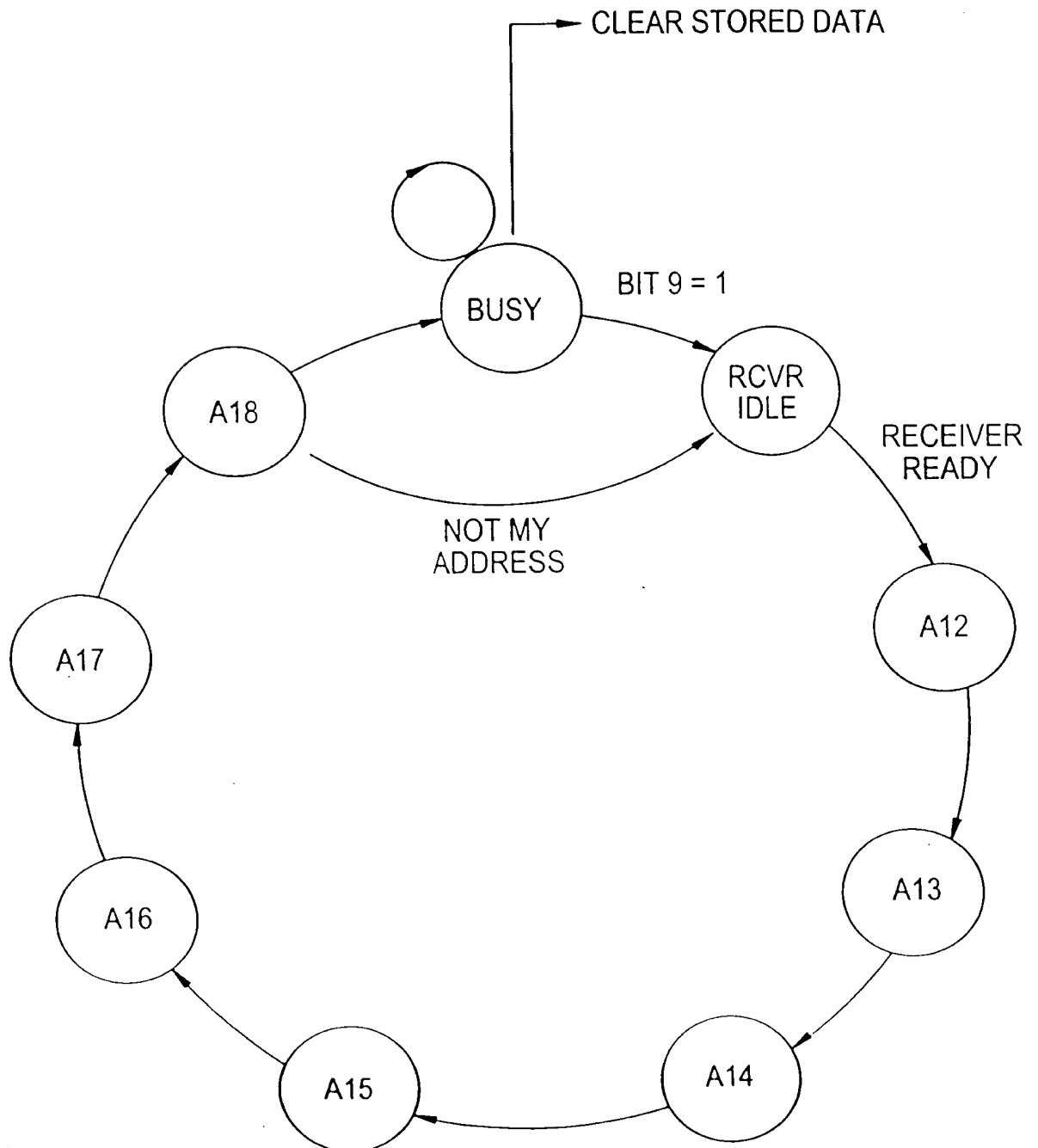


FIG. 68

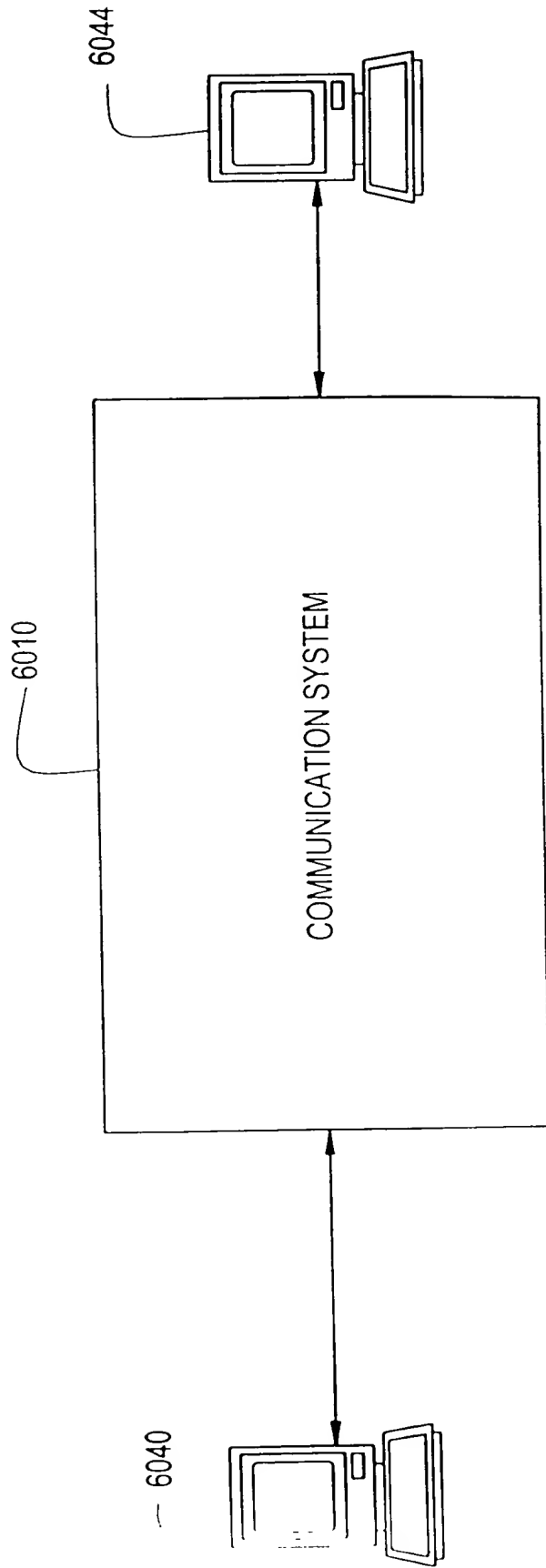
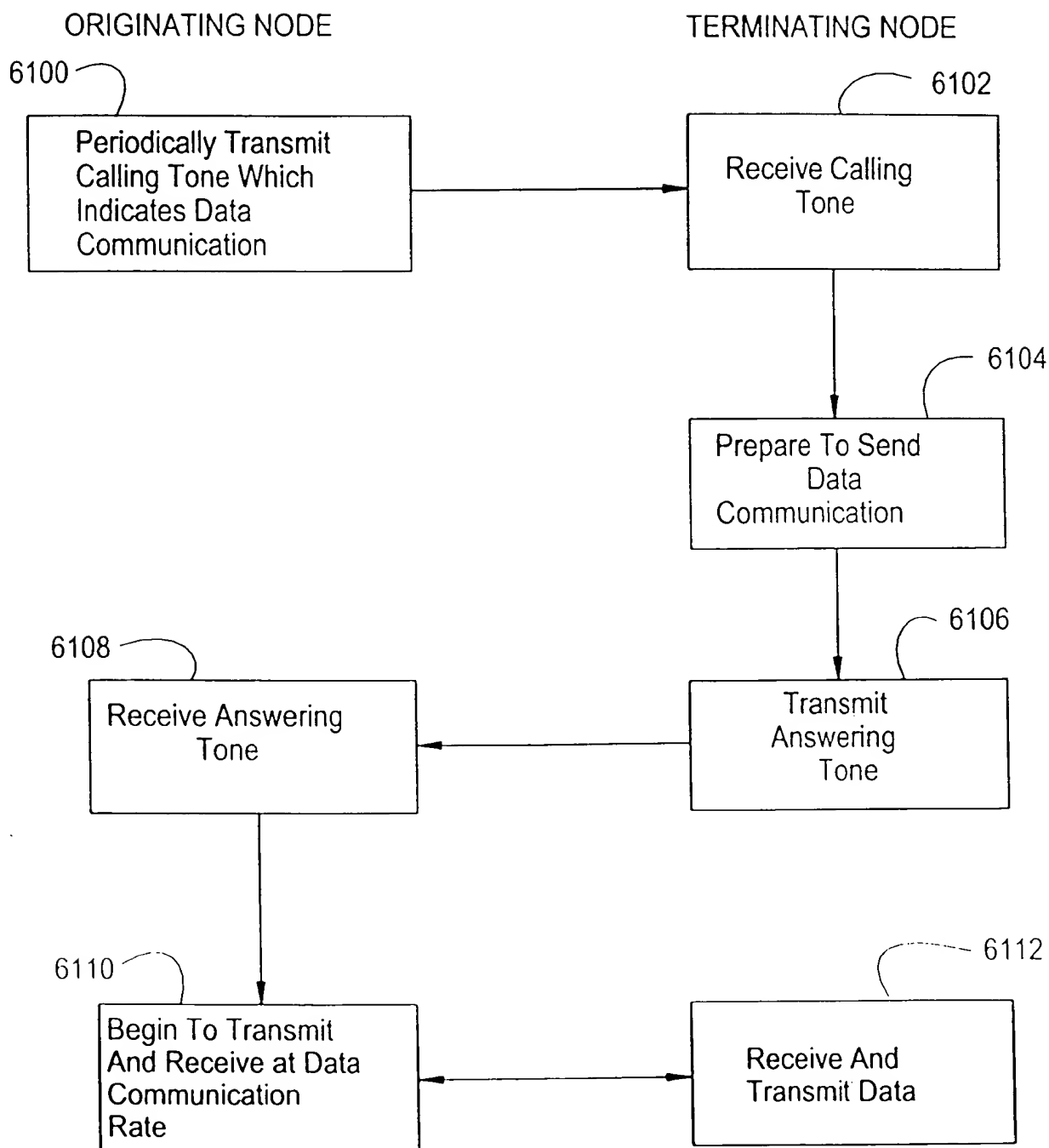


FIG. 69  
PRIOR ART



# FIG. 70

## COMMUNICATION SYSTEM

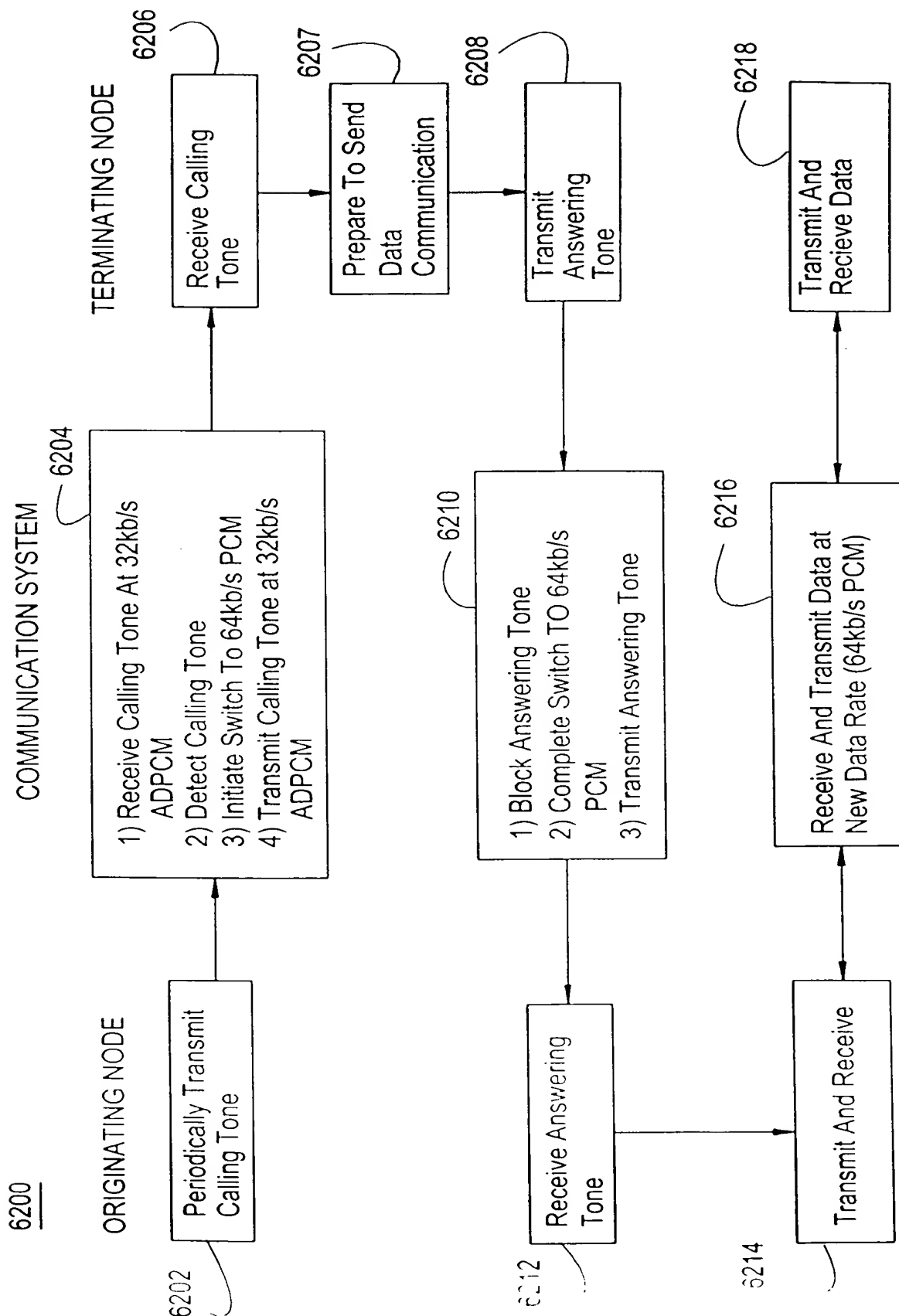


FIG. 71

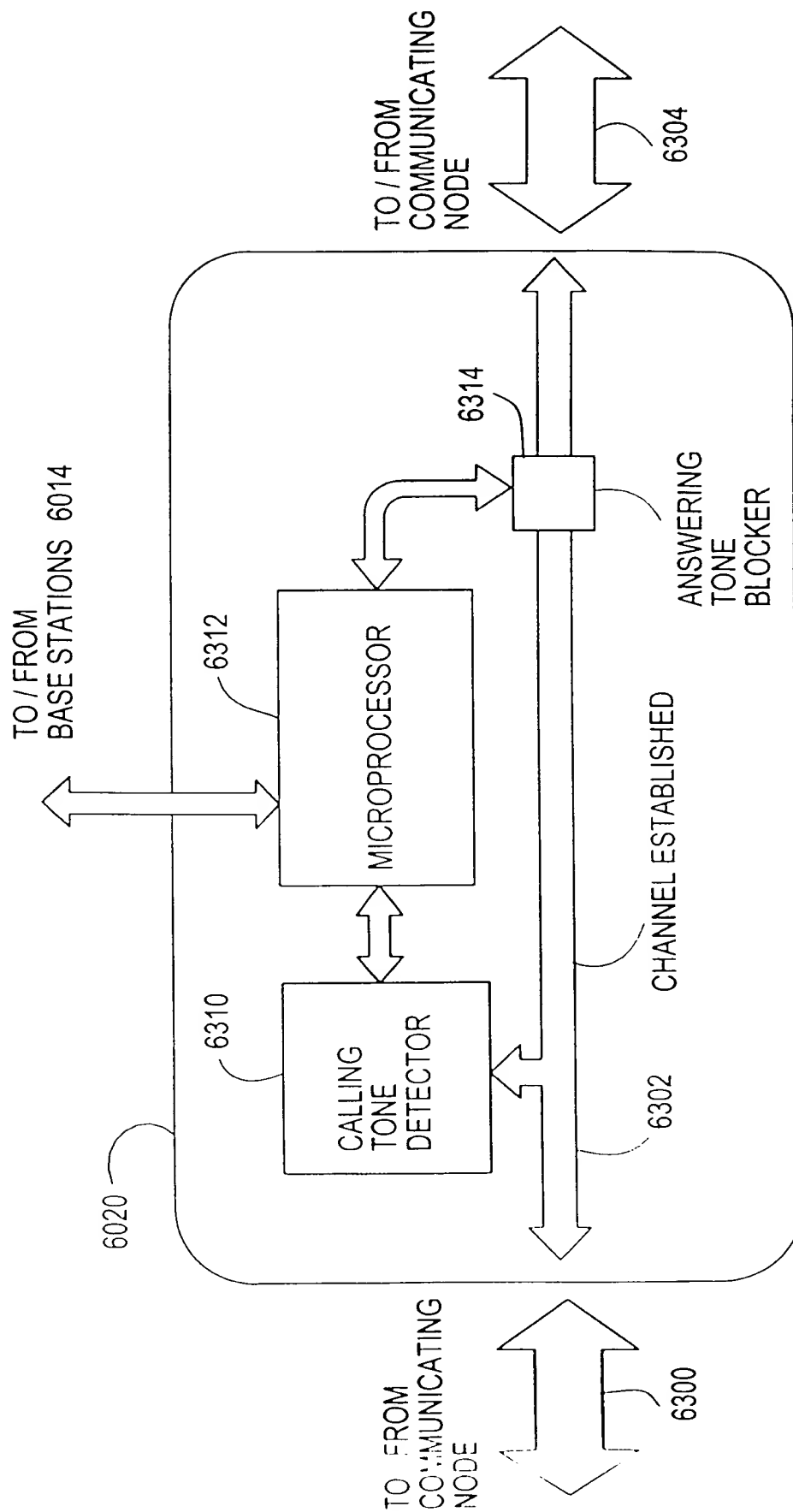


FIG. 72  
PRIOR ART

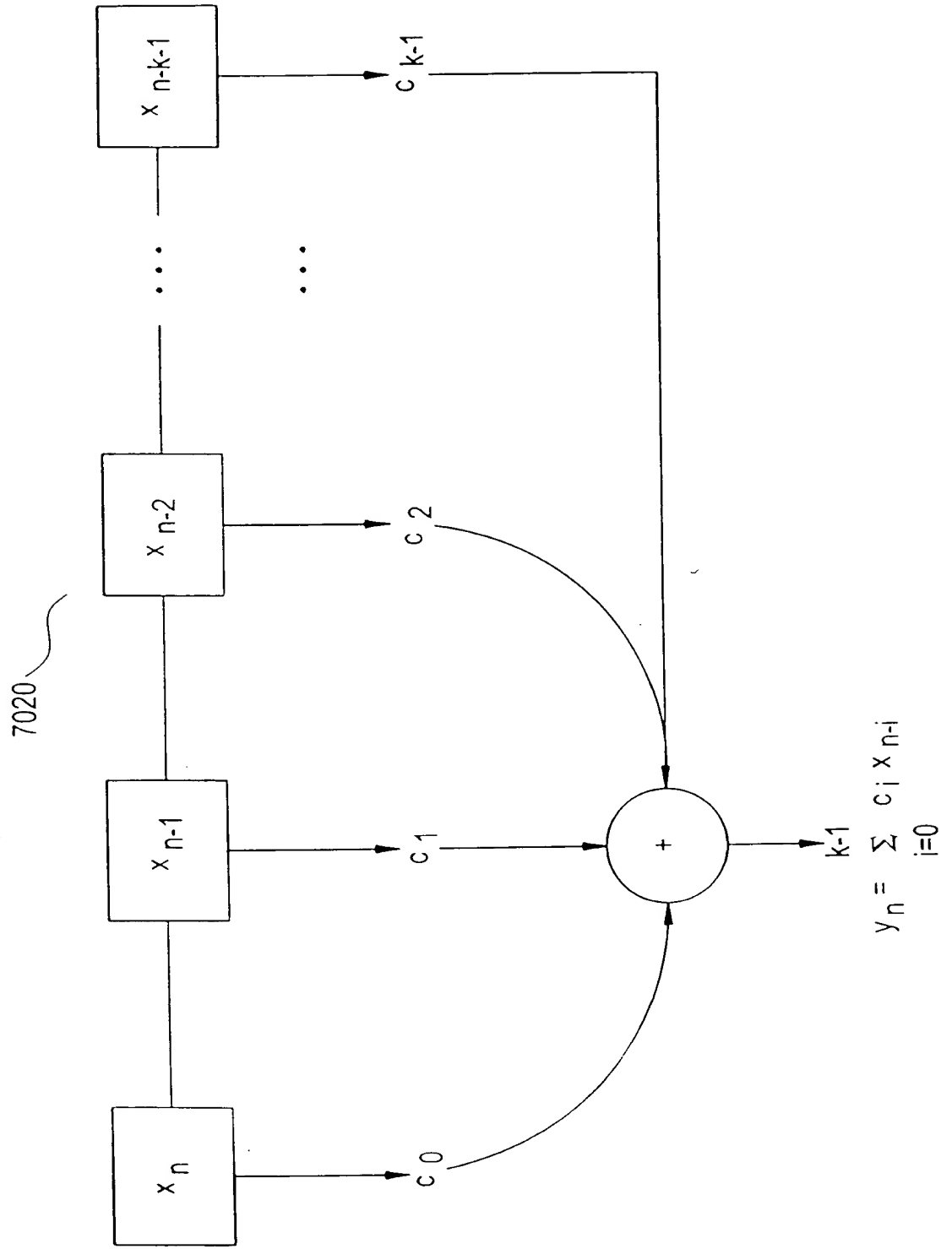


FIG. 73  
PRIOR ART

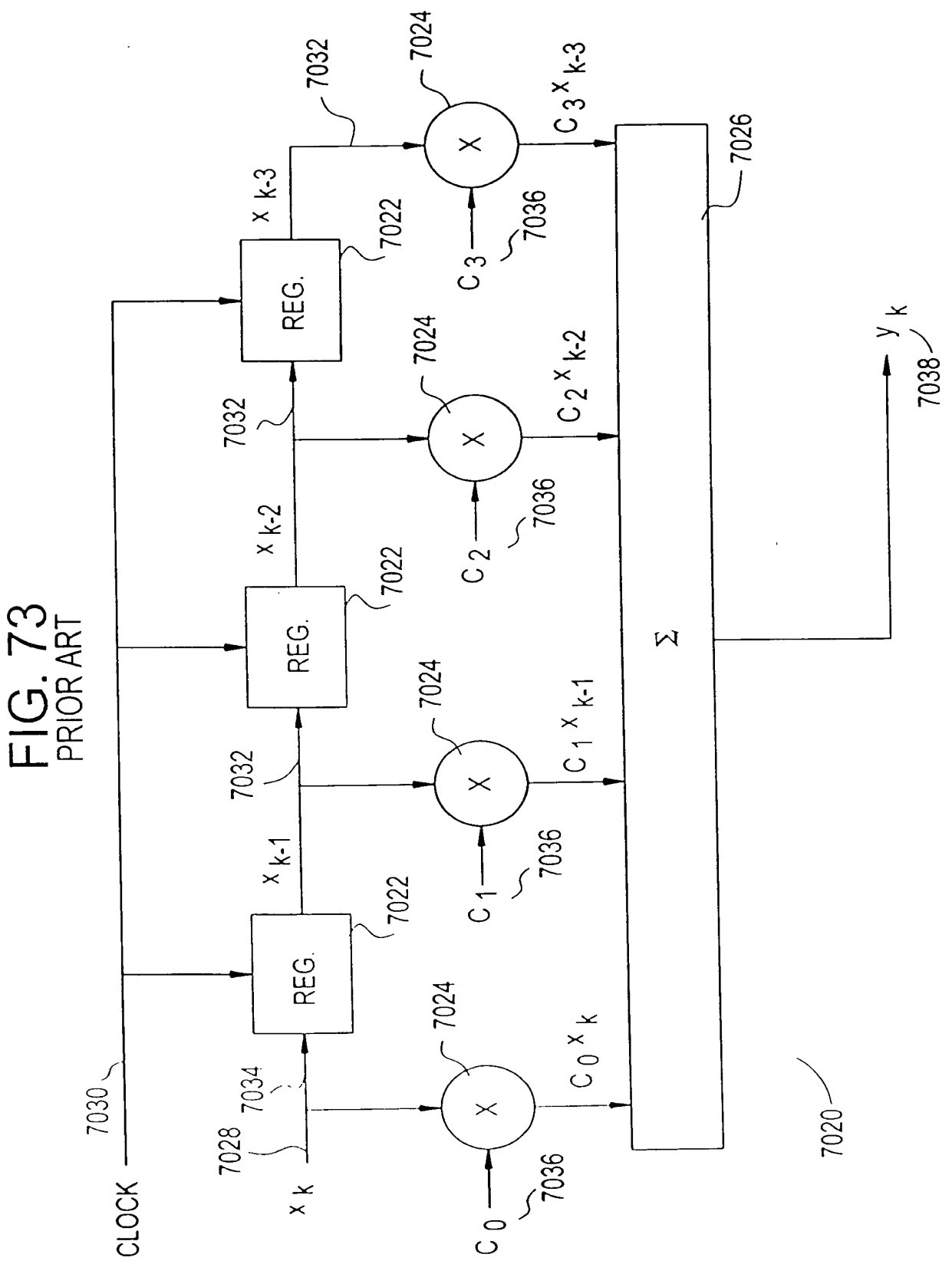




FIG. 74  
PRIOR ART

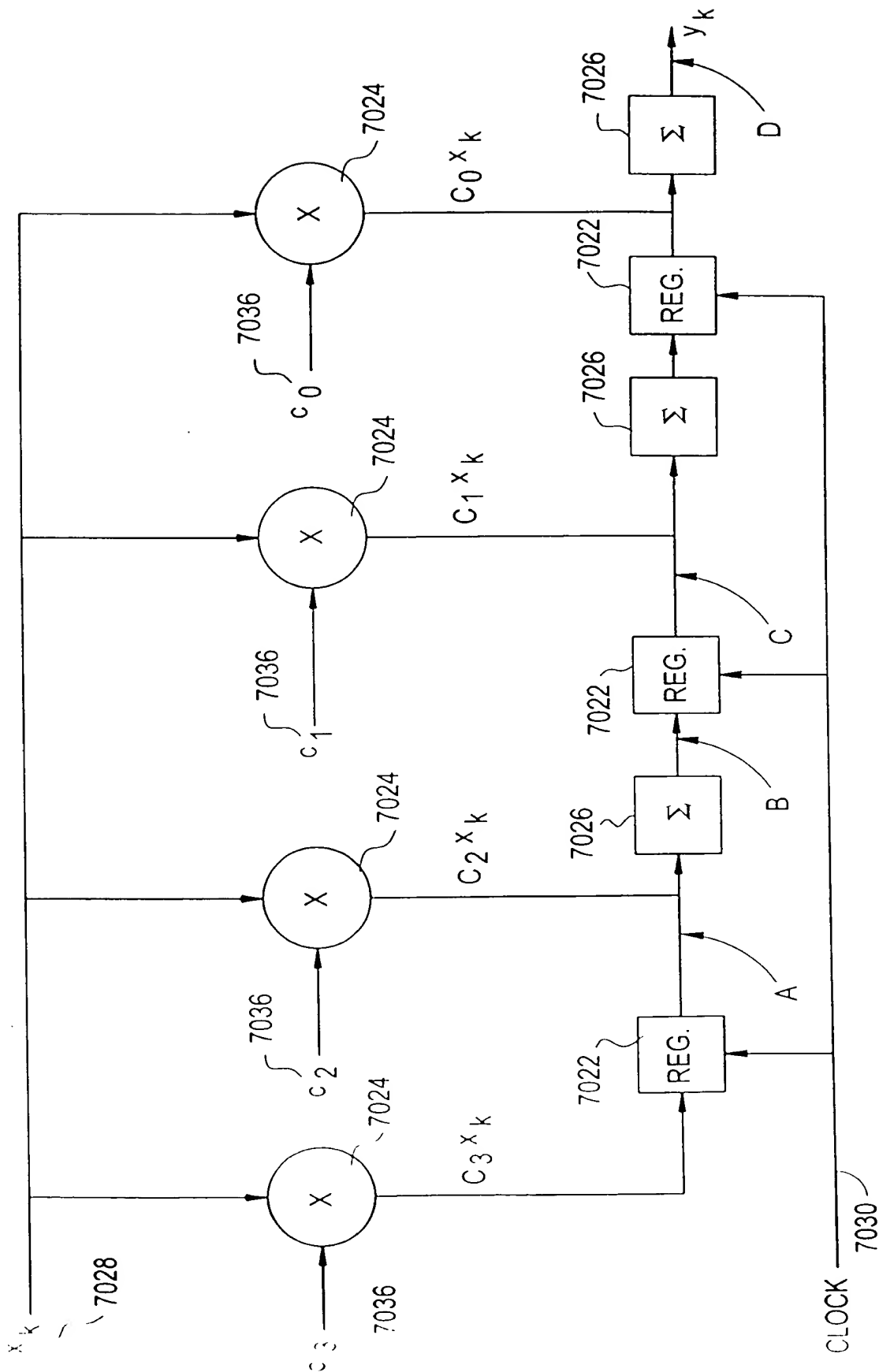
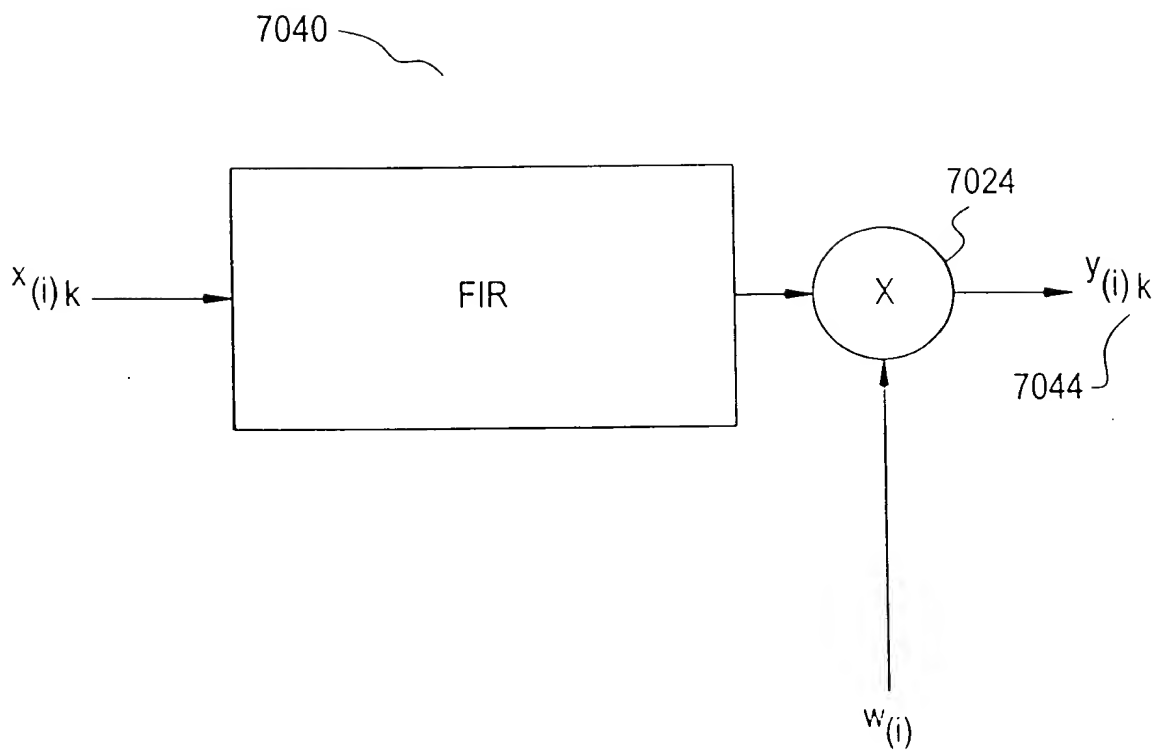
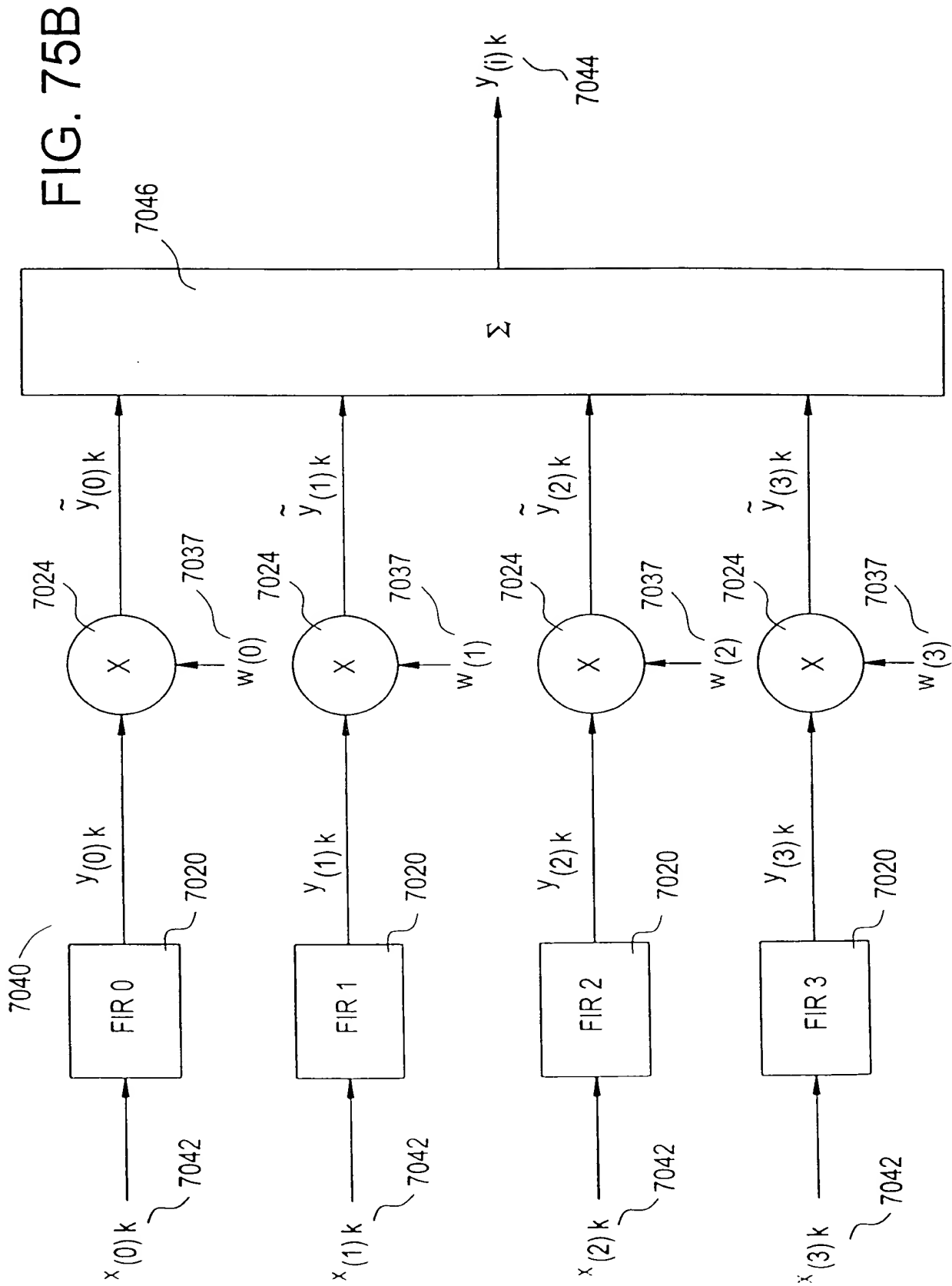


FIG. 75A





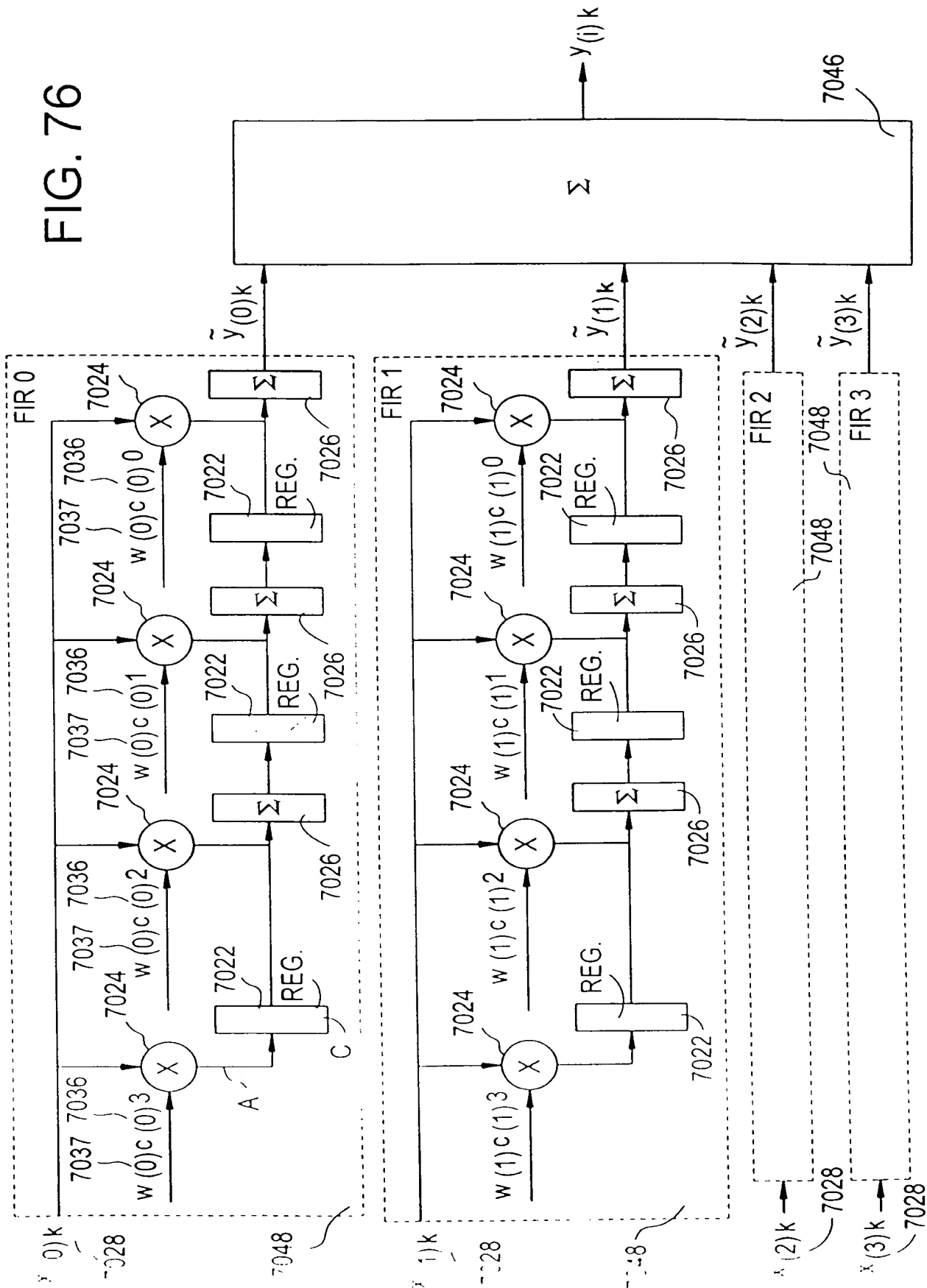


FIG. 77

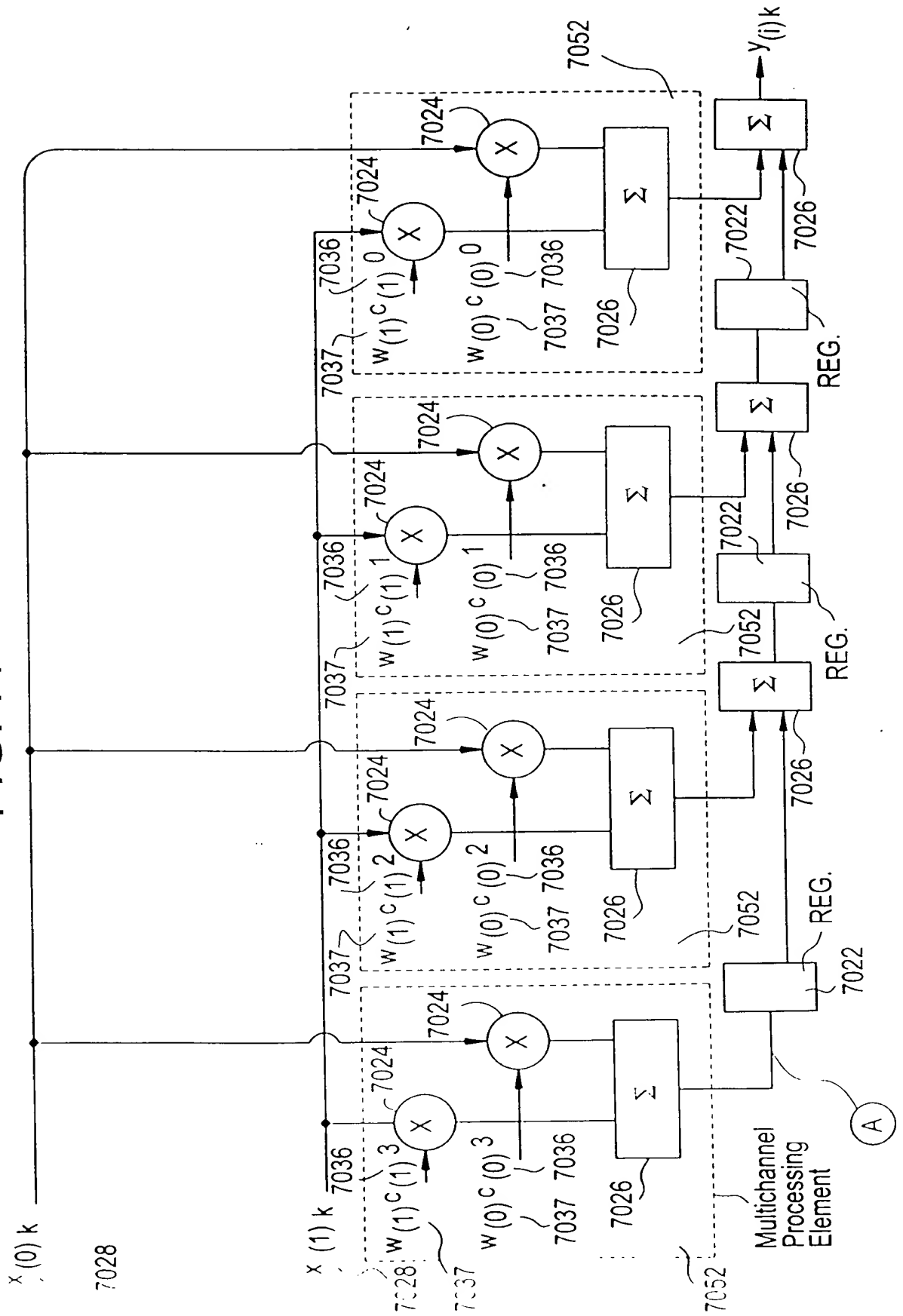


FIG. 78

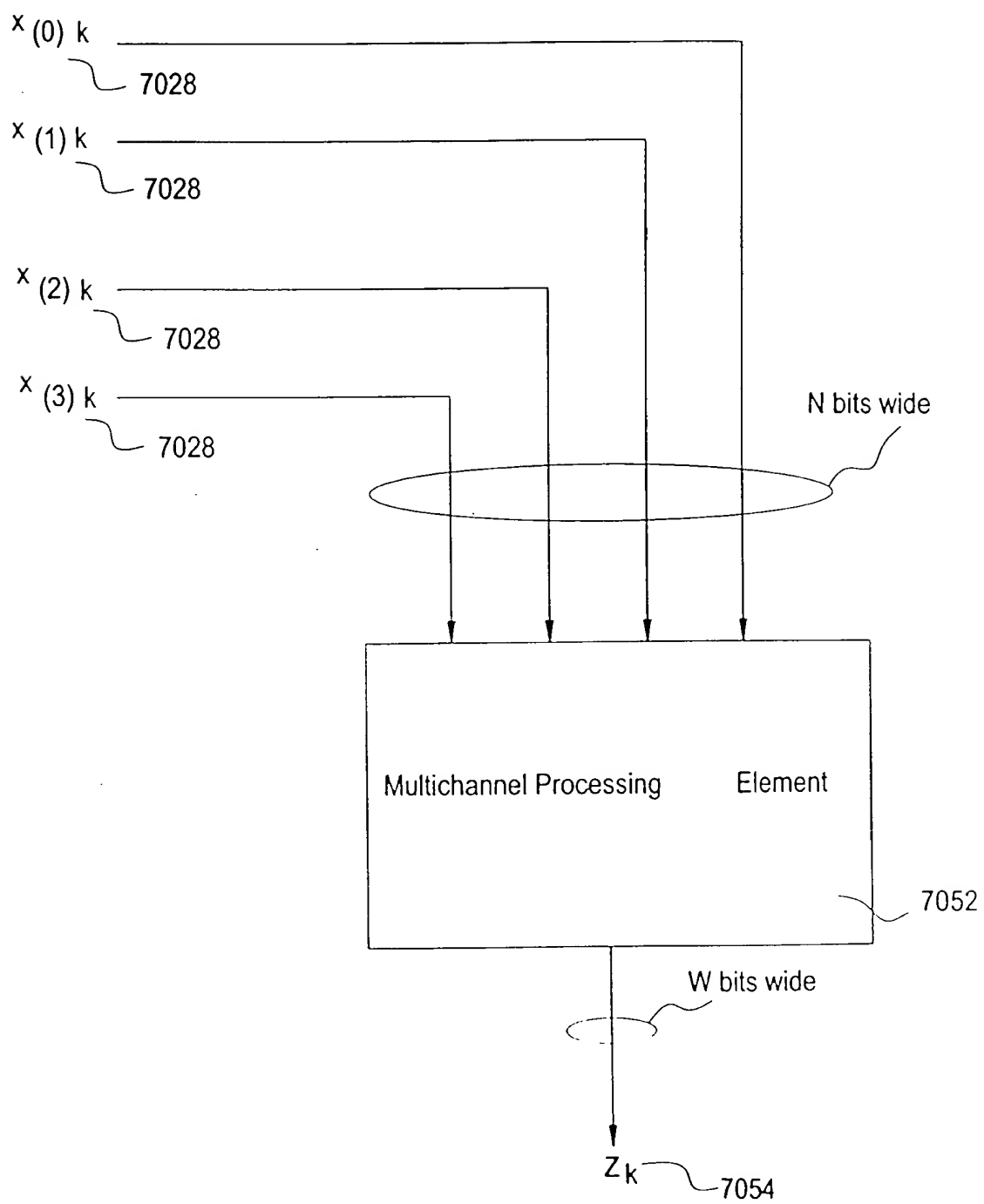


FIG. 79A

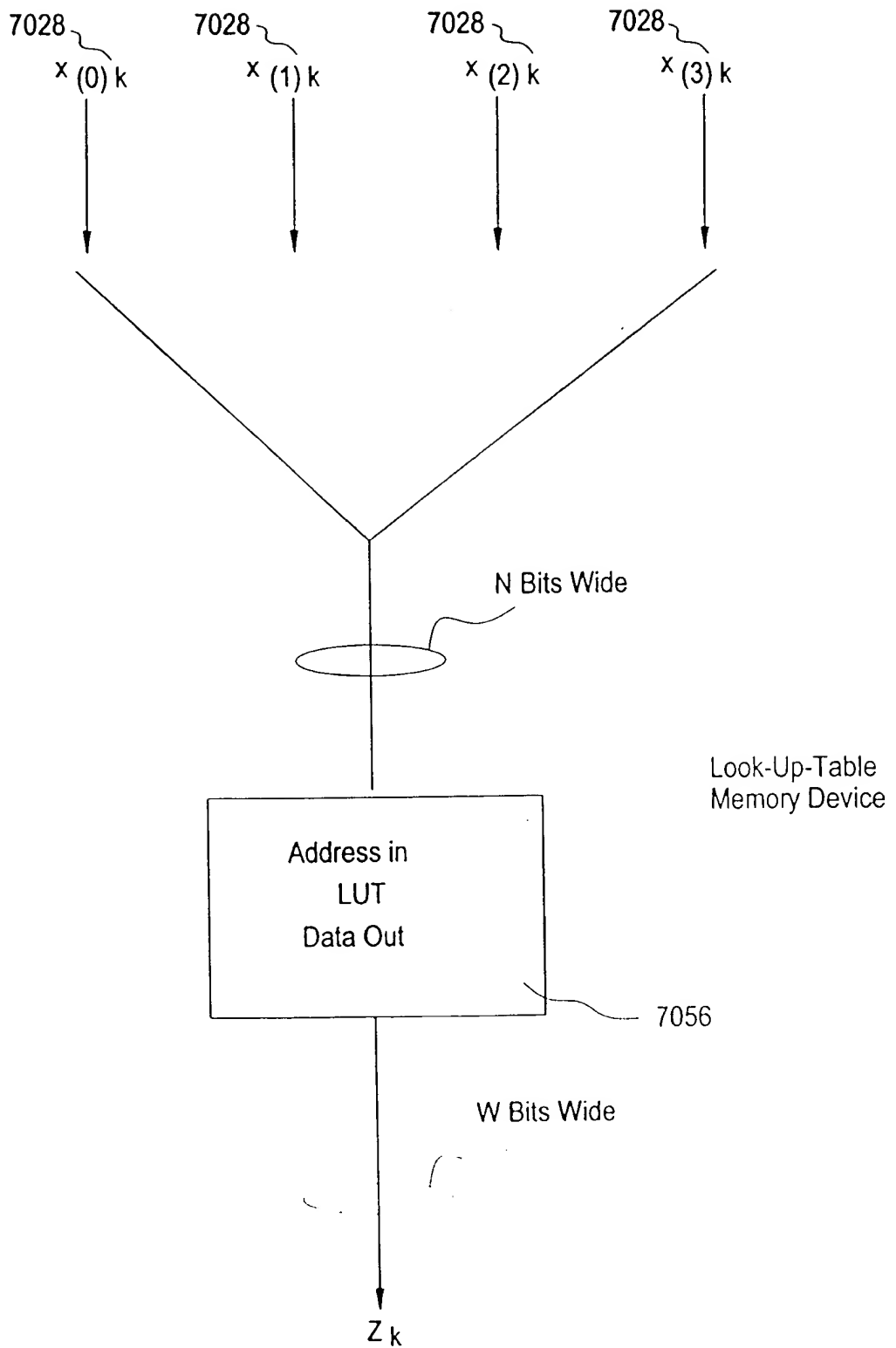


FIG. 79B

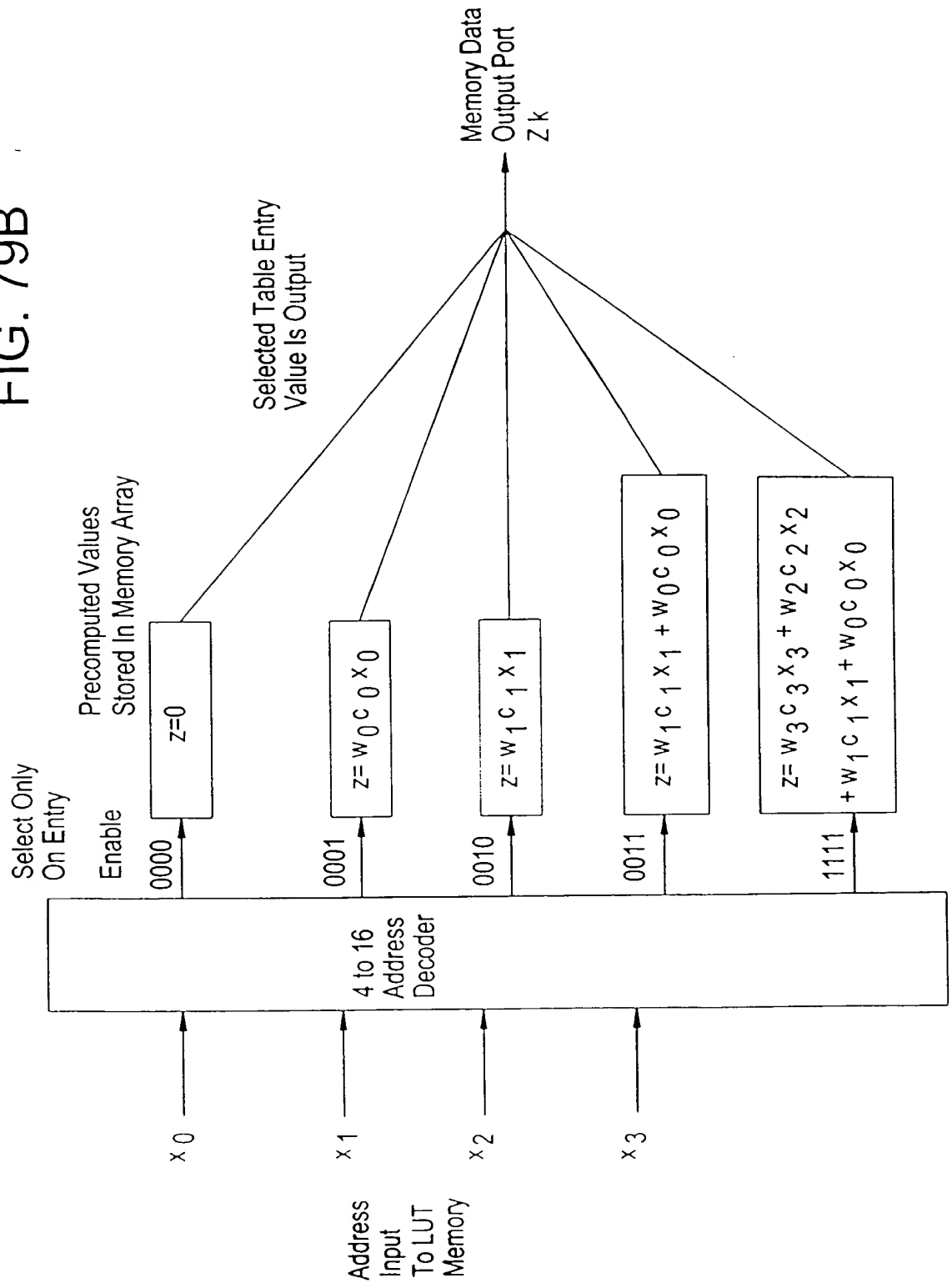




FIG. 80

